

# DRV5825P デジタル入力、48V<sub>pp</sub>、7.5A ステレオ、15A モノラル、ピエゾ・スピーカ・ドライバ、適応型 I/V リミッタ付き

## 1 特長

- 柔軟なオーディオ I/O :
  - 32、44.1、48、88.2、96kHz のサンプル・レートをサポート
  - I<sup>2</sup>S、LJ、RJ、TDM、SDOUT によるオーディオ・モニタまたはエコー・キャンセル
  - 3 線式のデジタル・オーディオ・インターフェイスをサポート (MCLK 不要)
- 高電圧、大電流ピエゾ・ドライバ
  - 48V<sub>pp</sub>
  - 2 × 7.5A (ステレオ 2.0 モード)
  - 1 × 15A (1.0 モード)
- 適応型 I/V リミッタ
  - 可変制限スレッシュホールド
  - インピーダンスと周波数に基づく電流リミッタ
  - リミッタがトリガされるまでゲインの減衰なし
  - 電力用抵抗の外付け不要
- 優れたオーディオ性能 :
  - THD+N ≤ 0.03% (V<sub>out</sub> = 2V<sub>rms</sub>、1kHz、PVDD = 12V)
  - SNR ≥ 110dB (A-weighted)、ICN ≤ 45μVRMS
- 高度な処理機能
  - サンプル・レート・コンバータ (SRC)、DC ブロッキング
  - 入力ミキサー、出カクロスバー、レベル・メータ
  - 2 × 15 BQ、2 ポスト BQ、クリップ
  - 適応型 I/V リミッタ、フル・バンド AGL
- 柔軟な電源構成
  - PVDD : 4.5V ~ 26.4V
  - DVDD および I/O : 1.8V または 3.3V
- 優れた自己保護機能を内蔵
  - 過電流エラー (OCE)
  - サイクル単位の電流制限
  - 過熱警告 (OTW)
  - 過熱エラー (OTE)
  - 低電圧 / 過電圧誤動作防止 (UVLO/OVLO)
- システム統合が簡単
  - I<sup>2</sup>C ソフトウェア制御
  - ソリューション・サイズの低減
    - 5 × 5mm の小型パッケージ
    - 電力用抵抗の外付け不要
    - ほとんどのアプリケーションでは、大容量電解コンデンサや大型のインダクタが不要

## 2 アプリケーション

- DTV、HDTV、UHD、および汎用モニタ
- ノート PC、タブレット PC

## 3 概要

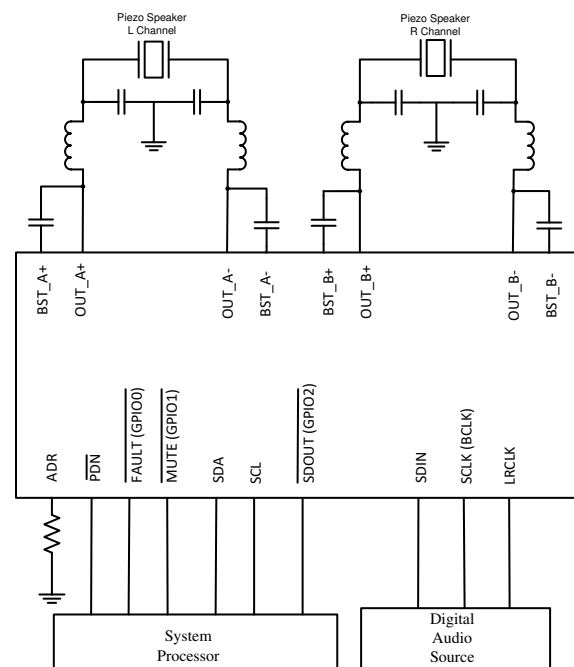
DRV5825P は高性能のステレオ、閉ループの Class-D アンプで、最高 96kHz アーキテクチャのオーディオ・プロセッサが内蔵されています。

強力なオーディオ DSP コアは高度なオーディオ処理をサポートします。内蔵サンプル・レート・コンバータ (SRC) は入力サンプル・レートの変化を検出します。これによって DSP 実行の対象サンプル・レートが自動的に決定され、オーディオ・アーティファクトの発生を防止します。これらのプロセス・フローは、以下をサポートしています。2×15 BQ、ピエゾ・スピーカ・インピーダンスと LC フィルタ・モデルに基づく適応型 I/V リミッタ、フルバンド自動ゲイン・リミッタ (AGL)、THD マネージャ (クリップ)。

### 製品情報

型番	パッケージ <sup>(1)</sup> (1 ページ)	本体サイズ (公称)
DRV5825P	VQFN (32) RHB	5.00mm × 5.00mm

(1) 利用可能なすべてのパッケージについては、このデータシートの末尾にある注文情報を参照してください。



概略回路図



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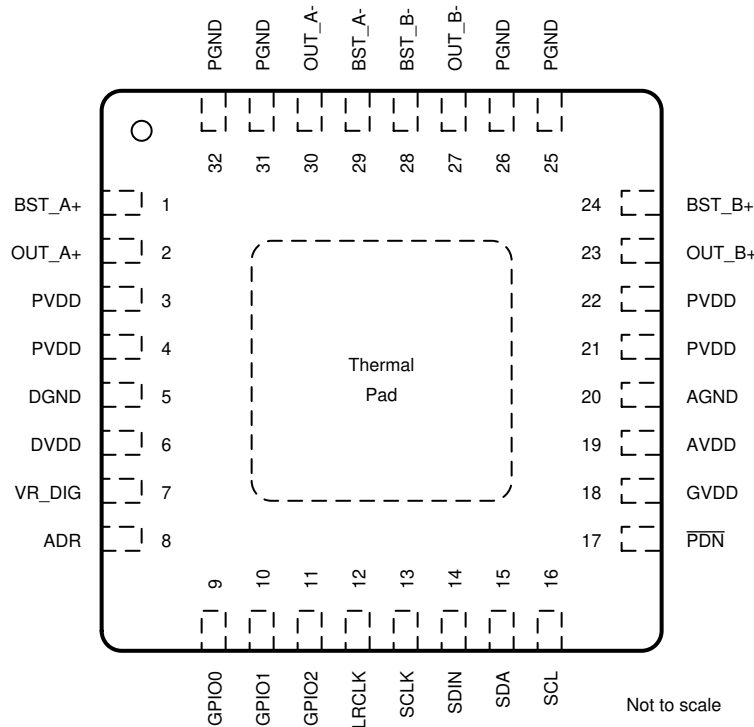
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## 4 Revision History

資料番号末尾の英字は改訂を表しています。その改訂履歴は英語版に準じています。

DATE	REVISION	NOTES
August 2020	*	Initial release.

## 5 Pin Configuration and Functions



**FIG 5-1. RHB Package 32-Pin VQFN Top View**

## Pin Functions

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NAME	NO.		
DGND	5	P	Digital ground
DVDD	6	P	3.3-V or 1.8-V digital power supply
VR_DIG	7	P	Internally regulated 1.5-V digital supply voltage. This pin must not be used to drive external devices
ADR	8	AI	A table of resistor value (Pull down to GND) will decide device I <sup>2</sup> C address. See <a href="#">Table 8-5</a> .
GPIO0	9	DI/O	General-purpose input/output, function of this pin can be programmed by register (Register Address 0x60h and 0x61h). Can be configured to be CMOS output or Open drain output (WARNZ or FAULTZ)
GPIO1	10	DI/O	General-purpose input/output, function of this pin can be programmed by register (Register Address 0x60h and 0x62h). Can be configured to be CMOS output or Open drain output (WARNZ or FAULTZ)
GPIO2	11	DI/O	General-purpose input/output, function of this pin can be programmed by register (Register Address 0x60h and 0x63h). Can be configured to be CMOS output or Open drain output (WARNZ or FAULTZ)
LRCLK	12	DI	Word select clock for the digital signal that is active on the serial port's input data line. In I <sup>2</sup> S, LJ and RJ, this corresponds to the left channel and right channel boundary. In TDM mode, this corresponds to the frame sync boundary.
SCLK <sup>(2)</sup>	13	DI	Bit clock for the digital signal that is active on the input data line of the serial data port. Sometimes, this pin also be written as "bit clock (BCLK)"
SDIN	14	DI	Data line to the serial data port
SDA	15	DI/O	I <sup>2</sup> C serial control data interface input/output
SCL	16	DI	I <sup>2</sup> C serial control clock input
PDN	17	DI	Power down, active-low. PDN place the amplifier in Shutdown, turn off all internal regulators.
GVDD	18	P	Gate drive internal regulator output. This pin must not be used to drive external devices
AVDD	19	P	Internally regulated 5-V analog supply voltage. This pin must not be used to drive external devices
AGND	20	P	Analog ground

PIN		TYPE <sup>(1)</sup>	DESCRIPTION
NAME	NO.		
PVDD	3	P	PVDD voltage input
	4	P	
	21	P	
	22	P	
PGND	25	P	Ground reference for power device circuitry. Connect this pin to system ground.
	26	P	
	31	P	
	32	P	
OUT_B+	23	O	Positive pin for differential speaker amplifier output B
BST_B+	24	P	Connection point for the OUT_B+ bootstrap capacitor which is used to create a power supply for the high-side gate drive for OUT_B+
OUT_B-	27	O	Negative pin for differential speaker amplifier output B
BST_B-	28	P	Connection point for the OUT_B- bootstrap capacitor which is used to create a power supply for the high-side gate drive for OUT_B-
BST_A-	29	P	Connection point for the OUT_A- bootstrap capacitor which is used to create a power supply for the high-side gate drive for OUT_A-
OUT_A-	30	O	Negative pin for differential speaker amplifier output A
BST_A+	1	P	Connection point for the OUT_A+ bootstrap capacitor which is used to create a power supply for the high-side gate drive for OUT_A+
OUT_A+	2	O	Positive pin for differential speaker amplifier output A
PowerPAD™		P	Connect to the system Ground

(1) AI = Analog input, AO = Analog output, DI = Digital Input, DO = Digital Output, DI/O = Digital Bi-directional (input and output), P = Power, G = Ground (0 V)

(2) Typically written "bit clock (BCLK)" in some audio codecs.

## 6 Specifications

### 6.1 Absolute Maximum Ratings

Free-air room temperature 25°C (unless otherwise noted) <sup>(1)</sup>

		MIN	MAX	UNIT
DVDD	Low-voltage digital supply	–0.3	3.9	V
PVDD	PVDD supply	–0.3	30	V
V <sub>I(DigIn)</sub>	DVDD referenced digital inputs <sup>(2)</sup>	–0.5	V <sub>DVDD</sub> + 0.5	V
V <sub>I(SPK_OUTxx)</sub>	Voltage at speaker output pins	–0.3	32	V
T <sub>A</sub>	Ambient operating temperature,	–25	85	°C
T <sub>stg</sub>	Storage temperature	–40	125	°C

- (1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) DVDD referenced digital pins include: ADR, GPIO0, GPIO1, GPIO2, LRCLK, SCLK, SDIN, SCL, SDA, PDN

### 6.2 ESD Ratings

			VALUE	UNIT
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 <sup>(1)</sup>	±2000	V
		Charged-device model (CDM), per JEDEC specification JESD22-C101 <sup>(2)</sup>	±500	

- (1) JEDEC document JEP155 states that 500-V HBM allows safe manufacturing with a standard ESD control process.
- (2) JEDEC document JEP157 states that 250-V CDM allows safe manufacturing with a standard ESD control process.

### 6.3 Recommended Operating Conditions

over operating free-air temperature range (unless otherwise noted)

			MIN	NOM	MAX	UNIT
V <sub>(POWER)</sub>	Power supply inputs	DVDD	1.62		3.63	V
		PVDD	4.5		26.4	
L <sub>OUT</sub>	Minimum inductor value in LC filter under short-circuit condition		1	4.7		µH

### 6.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		DRV5825P VQFN (RHB) 32 PINS	UNIT
		JEDEC STANDARD 4-LAYER PCB	
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	30	°C/W
R <sub>θJC(top)</sub>	Junction-to-case (top) thermal resistance	19.1	°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	9.9	°C/W
ψ <sub>JT</sub>	Junction-to-top characterization parameter	0.2	°C/W
ψ <sub>JB</sub>	Junction-to-board characterization parameter	10.5	°C/W

- (1) For more information about traditional and new thermal metrics, see the [Semiconductor and IC Package Thermal Metrics](#) application report.

## 6.5 Electrical Characteristics

Free-air room temperature 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
<b>DIGITAL I/O</b>						
IIH	Input logic high current level for DVDD referenced digital input pins	$V_{IN(DigIn)} = V_{DVDD}$			10	$\mu A$
IIL	Input logic low current level for DVDD referenced digital input pins	$V_{IN(DigIn)} = 0 V$			-10	$\mu A$
$V_{IH(DigIn)}$	Input logic high threshold for DVDD referenced digital inputs		70%			$V_{DVDD}$
$V_{IL(DigIn)}$	Input logic low threshold for DVDD referenced digital inputs				30%	$V_{DVDD}$
$V_{OH(DigIn)}$	Output logic high voltage level	$I_{OH} = 4 mA$	80%			$V_{DVDD}$
$V_{OL(DigIn)}$	Output logic low voltage level	$I_{OH} = -4 mA$			20%	$V_{DVDD}$
<b>I<sup>2</sup>C CONTROL PORT</b>						
$C_{L(I2C)}$	Allowable load capacitance for each I <sup>2</sup> C Line				400	pF
$f_{SCL(fast)}$	Support SCL frequency	No wait states, fast mode			400	kHz
$f_{SCL(slow)}$	Support SCL frequency	No wait states, slow mode			100	kHz
<b>SERIAL AUDIO PORT</b>						
$t_{DLY}$	Required LRCK/FS to SCLK rising edge delay		5			ns
$D_{SCLK}$	Allowable SCLK duty cycle		40%		60%	
$f_s$	Supported input sample rates		32		96	kHz
$f_{SCLK}$	Supported SCLK frequencies		32		64	$f_s$
$f_{SCLK}$	SCLK frequency				24.576	MHz
<b>SPEAKER AMPLIFIER (ALL OUTPUT CONFIGURATIONS)</b>						
$t_{off}$	Turn-off Time	Excluding volume ramp			10	ms
$I_{CC}$	Quiescent supply current of DVDD	PDN=2V,DVDD=3.3V,Play mode, Piezo Drive Alogorithm Enable,48kHz		17.5		mA
$I_{CC}$	Quiescent supply current of DVDD	PDN=2V,DVDD=3.3V,Sleep mode		0.87		mA
$I_{CC}$	Quiescent supply current of DVDD	PDN=2V,DVDD=3.3V,Deep Sleep mode		0.82		mA
$I_{CC}$	Quiescent supply current of DVDD	PDN=0.8V,DVDD=3.3V,Shutdown mode		7.4		$\mu A$
$I_{CC}$	Quiescent supply current of PVDD	PDN=2V, PVDD=24V, No Load, LC filter = 10 $\mu H$ + 0.47 $\mu F$ , Fsw = 768kHz, Output Hiz Mode		10.9		mA
$I_{CC}$	Quiescent supply current of PVDD	PDN=2V, PVDD=24V, No Load, LC filter = 10 $\mu H$ + 0.47 $\mu F$ , Fsw = 768kHz, Sleep Mode		7.3		mA
$I_{CC}$	Quiescent supply current of PVDD	PDN=2V, PVDD=13.5V, No Load, LC filter = 10 $\mu H$ + 0.47 $\mu F$ , Fsw = 768kHz, Deep Sleep Mode		12.01		$\mu A$
$I_{CC}$	Quiescent supply current of PVDD	PDN=0.8V, PVDD=13.5V, No Load, LC filter = 10 $\mu H$ + 0.47 $\mu F$ , Fsw = 768kHz, Shutdown Mode		7.8		$\mu A$

## 6.5 Electrical Characteristics (continued)

Free-air room temperature 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$A_{V(SPK\_AMP)}$	Programmable Gain	Value represents the "peak voltage" disregarding clipping due to lower PVDD). Measured at 0 dB input (1FS)	4.87		29.5	V
$\Delta A_{V(SPK\_AMP)}$	Amplifier gain error	Gain = 29.5 Vp		0.5		dB
$f_{SPK\_AMP}$	Switching frequency of the speaker amplifier			768		kHz
$R_{DS(on)}$	Drain-to-source on resistance of the individual output MOSFETs	FET + Metallization.		90		mΩ
$OCE_{THRES}$	Over-Current Error Threshold	Any short to supply, ground, or other channels, BTL Mode	7	7.5		A
	Over-Current cycle-by-cycle limit	BTL Mode	6	6.5		A
	Over-Current Error Threshold	Any short to supply, ground, or other channels, PBTL Mode	14	15		A
$OVE_{THRES(PVDD)}$	PVDD over voltage error threshold			28		V
$UVE_{THRES(PVDD)}$	PVDD under voltage error threshold			4.2		V
$OTE_{THRES}$	Over temperature error threshold			160		°C
$OTE_{Hysteresis}$	Over temperature error hysteresis			10		°C
$OTW_{THRES}$	Over temperature warning level 1	Read by register 0x73 bit0		112		°C
$OTW_{THRES}$	Over temperature warning level 2	Read by register 0x73 bit1		122		°C
$OTW_{THRES}$	Over temperature warning level 3	Read by register 0x73 bit2		134		°C
$OTW_{THRES}$	Over temperature warning level 4	Read by register 0x73 bit3		146		°C
<b>SPEAKER AMPLIFIER (STEREO BTL)</b>						
$ V_{OS} $	Amplifier offset voltage	Measured differentially with zero input data, programmable gain configured with 29.5 Vp/FS gain, $V_{PVDD} = 24$ V	-5		5	mV
$I_{CN(SPK)}$	Idle channel noise(A-weighted, AES17)	$V_{PVDD} = 24$ V, LC-filter, BD Modulation		45		μVrms
DR	Dynamic Range	A-Weighted, -60dBFS method, PVDD=24V, SPK_GAIN=29.5Vp/FS		111		dB
SNR	Signal-to-noise ratio	A-Weighted, referenced to 1% THD+N Output Level, PVDD = 24 V		111		dB
$K_{SVR}$	Power supply rejection ratio	Injected Noise = 1 KHz, 1 V <sub>rms</sub> , PVDD = 14.4 V, input audio signal = digital zero		72		dB
X-talk <sub>SPK</sub>	Cross-talk (worst case between left-to-right and right-to-left coupling)	f = 1 KHz		100		dB
<b>SPEAKER AMPLIFIER (MONO PBTL)</b>						
$ V_{OS} $	Amplifier offset voltage	Measured differentially with zero input data, programmable gain configured with 29.5 Vp gain, $V_{PVDD} = 24$ V	-7.5		7.5	mV
DR	Dynamic range	A-Weighted, -60 dBFS method, PVDD=19V		109		dB

## 6.5 Electrical Characteristics (continued)

Free-air room temperature 25°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
SNR	Signal-to-noise ratio	A-Weighted, referenced to 1% THD+N Output Level, PVDD = 19 V		109		dB
		A-Weighted, referenced to 1% THD+N Output Level, PVDD = 24 V		111		dB

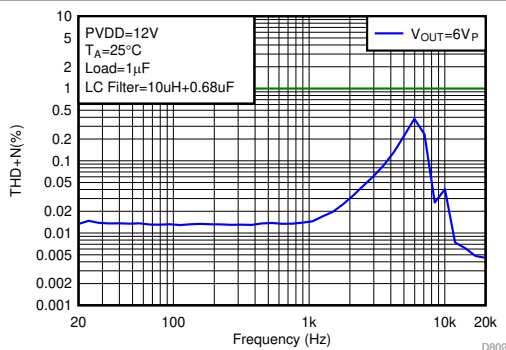
## 6.6 Timing Requirements

		MIN	NOM	MAX	UNIT
<b>Serial Audio Port Timing – Slave Mode</b>					
f <sub>SCLK</sub>	SCLK frequency	1.024			MHz
t <sub>SCLK</sub>	SCLK period	40			ns
t <sub>SCLKL</sub>	SCLK pulse width, low	16			ns
t <sub>SCLKH</sub>	SCLK pulse width, high	16			ns
t <sub>SL</sub>	SCLK rising to LRCK/FS edge	8			ns
t <sub>LS</sub>	LRCK/FS Edge to SCLK rising edge	8			ns
t <sub>SU</sub>	Data setup time, before SCLK rising edge	8			ns
t <sub>DH</sub>	Data hold time, after SCLK rising edge	8			ns
t <sub>DFS</sub>	Data delay time from SCLK falling edge			15	ns
<b>I<sup>2</sup>C Bus Timing – Standard</b>					ns
f <sub>SCL</sub>	SCL clock frequency			100	kHz
t <sub>BUF</sub>	Bus free time between a STOP and START condition	4.7			μs
t <sub>LOW</sub>	Low period of the SCL clock	4.7			μs
t <sub>HI</sub>	High period of the SCL clock	4			μs
t <sub>RS-SU</sub>	Setup time for (repeated) START condition	4.7			μs
t <sub>S-HD</sub>	Hold time for (repeated) START condition	4			μs
t <sub>D-SU</sub>	Data setup time	250			ns
t <sub>D-HD</sub>	Data hold time	0		3450	ns
t <sub>SCL-R</sub>	Rise time of SCL signal	20 + 0.1C <sub>B</sub>		1000	ns
t <sub>SCL-R1</sub>	Rise time of SCL signal after a repeated START condition and after an acknowledge bit	20 + 0.1C <sub>B</sub>		1000	ns
t <sub>SCL-F</sub>	Fall time of SCL signal	20 + 0.1C <sub>B</sub>		1000	ns
t <sub>SDA-R</sub>	Rise time of SDA signal	20 + 0.1C <sub>B</sub>		1000	ns
t <sub>SDA-F</sub>	Fall time of SDA signal	20 + 0.1C <sub>B</sub>		1000	ns
t <sub>P-SU</sub>	Setup time for STOP condition	4			μs
C <sub>b</sub>	Capacitive load for each bus line			400	pf
<b>I<sup>2</sup>C Bus Timing – Fast</b>					
f <sub>SCL</sub>	SCL clock frequency			400	kHz
t <sub>BUF</sub>	Bus free time between a STOP and START condition	1.3			μs
t <sub>LOW</sub>	Low period of the SCL clock	1.3			μs
t <sub>HI</sub>	High period of the SCL clock	600			ns
t <sub>RS-SU</sub>	Setup time for (repeated)START condition	600			ns
t <sub>RS-HD</sub>	Hold time for (repeated)START condition	600			ns
t <sub>D-SU</sub>	Data setup time	100			ns
t <sub>D-HD</sub>	Data hold time	0		900	ns
t <sub>SCL-R</sub>	Rise time of SCL signal	20 + 0.1C <sub>B</sub>		300	ns
t <sub>SCL-R1</sub>	Rise time of SCL signal after a repeated START condition and after an acknowledge bit	20 + 0.1C <sub>B</sub>		300	ns
t <sub>SCL-F</sub>	Fall time of SCL signal	20 + 0.1C <sub>B</sub>		300	ns
t <sub>SDA-R</sub>	Rise time of SDA signal	20 + 0.1C <sub>B</sub>		300	ns
t <sub>SDA-F</sub>	Fall time of SDA signal	20 + 0.1C <sub>B</sub>		300	ns
t <sub>P-SU</sub>	Setup time for STOP condition	600			ns
t <sub>SP</sub>	Pulse width of spike suppressed			50	ns
C <sub>b</sub>	Capacitive load for each bus line			400	pf

## 6.7 Typical Characteristics

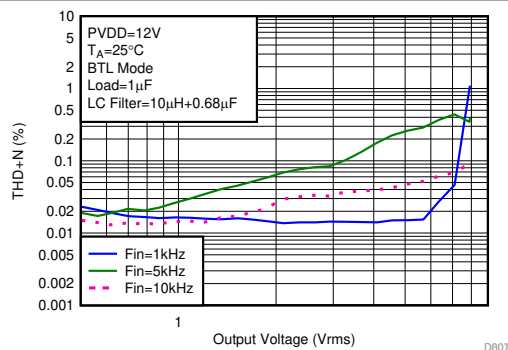
### 6.7.1 Bridge Tied Load (BTL) Configuration

Free-air room temperature 25°C (unless otherwise noted) Measurements were made using DRV5825PEVM board and Audio Precision System 2722 with Analog Analyzer filter set to 20-kHz brickwall filter. All measurements taken with audio frequency set to 1 kHz and device PWM frequency set to 768 kHz with 175kHz Loop Bandwidth and BD Modulation, 2 channel run, PPC3 setting with 5.5A current limiter, unless otherwise noted.



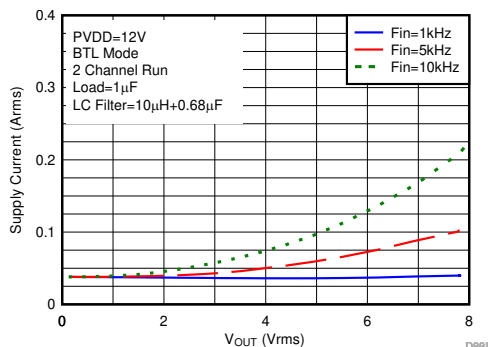
LC Filter = 10μH + 0.68μF       $V_{OUT} = 6 V_P$       Load = 1 μF

Figure 6-1. THD+N vs Frequency



LC Filter = 10μH + 0.68μF      Input Frequency = 1kHz, 5kHz, 10kHz      Load = 1 μF

Figure 6-2. THD+N vs Output Voltage (Per Channel)

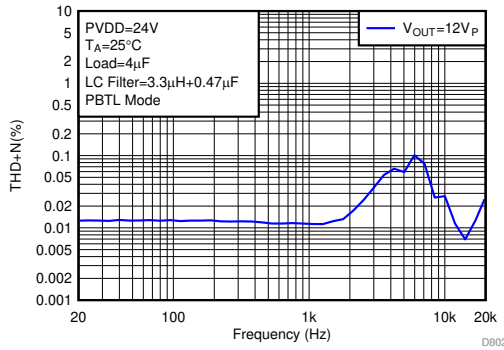


LC Filter = 10μH + 0.68μF      Input Frequency = 1kHz, 5kHz, 10kHz      Load = 1 μF

Figure 6-3. Supply Current vs Output Voltage (Per Channel)

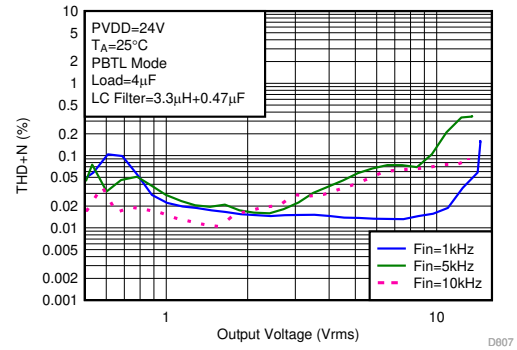
### 6.7.2 Parallel Bridge Tied Load (PBTL) Configuration

Free-air room temperature 25°C (unless otherwise noted) Measurements were made using DRV5825PEVM board and Audio Precision System 2722 with Analog Analyzer filter set to 20-kHz brickwall filter. All measurements taken with audio frequency set to 1 kHz and device PWM frequency set to 768 kHz with 175kHz Loop bandwidth, BD Modulation, the LC filter used was 3.3  $\mu$ H / 0.47  $\mu$ F ( Post-Filter PBTL), PPC3 setting with 9A current limiter, unless otherwise noted.



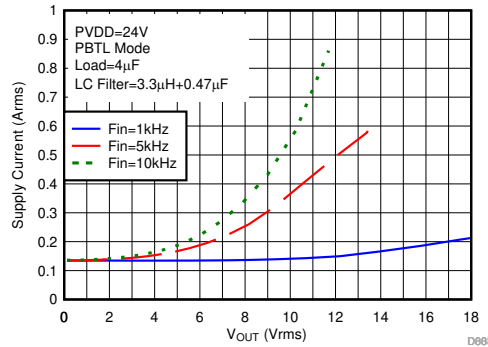
LC Filter = 3.3 $\mu$ H + 0.47 $\mu$ F      V<sub>OUT</sub> = 12 V<sub>P</sub>      Load = 4  $\mu$ F

Figure 6-4. THD+N vs Frequency



LC Filter = 3.3 $\mu$ H + 0.47 $\mu$ F      Input Frequency = 1kHz,5kHz,10kHz      Load = 4  $\mu$ F

Figure 6-5. THD+N vs Output Voltage



LC Filter = 3.3 $\mu$ H + 0.47 $\mu$ F      Input Frequency = 1kHz,5kHz,10kHz      Load = 4  $\mu$ F

Figure 6-6. Supply Current vs Output Voltage

## Parameter Measurement Information

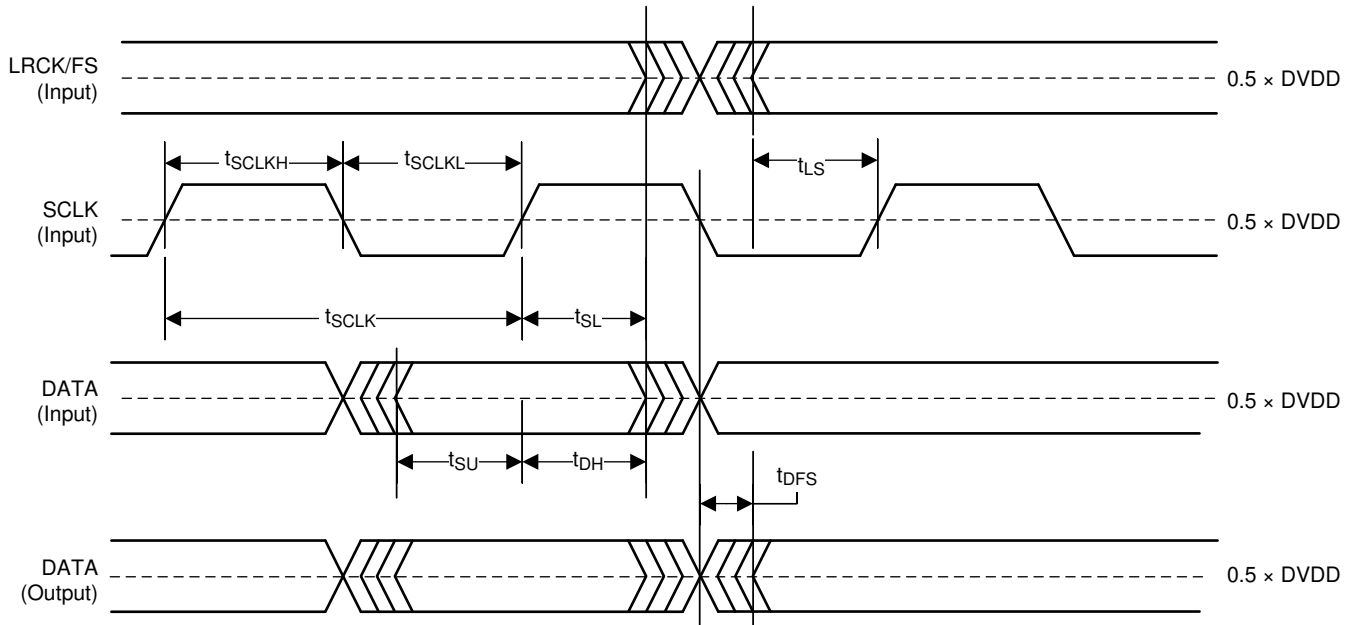


FIG 7-1. Serial Audio Port Timing in Slave Mode

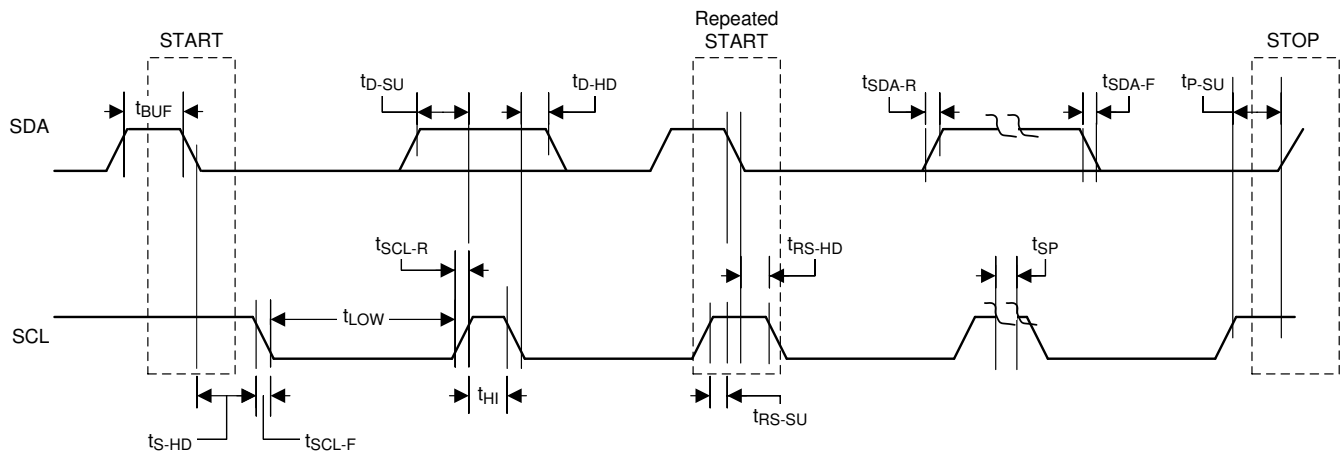
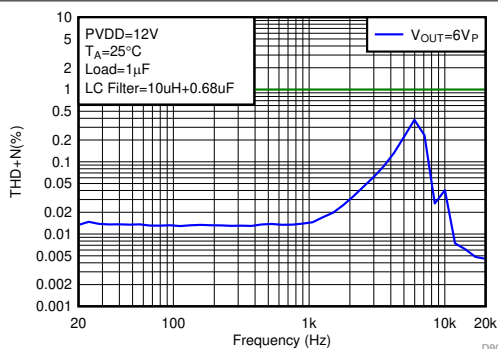


FIG 7-2. I<sup>2</sup>C Communication Port Timing Diagram

## 7 Typical Characteristics

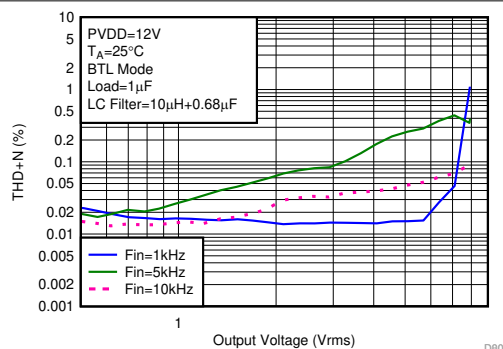
### 7.1 Bridge Tied Load (BTL) Configuration

Free-air room temperature 25°C (unless otherwise noted) Measurements were made using DRV5825PEVM board and Audio Precision System 2722 with Analog Analyzer filter set to 20-kHz brickwall filter. All measurements taken with audio frequency set to 1 kHz and device PWM frequency set to 768 kHz with 175kHz Loop Bandwidth and BD Modulation, 2 channel run, PPC3 setting with 5.5A current limiter, unless otherwise noted.



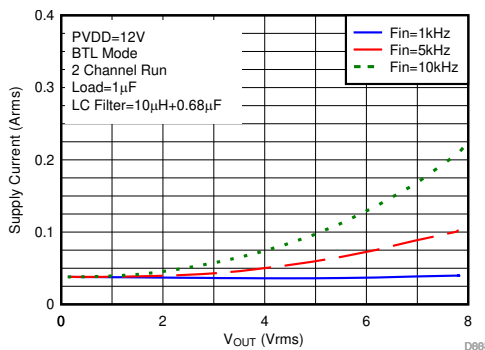
LC Filter = 10µH + 0.68µF       $V_{OUT} = 6 V_P$       Load = 1 µF

7-1. THD+N vs Frequency



LC Filter = 10µH + 0.68µF      Input Frequency = 1kHz, 5kHz, 10kHz      Load = 1 µF

7-2. THD+N vs Output Voltage (Per Channel)

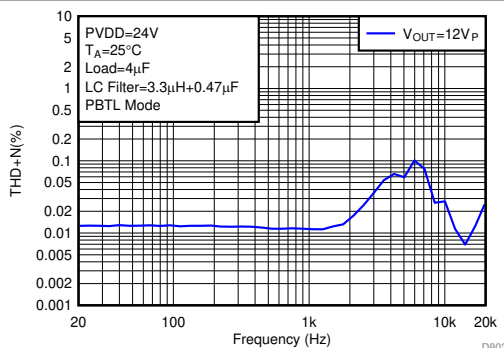


LC Filter = 10µH + 0.68µF      Input Frequency = 1kHz, 5kHz, 10kHz      Load = 1 µF

7-3. Supply Current vs Output Voltage (Per Channel)

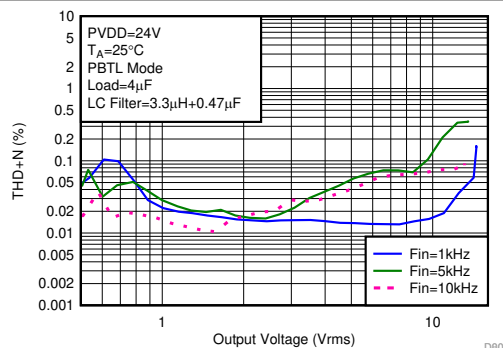
## 7.2 Parallel Bridge Tied Load (PBTTL) Configuration

Free-air room temperature 25°C (unless otherwise noted) Measurements were made using DRV5825PEVM board and Audio Precision System 2722 with Analog Analyzer filter set to 20-kHz brickwall filter. All measurements taken with audio frequency set to 1 kHz and device PWM frequency set to 768 kHz with 175kHz Loop bandwidth, BD Modulation, the LC filter used was 3.3  $\mu$ H / 0.47  $\mu$ F ( Post-Filter PBTTL), PPC3 setting with 9A current limiter, unless otherwise noted.



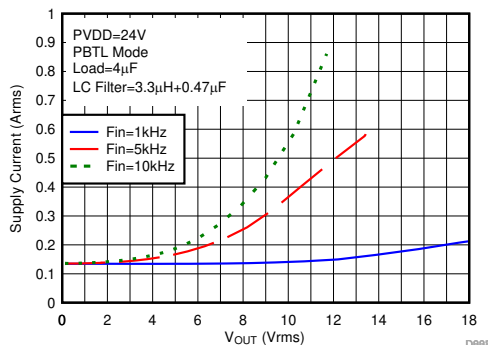
LC Filter = 3.3 $\mu$ H + 0.47 $\mu$ F      V<sub>OUT</sub> = 12 V<sub>P</sub>      Load = 4  $\mu$ F

7-4. THD+N vs Frequency



LC Filter = 3.3 $\mu$ H + 0.47 $\mu$ F      Input Frequency = 1kHz,5kHz,10kHz      Load = 4  $\mu$ F

7-5. THD+N vs Output Voltage



LC Filter = 3.3 $\mu$ H + 0.47 $\mu$ F      Input Frequency = 1kHz,5kHz,10kHz      Load = 4  $\mu$ F

7-6. Supply Current vs Output Voltage

## 8 Detailed Description

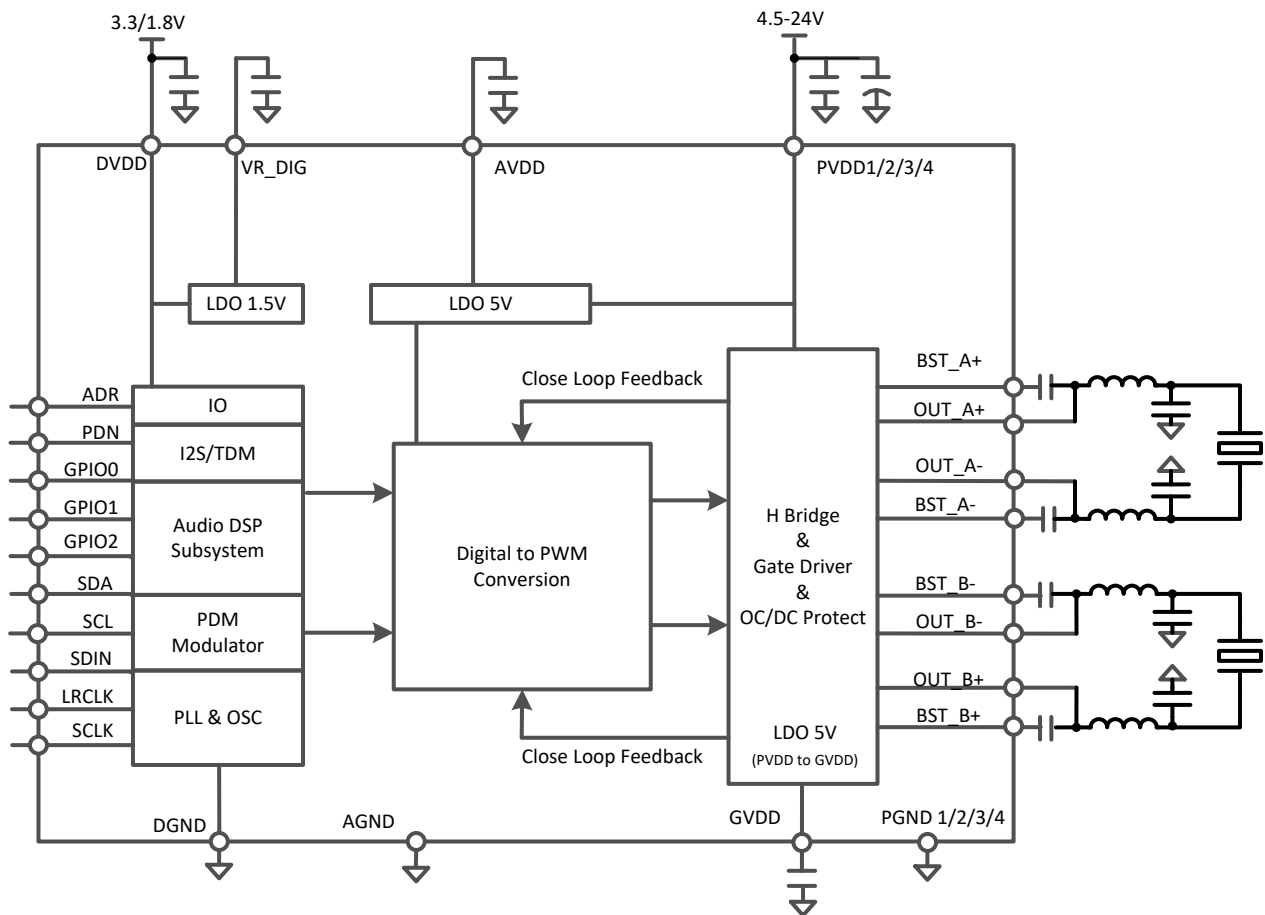
### 8.1 Overview

The DRV5825P device combines 4 main building blocks into a single cohesive device that maximizes sound quality, flexibility, and ease of use. The 4 main building blocks are listed as follows:

- A stereo digital to PWM modulator.
- An Audio DSP subsystem.
- A flexible close-loop amplifier capable of operating in stereo or mono, at several different switching frequencies, and with a variety of output voltages and loads.
- An I<sup>2</sup>C control port for communication with the device

The device requires only two power supplies for proper operation. A DVDD supply is required to power the low voltage digital circuitry. Another supply, called PVDD, is required to provide power to the output stage of the audio amplifier. Two internal LDOs convert PVDD to 5 V for GVDD and AVDD and to 1.5V for DVDD respectively.

### 8.2 Functional Block Diagram



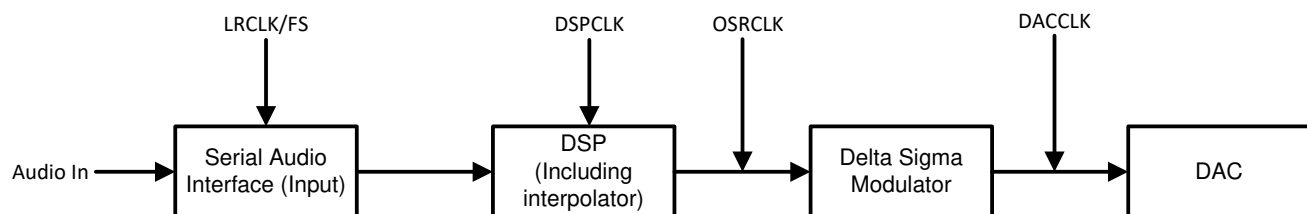
## 8.3 Feature Description

### 8.3.1 Power Supplies

For system design, DRV5825P needs a 3.3-V or 1.8-V supply in addition to the (typical) 12 V or 24 V power-stage supply. Two internal voltage regulators provide suitable voltage levels for the gate drive circuitry and internal circuitry. The external pins are provided only as a connection point for off-chip bypass capacitors to filter the supply. Connecting external circuitry to these regulator outputs may result in reduced performance and damage to the device. Additionally, all circuitry requiring a floating voltage supply, that is, the high-side gate drive, is accommodated by built-in bootstrap circuitry requiring only a few external capacitors. To provide good electrical and acoustical characteristics, the PWM signal path for the output stage is designed as identical, independent half-bridges. For this reason, each half-bridge has separate bootstrap pins (BST\_x). The gate drive voltages (GVDD) are derived from the PVDD voltage. Special attention should be paid to placing all decoupling capacitors as close to their associated pins as possible. In general, inductance between the power-supply pins and decoupling capacitors must be avoided. For a properly functioning bootstrap circuit, a small ceramic capacitor must be connected from each bootstrap pin (BST\_x) to the power-stage output pin (OUT\_x). When the power-stage output is low, the bootstrap capacitor is charged through an internal diode connected between the gate-drive regulator output pin (GVDD) and the bootstrap pin. When the power-stage output is high, the bootstrap capacitor potential is shifted above the output potential and thus provides a suitable voltage supply for the high-side gate driver.

### 8.3.2 Device Clocking

The DRV5825P device has flexible systems for clocking. Internally, the device requires a number of clocks, mostly at related clock rates to function correctly. All of these clocks can be derived from the Serial Audio Interface.



**8-1. Audio Flow with Respective Clocks**

8-1 shows the basic data flow and clock Distribution.

The Serial Audio Interface typically has 3 connection pins which are listed as follows:

- SCLK (Bit Clock)
- LRCLK/FS (Left/Right Word Clock or Frame Sync)
- SDIN (Input Data)

The device has an internal PLL that is used to take SCLK and create the higher rate clocks required by the DSP and the DAC clock.

The DRV5825P device has an audio sampling rate detection circuit that automatically senses which frequency the sampling rate is operating. Common audio sampling frequencies of 32 kHz, 44.1kHz – 48 kHz, 88.2 kHz – 96 kHz are supported. The sampling frequency detector sets the clock for DAC and DSP automatically.

If the input LRCLK/SCLK stopped during music playing, the DRV5825P DSP switches to sleep state and waiting for the clock recovery (Class D output switches to Hiz automatically ), once LRCLK/SCLK recovered, DRV5825P auto recovers to the play mode. There is no need to reload the DSP code.

### 8.3.3 Serial Audio Port – Clock Rates

The serial audio interface port is a 3-wire serial port with the signals LRCLK/FS, SCLK, and SDIN. SCLK is the serial audio bit clock, used to clock the serial data present on SDIN into the serial shift register of the audio interface. Serial data is clocked into the DRV5825P device with SCLK. The LRCLK/FS pin is the serial audio left/right word clock or frame sync when the device is operated in TDM Mode.

**表 8-1. Audio Data Formats, Bit Depths and Clock Rates**

FORMAT	DATA BITS	MAXIMUM LRCLK/FS FREQUENCY (kHz)	SCLK RATE (f <sub>s</sub> )
I <sup>2</sup> S/LJ/RJ	32, 24, 20, 16	32 to 96	64, 32
TDM	32, 24, 20, 16	32	128
		44.1, 48	128, 256, 512
		96	128, 256

When Clock halt, non-supported SCLK to LRCLK(FS) ratio is detected, the device reports Clock Error in Register 113 (Register Address 0x71).

### 8.3.4 Clock Halt Auto-recovery

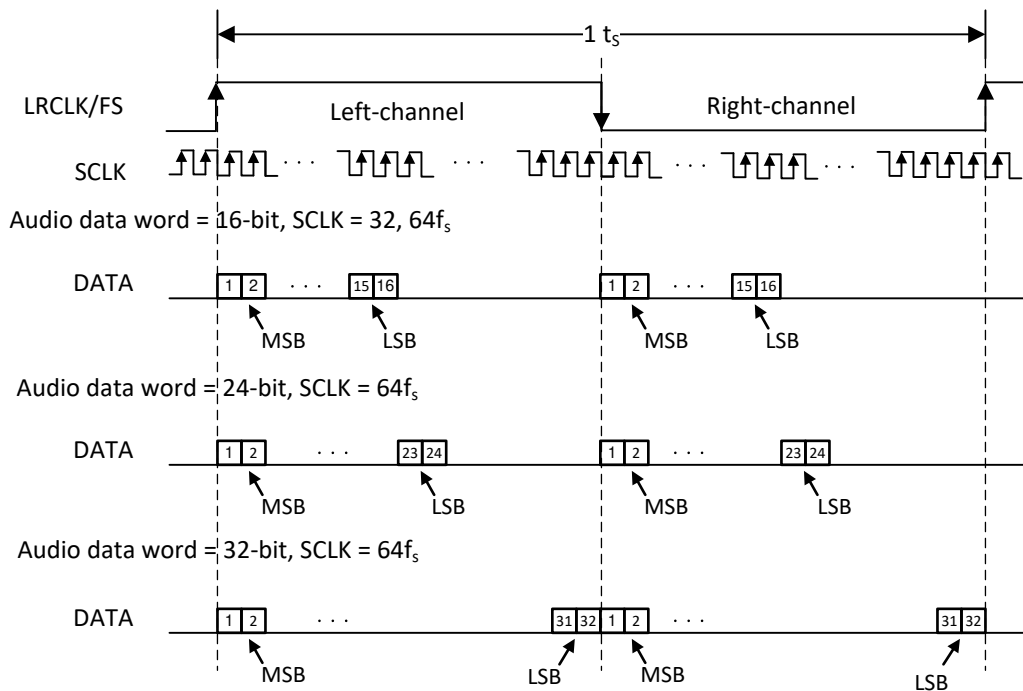
As some of host processor will Halt the I<sup>2</sup>S clock when there is no audio playing. When Clock halt, the device puts all channels into the Hi-Z state and reports Clock Error in Register 113 (Register Address 0x71). After audio clocks recovery, the device automatically returns to the previous state.

### 8.3.5 Sample Rate on the Fly Change

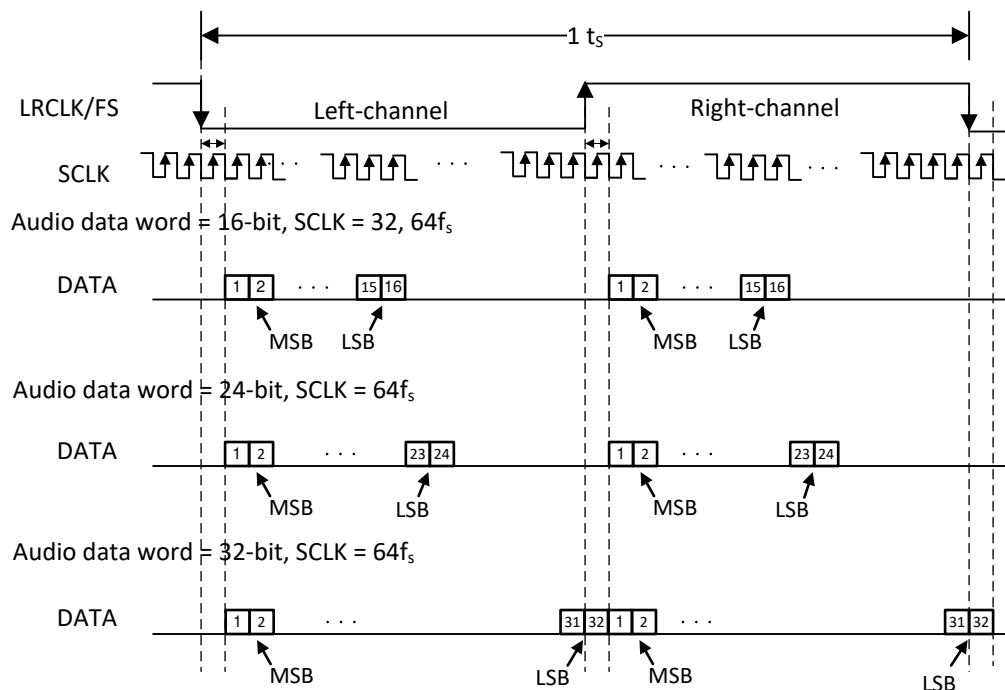
DRV5825P supports LRCLK(FS) rate on the fly change. For example, change LRCLK from 32kHz to 48kHz or 96kHz, Host processor needs to put the LRCLK(FS)/SCLK to Halt state at least 10ms before changing to the new sample rate.

### 8.3.6 Serial Audio Port - Data Formats and Bit Depths

The device supports industry-standard audio data formats, including standard I<sup>2</sup>S, left-justified, right-justified and TDM/DSP data. Data formats are selected via Register (Register Address 0x33h -D[5:4]). If the high width of LRCLK/FS in TDM/DSP mode is less than 8 cycles of SCLK, the register (Register Address 0x33h -D[3:2]) should set to 01. All formats require binary two's complement, MSB-first audio data; up to 32-bit audio data is accepted. All the data formats, word length and clock rate supported by this device are shown in 表 8-1. The data formats are detailed in 图 8-2 through 图 8-6. The word length are selected via Register (Register Address 0x33h -D[1:0]). The offsets of data are selected via Register (Register Address 0x33h -D[7]) and Register (Register Address 0x34h -D[7:0]). Default setting is I<sup>2</sup>S and 24 bit word length.



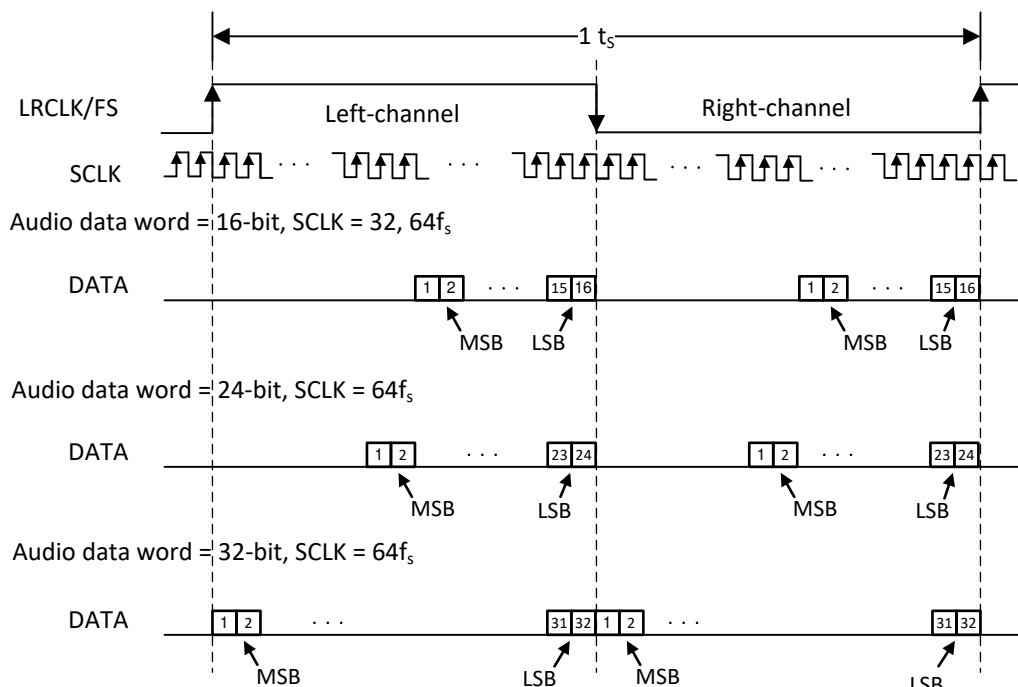
8-2. Left Justified Audio Data Format



I<sup>2</sup>S Data Format; L-channel = LOW, R-channel = HIGH

I<sup>2</sup>S Data Format; L-channel = LOW, R-channel = HIGH

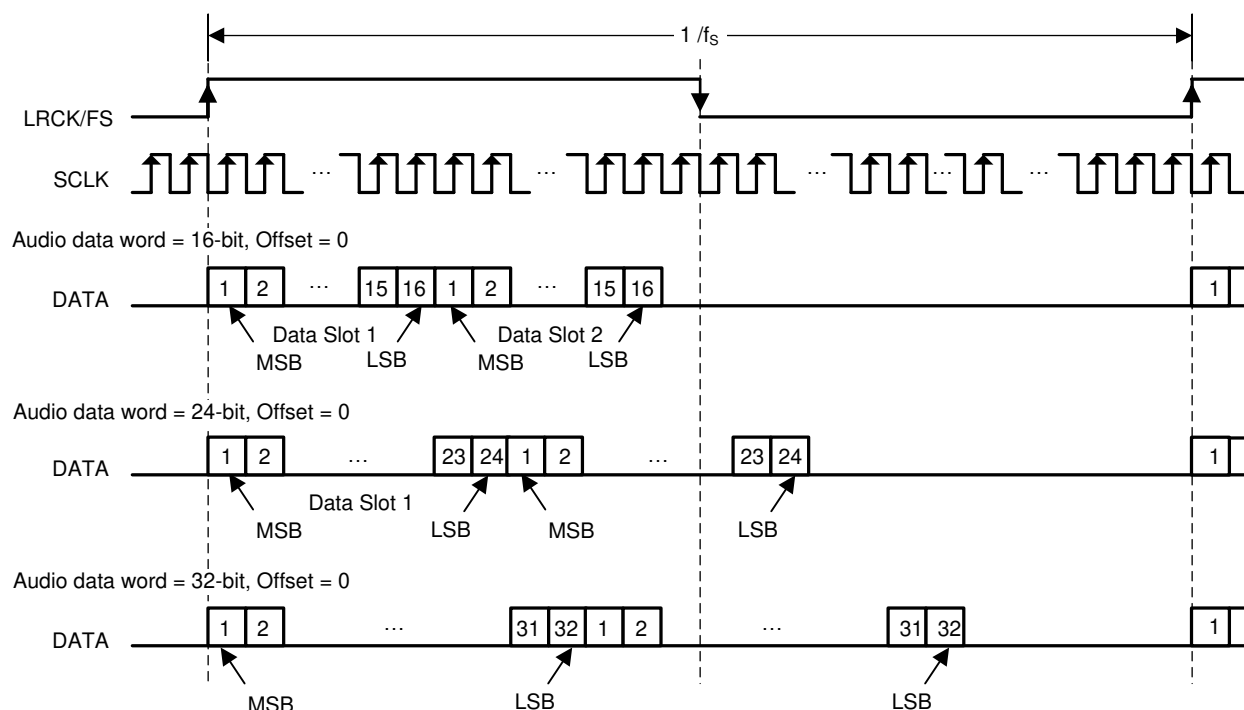
8-3. I<sup>2</sup>S Audio Data Format



Right-Justified Data Format; L-channel = HIGH, R-channel = LOW

Right Justified Data Format; L-channel = HIGH, R-channel = LOW

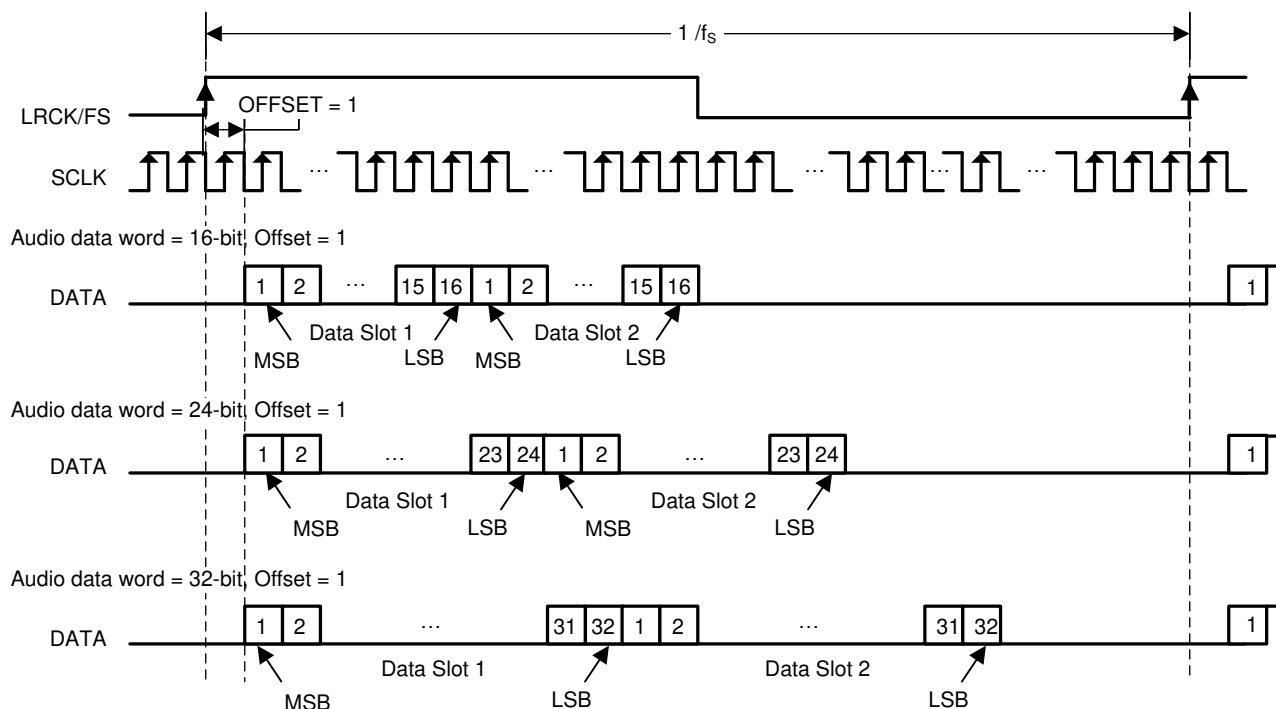
Figure 8-4. Right Justified Audio Data Format



TDM Data Format with OFFSET = 0

In TDM Modes, Duty Cycle of LRCK/FS should be 1x SCLK at minimum. Rising edge is considered frame start.

Figure 8-5. TDM 1 Audio Data Format



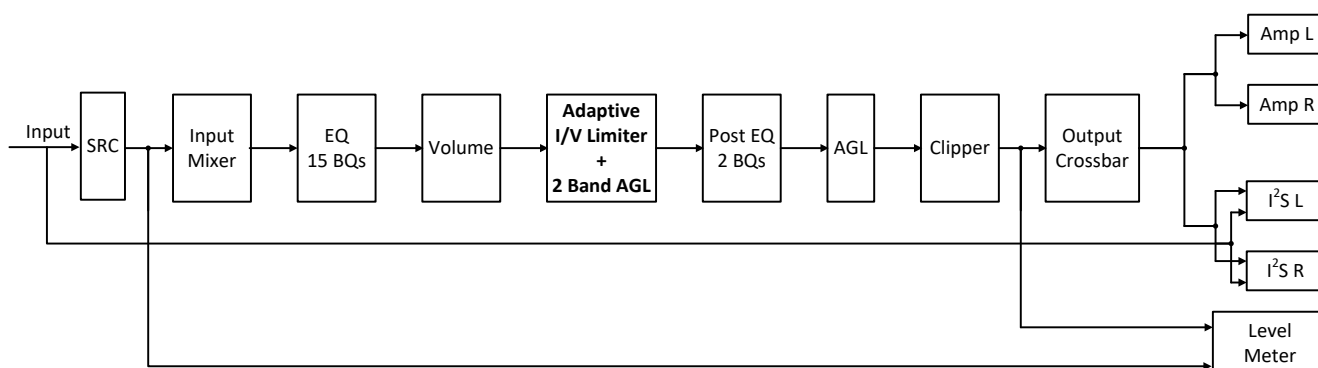
TDM Data Format with OFFSET = 1

In TDM Modes, Duty Cycle of LRCK/FS should be 1x SCLK at minimum. Rising edge is considered frame start.

## 8-6. TDM 2 Audio Data Format

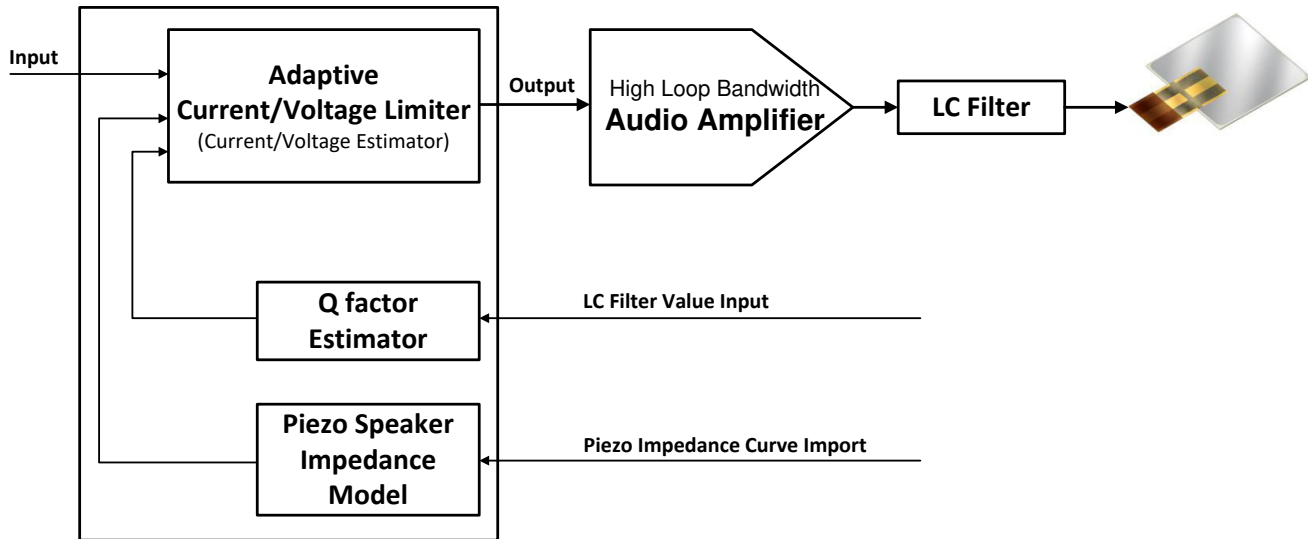
### 8.3.7 Digital Audio Processing

DRV5825P DSP can provide advanced audio processing functions, such as SRC (sample rate convertor), Input Mixer, 15 EQ bands, volume control, Smart Piezo Drive Algorithm, 2 Post EQs, Full band AGL, Clipper and Output crossbar, Level meter.



8-7. DRV5825P Audio Signal Processing

Piezo speaker behaves like a capacitor with low impedance at high frequency which means high frequency current is easier to trigger amplifier over current protection. Capacitive load also causes high Q to LC filter. Piezo drive algorithm do adaptive current/voltage limitation based on output filter's frequency response and piezo impedance. The current/voltage limiter only been triggered with large input level which means this algorithm enhance the dynamic range keep the original sound quality.



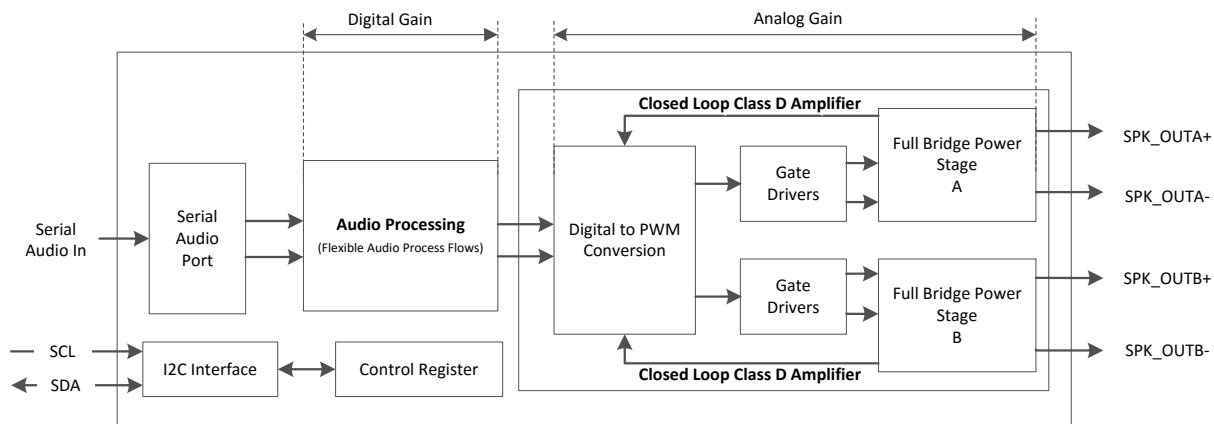
8-8. Adaptive I/V Limiter Algorithm

### 8.3.8 Class D Audio Amplifier

Following the digital clipper, the interpolated audio data is next sent to the Closed Loop Class-D amplifier, whose first stage is Digital to PWM Conversion (DPC) block. In this block, the stereo audio data is translated into two pairs of complimentary pulse width modulated (PWM) signals which are used to drive the outputs of the speaker amplifier. Feedback loops around the DPC ensure constant gain across supply voltages, reduce distortion, and increase immunity to power supply injected noise and distortion. The analog gain is also applied in the Class-D amplifier section of the device. The gain structures are discussed in detail below for both 8-9 and 表 8-2. The switching rate of the amplifier is configurable by register (Register Address 0x02h -D[6:4])

#### 8.3.8.1 Speaker Amplifier Gain Select

A combination of digital gain and analog gain is used to provide the overall gain of the speaker amplifier. As seen in 8-9, the audio path of the DRV5825P consists of a digital audio input port, a digital audio path, a digital to PWM converter (DPC), a gate driver stage, a Class D power stage, and a feedback loop which feeds the output information back into the DPC block to correct for distortion sensed on the output pins. The total amplifier gain is comprised of digital gain, shown in the digital audio path and the analog gain from the input of the analog modulator to the output of the speaker amplifier power stage.



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8-9. Speaker Amplifier Gain

As shown in [Figure 8-9](#), the first gain stage for the speaker amplifier is present in the digital audio path. It consists of the volume control and the digital boost block. The volume control is set to 0 dB by default, it does not change. For all settings of the register 0x54, AGAIN[4:0], the digital boost block remains at 0 dB. These gain settings ensure that the output signal is not clipping at different PVDD levels. 0dBFS output is 29.5-V peak output voltage

**表 8-2. Analog Gain Setting**

AGAIN <4:0>	GAIN (dBFS)	AMPLIFIER OUTPUT PEAK VOLTAGE (V <sub>p</sub> /FS)	AMPLIFIER OUTPUT PEAK VOLTAGE (dBV/FS)
00000 (Default Setting)	0	29.5V <sub>p</sub> /FS (Default Setting)	29.4dBV/FS
00001	-0.5	27.85V <sub>p</sub> /FS	28.9dBV/FS
00010	-1.0	26.29V <sub>p</sub> /FS	28.4dBV/FS
00011	-1.5	24.82V <sub>p</sub> /FS	27.9dBV/FS
.....	.....	.....	.....
11111	-15.5	4.95V <sub>p</sub> /FS	13.9dBV/FS

### 8.3.8.2 Class D Loop Bandwidth and Switching Frequency Setting

DRV5825P closed loop structure provides Loop bandwidth setting option (Setting by register 83 -Register address 0x53h-D[6-5]) to co-work with different switching frequency (Setting by register 2 -Register address 0x02h-D[6-4]). [表 8-3](#) shows recommended settings for the Loop Bandwidth and Switching Frequency selection. Same Fsw, Better THD+N performance with higher BW.

**表 8-3. Loop Bandwidth and Switching Frequency Setting**

Modulation Scheme	Fsw	BW (Loop Band Width)	Notes
BD	768kHz	80kHz, 100kHz, 120kHz, 175kHz	Principle: Fsw (Switching Frequency) ≥ 3 × Loop Bandwidth. Suggest to use 175kHz BW with 768kHz Fsw.

## 8.4 Device Functional Modes

### 8.4.1 Software Control

The DRV5825P device is configured via an I<sup>2</sup>C communication port.

The I<sup>2</sup>C Communication Protocol is detailed in the I<sup>2</sup>C Communication Port section. The I<sup>2</sup>C timing requirements are described in the I<sup>2</sup>C Bus Timing – Standard and I<sup>2</sup>C Bus Timing – Fast sections.

There are two methods to program DRV5825P DSP memory.

- Loading with I<sup>2</sup>C Communication Port by host processor. This method is recommend for most of applications.
- Fast loading from external EEPROM with SPI communication Port. This method can be used in some applications which need fast loading to save initialization time or release the Host Controller's loading. DRV5825P supports to load the DSP memory data from external EEPROM via SPI. The GPIOs can be configured as SI,SO and SCK for EEPROM via Register (0x60,0x61,0x62,0x63,0x64). The chip selection  $\overline{CS}$  of EEPROM is controlled by the Host Processor. See AppNote: [Load TAS5825M Configurations from EEPROM via SPI](#).

### 8.4.2 Speaker Amplifier Operating Modes

The DRV5825P device can be used with two different amplifier configurations, can be configured by Register 0x02h -D[2]:

- BTL Mode
- PBTL Mode

#### 8.4.2.1 BTL Mode

In BTL mode, the DRV5825P amplifies two independent signals, which represent the left and right portions of a stereo signal. The amplified left signal is presented on differential output pair shown as OUT\_A+ and OUT\_A-, the amplified right signal is presented on differential output pair shown as OUT\_B+ and OUT\_B-.

### 8.4.2.2 PBTL Mode

The PBTL mode of operation is used to describe operation in which the two outputs of the device are placed in parallel with one another to increase the power sourcing capabilities of the device. On the output side of the DRV5825P device, the summation of the devices can be done before the filter in a configuration called Pre-Filter Parallel Bridge Tied Load (PBTL). However, the two outputs can be required to merge together after the inductor portion of the output filter. Doing so does require two additional inductors, but allows smaller, less expensive inductors to be used because the current is divided between the two inductors. The process is called Post-Filter PBTL. On the input side of the DRV5825P device, the input signal to the PBTL amplifier is left frame of I<sup>2</sup>S or TDM data.

### 8.4.3 Low EMI Modes

DRV5825P employs several modes to minimize EMI during playing audio, and they can be used based on different applications.

#### 8.4.3.1 Spread Spectrum

Spread spectrum is used in some inductor free or inductor less case to minimize EMI noise. The DRV5825P supports Spread Spectrum with triangle mode.

User need configure register SS\_CTRL0 (0x6B) to Enable triangle mode and enable spread spectrum, select spread spectrum frequency and range with SS\_CTRL1 (0x6C). For 768kHz F<sub>SW</sub> which configured by DEVICE\_CTRL1 (0x02), the spread spectrum frequency and range are described in 表 8-4.

**表 8-4. Triangle Mode Spread Spectrum Frequency and Range Selection**

SS_TRI_CTRL[3:0]	0	1	2	3	4	5	6	7
Triangle Freq	24k				48k			
Spread Spectrum Range	5%	10%	20%	25%	5%	10%	20%	25%

User Application example: Central Switching Frequency is 768kHz, Triangle Frequency is 24kHz.

Register 0x6b = 0x03 // Enable Spread Spectrum

Register 0x6c = 0x03 // SS\_CTRL[3:0]=0001, Triangle Frequency = 24kHz, Spread Spectrum Range should be 10% (730kHz~806kHz)

#### 8.4.3.2 Channel to Channel Phase Shift

This device supports channel to channel 180-degree PWM phase shift to minimize the EMI. Bit 0 of Register 0x53 can be used to disable or enable the phase shift.

#### 8.4.3.3 Multi-Devices PWM Phase Synchronization

DRV5825P support up to 4 phases selection for the multi devices application system. For example, when a system integrated 4 DRV5825P devices, user can select phase0/1/2/3 for each device by register PHASE\_CTRL(0x6A), which means there is a 45 degree phase shift between each device to minimize the EMI.

There are two methods for Multi-Device PWM phase synchronization. Phase Synchronization With I<sup>2</sup>S Clock In Startup Phase or Phase Synchronization With GPIO.

##### 8.4.3.3.1 Phase Synchronization With I<sup>2</sup>S Clock In Startup Phase

1. Step 1, Halt I<sup>2</sup>S clock.
2. Step 2, Configure each device phase selection and enable the phase synchronization. For example: Register 0x6A=0x03 for device 0; Register 0x6A=0x07 for device 1; Register 0x6A=0x0B for device 2; Register 0x6A=0x0F for device 3.
3. Step 3, Configure each device into HIZ mode.
4. Step 4, Provide I<sup>2</sup>S to each device. Phase synchronization for all 4 devices will be automatically done by internal sequence.
5. Step 5, Initialize the DSP code (This step can be skipped if only need to do the Phase Synchronization).

6. Step 6, Device to Device PWM phase shift should be fixed with 45 degree.

#### 8.4.3.3.2 Phase Synchronization With GPIO

1. Step 1, Connect GPIOx pin of each device to SOC's GPIO pin on PCB.
2. Step 2, Configure each device GPIOx as phase sync input usage by registers GPIO\_CTRL (0x60) and GPIO\_INPUT\_SEL (0x64).
3. Step 3, Select different phase for each device and enable phase synchronization by register PHASE\_CTRL (0x6A).
4. Step 4, Configure each device into PLAY mode by register DEVICE\_CTRL2 (0x03) and monitor the POWER\_STATE register (0x68) until device changed to HIZ state.
5. Step 5, Give a 0 to 1 toggle on SOC GPIO. Then all 4 devices will enter into PLAY mode and device to Device PWM phase shift should be fixed with 45 degree.
6. Step 6, Phase Synchronization has been finished. Configure the GPIOx pin to other function based on the application.

#### 8.4.4 Device State Control

Except Shutdown Mode, DRV5825P has other 4 states for different power dissipation which listed in the *Electrical Characteristics Table*.

- Deep Sleep Mode. Register 0x03h -D[1:0]=00, Device stays in Deep Sleep Mode. In this mode, I<sup>2</sup>C block keep works. This mode can be used to extend the battery life time in some portable speaker application case, once the host processor stopped playing audio for a long time, DRV5825P can be set to Deep Sleep Mode to minimize power dissipation until host processor start playing audio again. Device returns back to Play Mode by setting Register 0x03h -D[1:0] to 11. Compare with Shutdown Mode (Pull  $\overline{\text{PDN}}$  Low), enter or exit Deep Sleep Mode, DSP keeps active.
- Sleep Mode. Register 0x03h -D[1:0]=01, Device stays in Sleep Mode. In this mode, I<sup>2</sup>C block, Digital core, DSP Memory, 5V Analog LDO keep works. Compare with Shutdown Mode (Pull  $\overline{\text{PDN}}$  Low), enter or exit Sleep Mode, DSP keeps active.
- Output Hiz Mode. Register 0x03h -D[1:0]=10, Device stays in Hiz Mode. In this mode, Only output driver set to be Hiz state, all other block work normally.
- Play Mode. Register 0x03h -D[1:0]=11, Device stays in Play Mode.

#### 8.4.5 Device Modulation

DRV5825P supports piezo drive algorithm based on BD modulation.

With BD modulation, each output is switching from 0 volts to the supply voltage. The OUTPx and OUTNx are in phase with each other with no input so that there is little or no current in the speaker. The duty cycle of OUTPx is greater than 50% and OUTNx is less than 50% for positive output voltages. The duty cycle of OUTPx is less than 50% and OUTNx is greater than 50% for negative output voltages. The voltage across the load sits at 0 V throughout most of the switching period, reducing the switching current, which reduces any I<sup>2</sup>R losses in the load.

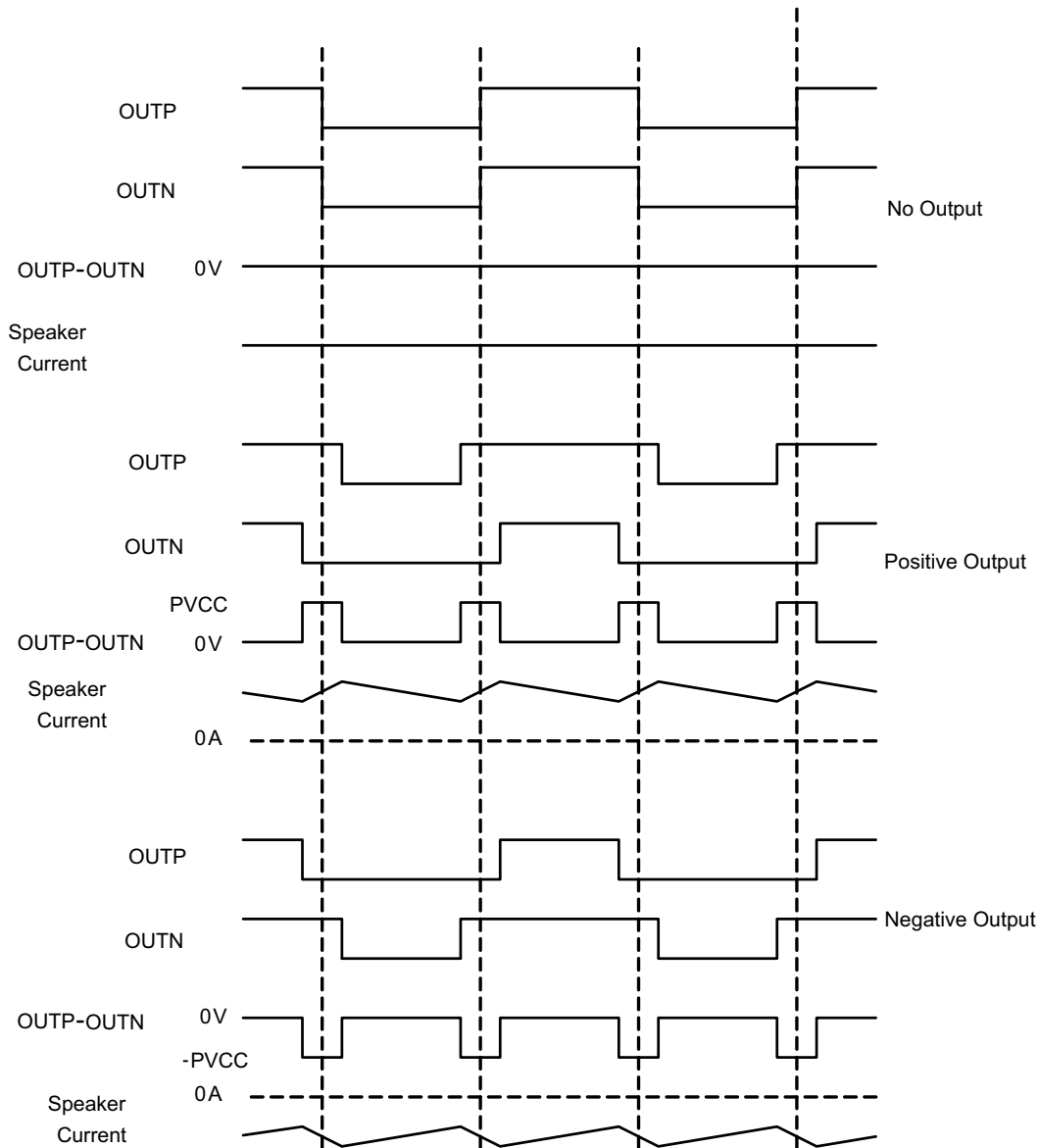


图 8-10. BD Mode Modulation

## 8.5 Programming and Control

### 8.5.1 I<sup>2</sup>C Serial Communication Bus

The device has a bidirectional serial control interface that is compatible with I<sup>2</sup>C bus protocol and supports 100 and 400-kHz data transfer rates for random and sequential write and read operations as a slave device. Because the DRV5825P register map and DSP memory spans multi pages, the user should change from page to page before writing individual register or DSP memory. Changing from page to page is accomplished via register 0 on each page. This register value selects the page address, from 0 to 255. All registers listed in DRV5825P Datasheet belongs to Page 0

### 8.5.2 I<sup>2</sup>C Slave Address

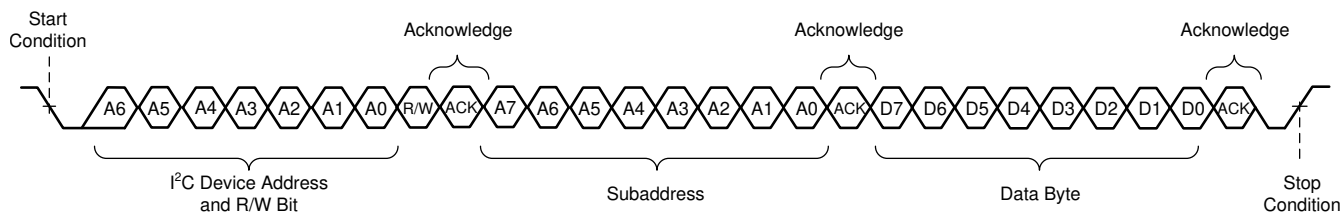
The DRV5825P device has 7 bits for the slave address. The first five bits (MSBs) of the slave address are factory preset to 10011(0x9x). The next two bits of address byte are the device select bits which can be user-defined by ADR pin in 表 8-5.

**表 8-5. I<sup>2</sup>C Slave Address Configuration**

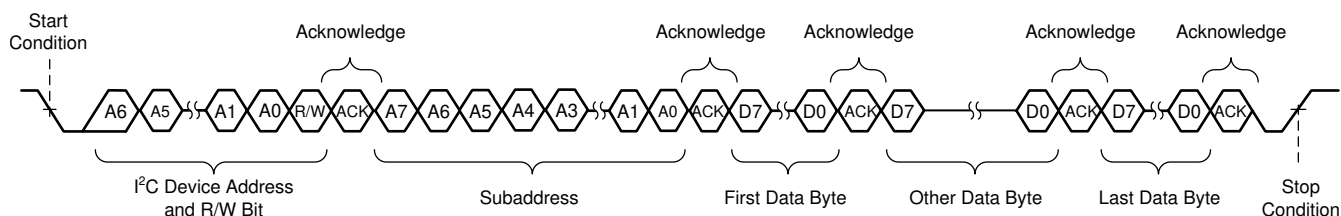
ADR PIN Configuration	MSBs					User Define		LSB
0 $\Omega$ to GND	1	0	0	1	1	0	0	R/ $\bar{W}$
1k $\Omega$ to GND	1	0	0	1	1	0	1	R/ $\bar{W}$
4.7k $\Omega$ to GND	1	0	0	1	1	1	0	R/ $\bar{W}$
15k $\Omega$ to GND	1	0	0	1	1	1	1	R/ $\bar{W}$

**8.5.2.1 Random Write**

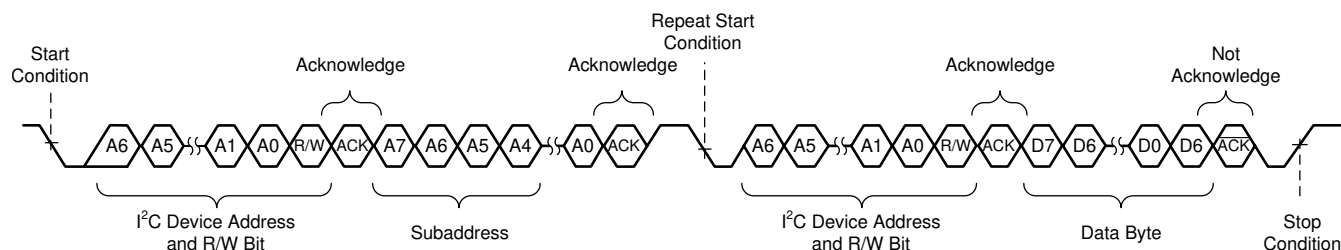
As shown in [图 8-11](#), a single-byte data-write transfer begins with the master device transmitting a start condition followed by the I<sup>2</sup>C device address and the read/write bit. The read/write bit determines the direction of the data transfer. For a write data transfer, the read/write bit is a 0. After receiving the correct I<sup>2</sup>C device address and the read/write bit, the device responds with an acknowledge bit. Next, the master transmits the address byte corresponding to the internal memory address being accessed. After receiving the address byte, the device again responds with an acknowledge bit. Next, the master device transmits the data byte to be written to the memory address being accessed. After receiving the data byte, the device again responds with an acknowledge bit. Finally, the master device transmits a stop condition to complete the single-byte data-write transfer.

**图 8-11. Random Write Transfer****8.5.2.2 Sequential Write**

A sequential data-write transfer is identical to a single-byte data-write transfer except that multiple data bytes are transmitted by the master to the device as shown in [图 8-12](#). After receiving each data byte, the device responds with an acknowledge bit and the I<sup>2</sup>C subaddress is automatically incremented by one.

**图 8-12. Sequential Write Transfer****8.5.2.3 Random Read**

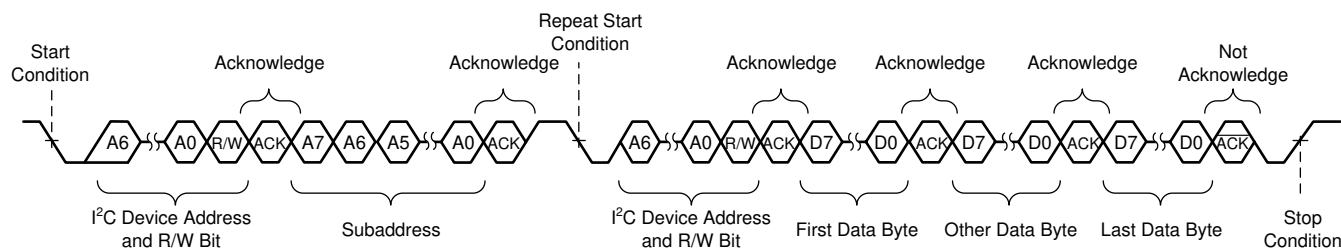
As shown in [图 8-13](#), a single-byte data-read transfer begins with the master device transmitting a start condition followed by the I<sup>2</sup>C device address and the read/write bit. For the data-read transfer, both a write followed by a read are actually done. Initially, a write is done to transfer the address byte of the internal memory address to be read. As a result, the read/write bit is a 0. After receiving the address and the read/write bit, the device responds with an acknowledge bit. In addition, after sending the internal memory address byte, the master device transmits another start condition followed by the address and the read/write bit again. This time the read/write bit is a 1, indicating a read transfer. After receiving the address and the read/write bit, the device again responds with an acknowledge bit. Next, the device transmits the data byte from the memory address being read. After receiving the data byte, the master device transmits a not-acknowledge followed by a stop condition to complete the single-byte data-read transfer.



**FIGURE 8-13. Random Read Transfer**

#### 8.5.2.4 Sequential Read

A sequential data-read transfer is identical to a single-byte data-read transfer except that multiple data bytes are transmitted by the device to the master device as shown in [FIGURE 8-14](#). Except for the last data byte, the master device responds with an acknowledge bit after receiving each data byte and automatically increments the I<sup>2</sup>C sub address by one. After receiving the last data byte, the master device transmits a not-acknowledge followed by a stop condition to complete the transfer.



**FIGURE 8-14. Sequential Read Transfer**

### 8.5.2.5 DSP Memory Book, Page and BQ update

On Page 0x00 of each book, Register 0x7f is used to change the book. Register 0x00 of each page is used to change the page. To change a Page first write 0x00 to Register 0x00 to switch to Page 0 then write the book number to Register 0x7f on Page 0. To switch between pages in a book, simply write the page number to register 0x00.

All the Biquad Filters coefficients are addressed in book 0xAA. The five coefficients of every Biquad Filter should be written entirely and sequentially from the lowest address to the highest address. The address of all Biquad Filters can be found in Register Maps: 表 8-6.

### 8.5.2.6 Checksum

This device supports two different check sum schemes, a cyclic redundancy check (CRC) checksum and an Exclusive (XOR) checksum. Register reads do not change checksum, but writes to even nonexistent registers will change the checksum. Both checksums are 8-bit checksums and both are available together simultaneously. The checksums can be reset by writing a starting value (eg. 0x 00 00 00 00) to their respective 4-byte register locations.

#### 8.5.2.6.1 Cyclic Redundancy Check (CRC) Checksum

The 8-bit CRC checksum used is the 0x7 polynomial (CRC-8-CCITT I.432.1; ATM HEC, ISDN HEC and cell delineation,  $(1 + x^1 + x^2 + x^8)$ ). A major advantage of the CRC checksum is that it is input order sensitive. The CRC supports all I<sup>2</sup>C transactions, excluding book and page switching. The CRC checksum is read from register 0x7E on page0 of Book 0x8C (Book\_140, Page\_0, Reg\_126). The CRC checksum can be reset by writing 0x00 to the same register locations where the CRC checksum is valid.

#### 8.5.2.6.2 Exclusive or (XOR) Checksum

The XOR checksum is a simpler checksum scheme. It performs sequential XOR of each register byte write with the previous 8-bit checksum register value. XOR supports only Book 0x8C, and excludes page switching and all registers in Page 0x00 of Book 0x8C. XOR checksum is read from location register 0x7D on page 0x00 of book 0x8C (B\_140, Page\_0, Reg\_125). The XOR Checksum can be reset by writing 0x00 to the same register location where it is read.

PurePath™ Console tools supports CRC and XOR check sum value calculation based on register writing scripps.

#### Note

List both CRC and XOR application scenarios in below example, but only one Checksum (CRC or XOR) method is needed.

Example: Update EQ parameters.

1. Use PPC3 to calculate the EQ parametes and save to .cfg file.

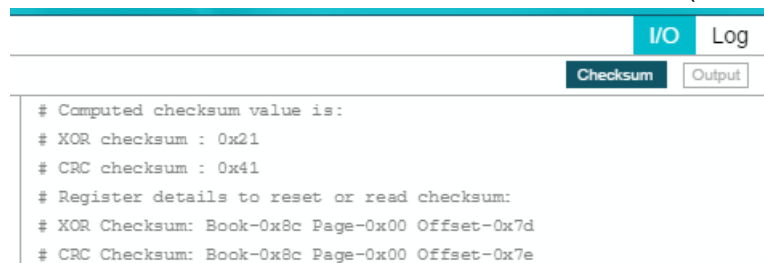
```
w 58 00 00
```

```
w 58 7f aa
```

```
w 58 00 24
```

```
w 58 18 08 25 39 ce f0 bc db 13 07 26 4d 48 0f 43 24 ed f8 b4 78 ea #EQ parameters
```

2. Use PPC3 to calculate CRC and XOR Checksum results (based on .cfg file).



```

I/O Log
Checksum Output
# Computed checksum value is:
# XOR checksum : 0x21
# CRC checksum : 0x41
# Register details to reset or read checksum:
# XOR Checksum: Book-0x8c Page-0x00 Offset-0x7d
# CRC Checksum: Book-0x8c Page-0x00 Offset-0x7e
  
```

3. Update EQ parameters with CRC/XOR Checksum.

w 58 00 00

w 58 7f 8c

w 58 00 00

w 58 7e 00 #Reset CRC start value to 0x00

w 58 7d 00 #Reset XOR start value to 0x00

w 58 00 00

w 58 7f aa

w 58 00 24

w 58 18 08 25 39 ce f0 bc db 13 07 26 4d 48 0f 43 24 ed f8 b4 78 ea #EQ parameters update

w 58 00 00

w 58 7f 8c

w 58 00 00

r 58 7d 01 #Check if the XOR checksum readback data is 0x21

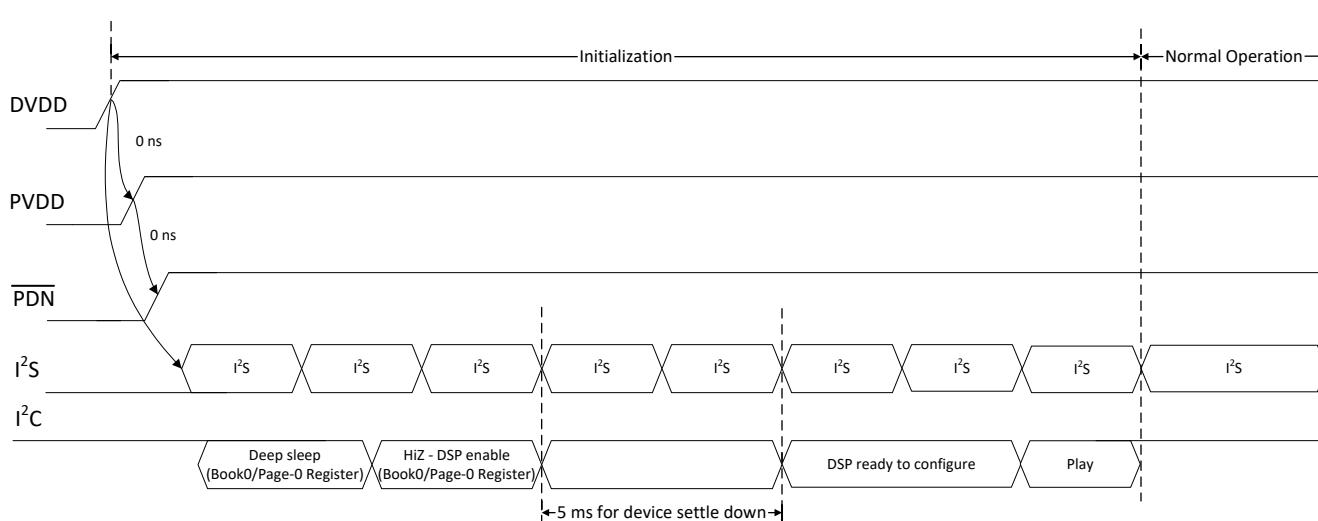
r 58 7e 01 #Check if the CRC checksum readback data is 0x41

### 8.5.3 Control via Software

- Startup Procedures
- Shutdown Procedures

#### 8.5.3.1 Startup Procedures

1. Configure ADR pin with proper setting for I<sup>2</sup>C device address.
2. Bring up power supplies (it does not matter if PVDD or DVDD comes up first).
3. Once power supplies are stable, bring up  $\overline{\text{PDN}}$  to High, then start SCLK, LRCLK.
4. Once I<sup>2</sup>S clock are stable, set the device into Hi-Z state and enable DSP via the I<sup>2</sup>C control port.
5. Wait 5ms at least. Then initialize the DSP Coefficient, then set the device to Play state
6. The device is now in normal operation.



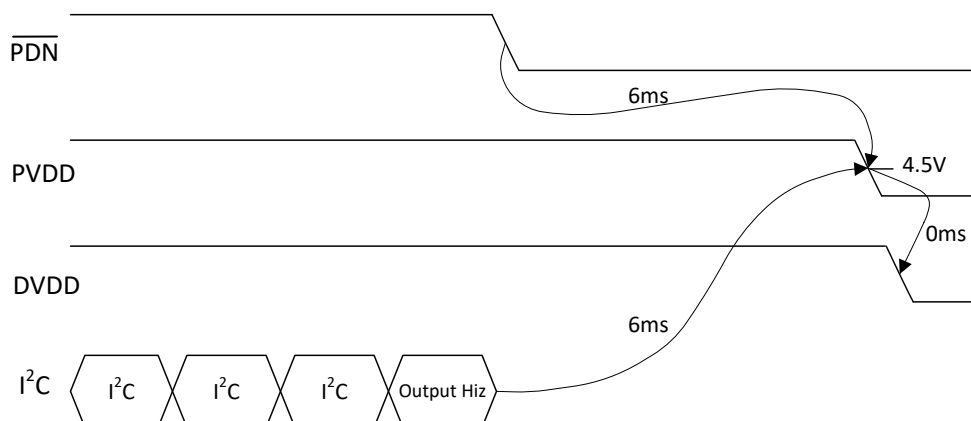
**Notes:**

- 1) I<sup>2</sup>S only permits to start after DVDD fully powered up. But No sequence requirement with  $\overline{\text{PDN}}$ .
- 2) I<sup>2</sup>C only response with  $\overline{\text{PDN}}$  brought up to HIGH.
- 3) If I<sup>2</sup>C register is general register in Book 0, no sequence requirement, write/read BEFORE or AFTER I<sup>2</sup>S clock ready. But if I<sup>2</sup>C register is DSP register (Other BOOK/PAGE), suggest to follow the 5ms requirements and make sure I<sup>2</sup>S clock is ready (Especially for the first time initialization after power up).
- 4) No sequence requirement for PVDD and DVDD.

#### 8-15. Start-up Sequence

### 8.5.3.2 Shutdown Procedures

1. The device is in normal operation.
2. Configure the Register 0x03h -D[1:0]=10 (Hi-Z) via the I<sup>2</sup>C control port or Pull  $\overline{\text{PDN}}$  low.
3. Wait at least 6ms (this time depends on the LRCLK rate ,digital volume and digital volume ramp down rate).
4. Bring down power supplies.
5. The device is now fully shutdown and powered off.



- Before PVDD/DVDD power down, Class D Output driver needs to be disabled by  $\overline{\text{PDN}}$  or by I<sup>2</sup>C.
- At least 6ms delay needed based on LRCLK (Fs) = 48kHz, Digital volume ramp down update every sample period, decreased by 0.5dB for each update, digital volume = 24dB. Change the value of register 0x4C and 0x4E or change the LRCLK rate, the delay changes.

**8-16. Power-Down Sequence**

### 8.5.3.3 Protection and Monitoring

#### 8.5.3.3.1 Overcurrent Limit (Cycle-By-Cycle)

The CBC current-limiting circuit terminates each PWM pulse limit the output current flow to the average current limit ( $I_{LIM}$ ) threshold. The overall effect on the audio in the case of a current overload is quite similar a voltage-clipping event, temporarily limiting power at the peaks of the music signal and normal operation continues without disruption on removal of the overload.

---

#### Note

CBC (Cycle-By-Cycle) current-limiting only allows in BTL mode, not allowed under PBTL.

---

#### 8.5.3.3.2 Overcurrent Shutdown (OCSD)

Under severe short-circuit event, such as a short to PVDD or ground, the device uses a peak-current detector, and the affected channel shuts down in  $< 100$  ns if the peak current are enough. The shutdown speed depends on a number of factors, such as the impedance of the short circuit, supply voltage, and switching frequency. The user may restart the affected channel via I<sup>2</sup>C. An OCSD event activates the fault pin, and the I<sup>2</sup>C fault register saves a record. If the supply or ground short is strong enough to exceed the peak current threshold but not severe enough to trigger the OSCD, the peak current limiter prevents excess current from damaging the output FETs, and operation returns to normal after the short is removed.

#### 8.5.3.3.3 DC Detect

If the DRV5825P device measures a DC offset in the output voltage, the FAULTZ line is pulled low and the OUTxx outputs transition to high impedance, signifying a fault.

## 8.6 Register Maps

### 8.6.1 CONTROL PORT Registers

表 8-6 lists the memory-mapped registers for the CONTROL PORT. All register offset addresses not listed in 表 8-6 should be considered as reserved locations and the register contents should not be modified.

表 8-6. CONTROL PORT Registers

Offset	Acronym	Register Name	Section
1h	RESET_CTRL	Register 1	<a href="#">セクション 8.6.1.2</a>
2h	DEVICE_CTRL_1	Register 2	<a href="#">セクション 8.6.1.3</a>
3h	DEVICE_CTRL2	Register 3	<a href="#">セクション 8.6.1.4</a>
Fh	I2C_PAGE_AUTO_INC	Register 15	<a href="#">セクション 8.6.1.5</a>
28h	SIG_CH_CTRL	Register 40	<a href="#">セクション 8.6.1.6</a>
29h	CLOCK_DET_CTRL	Register 41	<a href="#">セクション 8.6.1.7</a>
30h	SDOUT_SEL	Register 48	<a href="#">セクション 8.6.1.8</a>
31h	I2S_CTRL	Register 49	<a href="#">セクション 8.6.1.9</a>
33h	SAP_CTRL1	Register 51	<a href="#">セクション 8.6.1.10</a>
34h	SAP_CTRL2	Register 52	<a href="#">セクション 8.6.1.11</a>
35h	SAP_CTRL3	Register 53	<a href="#">セクション 8.6.1.12</a>
37h	FS_MON	Register 55	<a href="#">セクション 8.6.1.13</a>
38h	BCK (SCLK)_MON	Register 56	<a href="#">セクション 8.6.1.14</a>
39h	CLKDET_STATUS	Register 57	<a href="#">セクション 8.6.1.15</a>
40h	DSP_PGM_MODE	Register 64	<a href="#">セクション 8.6.1.16</a>
46h	DSP_CTRL	Register 70	<a href="#">セクション 8.6.1.17</a>
4Ch	DIG_VOL	Register 76	<a href="#">セクション 8.6.1.18</a>
4Eh	DIG_VOL_CTRL1	Register 78	<a href="#">セクション 8.6.1.19</a>
4Fh	DIG_VOL_CTRL2	Register 79	<a href="#">セクション 8.6.1.20</a>
50h	AUTO_MUTE_CTRL	Register 80	<a href="#">セクション 8.6.1.21</a>
51h	AUTO_MUTE_TIME	Register 81	<a href="#">セクション 8.6.1.22</a>
53h	ANA_CTRL	Register 83	<a href="#">セクション 8.6.1.23</a>
54h	AGAIN	Register 84	<a href="#">セクション 8.6.1.24</a>
55h	SPI_CLK	Register 85	<a href="#">セクション 8.6.1.25</a>
56h	EEPROM_CTRL0	Register 86	<a href="#">セクション 8.6.1.26</a>
57h	EEPROM_RD_CMD	Register 87	<a href="#">セクション 8.6.1.27</a>
58h	EEPROM_ADDR_START0	Register 88	<a href="#">セクション 8.6.1.28</a>
59h	EEPROM_ADDR_START1	Register 89	<a href="#">セクション 8.6.1.29</a>
5Ah	EEPROM_ADDR_START2	Register 90	<a href="#">セクション 8.6.1.30</a>
5Bh	EEPROM_BOOT_STATUS	Register 91	<a href="#">セクション 8.6.1.31</a>
5Ch	BQ_WR_CTRL1	Register 92	<a href="#">セクション 8.6.1.32</a>
5Eh	PVDD_ADC	Register 94	<a href="#">セクション 8.6.1.33</a>
60h	GPIO_CTRL	Register 96	<a href="#">セクション 8.6.1.34</a>
61h	GPIO0_SEL	Register 97	<a href="#">セクション 8.6.1.35</a>
62h	GPIO1_SEL	Register 98	<a href="#">セクション 8.6.1.36</a>
63h	GPIO2_SEL	Register 99	<a href="#">セクション 8.6.1.37</a>
64h	GPIO_INPUT_SEL	Register 100	<a href="#">セクション 8.6.1.38</a>
65h	GPIO_OUT	Register 101	<a href="#">セクション 8.6.1.39</a>
66h	GPIO_OUT_INV	Register 102	<a href="#">セクション 8.6.1.40</a>
67h	DIE_ID	Register 103	<a href="#">セクション 8.6.1.41</a>

**表 8-6. CONTROL PORT Registers (continued)**

Offset	Acronym	Register Name	Section
68h	POWER_STATE	Register 104	<a href="#">セクション 8.6.1.42</a>
69h	AUTOMUTE_STATE	Register 105	<a href="#">セクション 8.6.1.43</a>
6Ah	PHASE_CTRL	Register 106	<a href="#">セクション 8.6.1.44</a>
6Bh	SS_CTRL0	Register 107	<a href="#">セクション 8.6.1.45</a>
6Ch	SS_CTRL1	Register 108	<a href="#">セクション 8.6.1.46</a>
6Dh	SS_CTRL2	Register 109	<a href="#">セクション 8.6.1.47</a>
6Eh	SS_CTRL3	Register 110	<a href="#">セクション 8.6.1.48</a>
6Fh	SS_CTRL4	Register 111	<a href="#">セクション 8.6.1.49</a>
70h	CHAN_FAULT	Register 112	<a href="#">セクション 8.6.1.50</a>
71h	GLOBAL_FAULT1	Register 113	<a href="#">セクション 8.6.1.51</a>
72h	GLOBAL_FAULT2	Register 114	<a href="#">セクション 8.6.1.52</a>
73h	WARNING	Register 115	<a href="#">セクション 8.6.1.53</a>
74h	PIN_CONTROL1	Register 116	<a href="#">セクション 8.6.1.54</a>
75h	PIN_CONTROL2	Register 117	<a href="#">セクション 8.6.1.55</a>
76h	MISC_CONTROL	Register 118	<a href="#">セクション 8.6.1.56</a>
77h	CBC_CONTROL	Register 119	<a href="#">セクション 8.6.1.57</a>
78h	FAULT_CLEAR	Register 120	<a href="#">セクション 8.6.1.58</a>

Complex bit access types are encoded to fit into small table cells. [表 8-7](#) shows the codes that are used for access types in this section.

**表 8-7. CONTROL PORT Access Type Codes**

Access Type	Code	Description
Read Type		
R	R	Read
Write Type		
W	W	Write
Reset or Default Value		
-n		Value after reset or the default value

### 8.6.1.1 RESET\_CTRL Register (Offset = 1h) [reset = 0x00]

RESET\_CTRL is shown in [图 8-13](#) and described in [表 8-8](#).

Return to [表 8-6](#).

**图 8-13. RESET\_CTRL Register**

7	6	5	4	3	2	1	0
RESERVED			RST_MOD	RESERVED			RST_REG
R/W			W	R			W

**表 8-8. RESET\_CTRL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	000	This bit is reserved
4	RST_DIG_CORE	W	0	WRITE CLEAR BIT Reset DIG_CORE WRITE CLEAR BIT Reset Full Digital Core. This bit resets the Full Digital Signal Path (Include DSP coefficient RAM and I2C Control Port Registers), Since the DSP is also reset, the coefficient RAM content will also be cleared by the DSP. 0: Normal 1: Reset Full Digital Signal Path
3-1	RESERVED	R	000	This bit is reserved
0	RST_REG	W	0	WRITE CLEAR BIT Reset Registers This bit resets the mode registers back to their initial values. Only reset Control Port Registers, The RAM content is not cleared. 0: Normal 1: Reset I <sup>2</sup> C Control Port Registers

### 8.6.1.2 DEVICE\_CTRL\_1 Register (Offset = 2h) [reset = 0x00]

DEVICE\_CTRL\_1 is shown in 图 8-14 and described in 表 8-9.

Return to 表 8-6.

图 8-14. DEVICE\_CTRL\_1 Register

7	6	5	4	3	2	1	0
RESERVED	FSW_SEL			RESERVED	DAMP_PBTl	DAMP_MOD	
R/W	R/W			R/W	R/W	R/W	

表 8-9. DEVICE\_CTRL\_1 Register Field Descriptions

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	This bit is reserved
6-4	FSW_SEL	R/W	000	SELECT F <sub>SW</sub> 000:384kHz 100:768kHz (Adaptive I/V Limiter co-operate with 768kHz F <sub>SW</sub> ) Others:Reserved
3	RESERVED	R/W	0	This bit is reserved
2	DAMP_PBTl	R/W	0	0: SET DAMP TO BTL MODE 1:SET DAMP TO PBTl MODE
1-0	RESERVED	R/W	00	This bit is reserved

### 8.6.1.3 DEVICE\_CTRL2 Register (Offset = 3h) [reset = 00x10]

DEVICE\_CTRL2 is shown in [图 8-15](#) and described in [表 8-10](#).

Return to [表 8-6](#).

**图 8-15. DEVICE\_CTRL2 Register**

7	6	5	4	3	2	1	0
RESERVED			DIS_DSP	MUTE_LEFT	RESERVED	CTRL_STATE	
R/W			R/W	R/W	R/W	R/W	

**表 8-10. DEVICE\_CTRL2 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	000	This bit is reserved
4	DIS_DSP	R/W	1	DSP reset When the bit is made 0, DSP will start powering up and send out data. This needs to be made 0 only after all the input clocks are settled so that DMA channels do not go out of sync. 0: Normal operation 1: Reset the DSP
3	MUTE	R/W	0	Mute both Left and Right Channel This bit issues soft mute request for both left and right channel. The volume will be smoothly ramped down/up to avoid pop/click noise. 0: Normal volume 1: Mute
2	RESERVED	R/W	0	This bit is reserved
1-0	CTRL_STATE	R/W	00	device state control register 00: Deep Sleep 01: Sleep 10: Hiz, 11: PLAY

#### 8.6.1.4 I2C\_PAGE\_AUTO\_INC Register (Offset = Fh) [reset = 0x00]

I2C\_PAGE\_AUTO\_INC is shown in [图 8-16](#) and described in [表 8-11](#).

Return to [表 8-6](#).

**图 8-16. I2C\_PAGE\_AUTO\_INC Register**

7	6	5	4	3	2	1	0
RESERVED				PAGE_AUTOINC_REG	RESERVED		
R/W				R/W	R/W		

**表 8-11. I2C\_PAGE\_AUTO\_INC Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	This bit is reserved
3	PAGE_AUTOINC_REG	R/W	0	Page auto increment disable Disable page auto increment mode. for non -zero books. When end of page is reached it goes back to 8th address location of next page when this bit is 0. When this bit is 1 it goes to 0 th location of current page itself like in older part. 0: Enable Page auto increment 1: Disable Page auto increment
2-0	RESERVED	R/W	000	This bit is reserved

### 8.6.1.5 SIG\_CH\_CTRL Register (Offset = 28h) [reset = 0x00]

SIG\_CH\_CTRL is shown in [图 8-17](#) and described in [表 8-12](#).

Return to [表 8-6](#).

**图 8-17. SIG\_CH\_CTRL Register**

7	6	5	4	3	2	1	0
SCLK_RATIO_CONFIGURE				FSMODE	RESERVED		
R/W				R/W	R/W		

**表 8-12. SIG\_CH\_CTRL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-4	SCLK_RATIO_CONFIGURE	R/W	0000	These bits indicate the configured SCLK ratio, the number of SCLK clocks in one audio frame. Device will set this ratio automatically. 4'b0011:32FS 4'b0101:64FS 4'b0111:128FS 4'b1001:256FS 4'b1011:512FS
3	FSMODE	R/W	0	FS Speed Mode These bits select the FS operation mode, which must be set according to the current audio sampling rate. Need set it manually If the input Fs is 44.1kHz/88.2kHz/176.4kHz. 4'b0000 Auto detection 4'b0100 Reserved 4'b0110 32KHz 4'b1000 44.1KHz 4'b1001 48KHz 4'b1010 88.2KHz 4'b1011 96KHz 4'b1100 176.4KHz 4'b1101 192KHz Others Reserved
2-0	RESERVED	R/W	000	This bit is reserved

### 8.6.1.6 CLOCK\_DET\_CTRL Register (Offset = 29h) [reset = 0x00]

CLOCK\_DET\_CTRL is shown in [图 8-18](#) and described in [表 8-13](#).

Return to [表 8-6](#).

**图 8-18. CLOCK\_DET\_CTRL Register**

7	6	5	4	3	2	1	0
RESERVED	DIS_DET_PLL	DIS_DET_SCLK_RANGE	DIS_DET_FS	DIS_DET_SCLK	DIS_DET_MISS	RESERVED	RESERVED
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

**表 8-13. CLOCK\_DET\_CTRL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	This bit is reserved
6	DIS_DET_PLL	R/W	0	Ignore PLL overrate Detection This bit controls whether to ignore the PLL overrate detection. The PLL must be slow than 150MHz or an error will be reported. When ignored, a PLL overrate error will not cause a clock error. 0: Regard PLL overrate detection 1: Ignore PLL overrate detection
5	DIS_DET_SCLK_RANGE	R/W	0	Ignore BCK Range Detection This bit controls whether to ignore the SCLK range detection. The SCLK must be stable between 256KHz and 50MHz or an error will be reported. When ignored, a SCLK range error will not cause a clock error. 0: Regard BCK Range detection 1: Ignore BCK Range detection
4	DIS_DET_FS	R/W	0	Ignore FS Error Detection This bit controls whether to ignore the FS Error detection. When ignored, FS error will not cause a clock error. But CLKDET_STATUS will report fs error. 0: Regard FS detection 1: Ignore FS detection
3	DIS_DET_SCLK	R/W	0	Ignore SCLK Detection This bit controls whether to ignore the SCLK detection against LRCK. The SCLK must be stable between 32FS and 512FS inclusive or an error will be reported. When ignored, a SCLK error will not cause a clock error. 0: Regard SCLK detection 1: Ignore SCLK detection
2	DIS_DET_MISS	R/W	0	Ignore SCLK Missing Detection This bit controls whether to ignore the SCLK missing detection. When ignored an SCLK missing will not cause a clock error. 0: Regard SCLK missing detection 1: Ignore SCLKmissing detection
1	RESERVED	R/W	0	This bit is reserved
0	RESERVED	R/W	0	This bit is reserved

### 8.6.1.7 SDOUT\_SEL Register (Offset = 30h) [reset = 0x00]

SDOUT\_SEL is shown in [图 8-20](#) and described in [表 8-14](#).

Return to [表 8-6](#).

**图 8-19. SDOUT\_SEL Register**

7	6	5	4	3	2	1	0
RESERVED					RESERVED		SDOUT_SEL
R/W					R/W		R/W

**表 8-14. SDOUT\_SEL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-1	RESERVED	R/W	0000000	These bits are reserved
0	SDOUT_SEL	R/W	0	SDOUT Select. This bit selects what is being output as SDOUT pin. 0: SDOUT is the DSP output (post-processing) 1: SDOUT is the DSP input (pre-processing)

### 8.6.1.8 I2S\_CTRL Register (Offset = 31h) [reset = 0x00]

I2S\_CTRL is shown in [图 8-20](#) and described in [表 8-15](#).

Return to [表 8-6](#).

**图 8-20. I2S\_CTRL Register**

7	6	5	4	3	2	1	0
RESERVED		SCLK_INV	RESERVED	RESERVED	RESERVED		RESERVED
R/W		R/W	R/W	R	R		R/W

**表 8-15. I2S\_CTRL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-6	RESERVED	R/W	00	This bit is reserved
5	SCLK_INV	R/W	0	SCLK Polarity This bit sets the inverted SCLK mode. In inverted SCLK mode, the DAC assumes that the LRCK and DIN edges are aligned to the rising edge of the SCLK. Normally they are assumed to be aligned to the falling edge of the SCLK. 0: Normal SCLK mode 1: Inverted SCLK mode
4	RESERVED	R/W	0	This bit is reserved
3	RESERVED	R	0	This bit is reserved
2-1	RESERVED	R	00	These bits are reserved
0	RESERVED	R/W	0	This bit is reserved

### 8.6.1.9 SAP\_CTRL1 Register (Offset = 33h) [reset = 0x02]

SAP\_CTRL1 is shown in [图 8-21](#) and described in [表 8-16](#).

Return to [表 8-6](#).

**图 8-21. SAP\_CTRL1 Register**

7	6	5	4	3	2	1	0
I2S_SHIFT_MSB	RESERVED	DATA_FORMAT		I2S_LRCLK_PULSE		WORD_LENGTH	
R/W	R/W	R/W		R/W		R/W	

**表 8-16. SAP\_CTRL1 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7	I2S_SHIFT_MSB	R/W	0	I2S Shift MSB
6	RESERVED	R/W	0	This bit is reserved
5-4	DATA_FORMAT	R/W	00	I2S Data Format These bits control both input and output audio interface formats for DAC operation. 00: I2S 01: TDM/DSP 10: RTJ 11: LTJ
3-2	I2S_LRCLK_PULSE	R/W	00	01: LRCLK pulse < 8 SCLK
1-0	WORD_LENGTH	R/W	10	I2S Word Length These bits control both input and output audio interface sample word lengths for DAC operation. 00: 16 bits 01: 20 bits 10: 24 bits 11: 32 bits

### 8.6.1.10 SAP\_CTRL2 Register (Offset = 34h) [reset = 0x00]

SAP\_CTRL2 is shown in [図 8-22](#) and described in [表 8-17](#).

Return to [表 8-6](#).

**図 8-22. SAP\_CTRL2 Register**

7	6	5	4	3	2	1	0
I2S_SHIFT							
R/W							

**表 8-17. SAP\_CTRL2 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-0	I2S_SHIFT	R/W	00000000	<p>I2S Shift LSB</p> <p>These bits control the offset of audio data in the audio frame for both input and output. The offset is defined as the number of SCLK from the starting (MSB) of audio frame to the starting of the desired audio sample. MSB [8] locates in <a href="#">セクション 8.6.1.10</a></p> <p>00000000: offset = 0 SCLK (no offset)</p> <p>00000001: offset = 1 SCLK</p> <p>00000010: offset = 2 SCLKs</p> <p>and</p> <p>11111111: offset = 512 SCLKs</p>

### 8.6.1.11 SAP\_CTRL3 Register (Offset = 35h) [reset = 0x11]

SAP\_CTRL3 is shown in [图 8-23](#) and described in [表 8-18](#).

Return to [表 8-6](#).

**图 8-23. SAP\_CTRL3 Register**

7	6	5	4	3	2	1	0
RESERVED		LEFT_DAC_DPATH		RESERVED		RIGHT_DAC_DPATH	
R/W		R/W		R/W		R/W	

**表 8-18. SAP\_CTRL3 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-6	RESERVED	R/W	00	These bits are reserved
5-4	LEFT_DAC_DPATH	R/W	01	Left DAC Data Path. These bits control the left channel audio data path connection. 00: Zero data (mute) 01: Left channel data 10: Right channel data 11: Reserved (do not set)
3-2	RESERVED	R/W	00	These bits are reserved
1-0	RIGHT_DAC_DPATH	R/W	01	Right DAC Data Path. These bits control the right channel audio data path connection. 00: Zero data (mute) 01: Right channel data 10: Left channel data 11: Reserved (do not set)

### 8.6.1.12 FS\_MON Register (Offset = 37h) [reset = 0x00]

FS\_MON is shown in [图 8-24](#) and described in [表 8-19](#).

Return to [表 8-6](#).

**图 8-24. FS\_MON Register**

7	6	5	4	3	2	1	0
RESERVED		SCLK_RATIO_HIGH		FS			
R/W		R		R			

**表 8-19. FS\_MON Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-6	RESERVED	R/W	00	This bit is reserved
5-4	SCLK_RATIO_HIGH	R	00	2 msbs of detected SCLK ratio
3-0	FS	R	0000	These bits indicate the currently detected audio sampling rate. 4 'b0000 FS Error 4 'b0100 16KHz 4 'b0110 32KHz 4 'b1000 Reserved 4 'b1001 48KHz 4 'b1011 96KHz 4 'b1101 192KHz Others Reserved

### 8.6.1.13 BCK (SCLK)\_MON Register (Offset = 38h) [reset = 0x00]

BCK\_MON is shown in [图 8-25](#) and described in [表 8-20](#).

Return to [表 8-6](#).

**图 8-25. BCK (SCLK)\_MON Register**

7	6	5	4	3	2	1	0
BCLK (SCLK)_RATIO_LOW							
R							

**表 8-20. BCK\_MON Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-0	BCLK (SCLK)_RATIO_LOW	R	00000000	These bits indicate the currently detected BCK (SCLK) ratio, the number of BCK (SCLK) clocks in one audio frame. BCK (SCLK) = 32 FS~512 FS

#### 8.6.1.14 CLKDET\_STATUS Register (Offset = 39h) [reset = 0x00]

CLKDET\_STATUS is shown in [图 8-26](#) and described in [表 8-21](#).

Return to [表 8-6](#).

**图 8-26. CLKDET\_STATUS Register**

7	6	5	4	3	2	1	0
RESERVED			DET_STATUS				
R/W			R				

**表 8-21. CLKDET\_STATUS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-6	RESERVED	R/W	00	These bits are reserved
5-0	DET_STATUS	R	000000	<p>bit0: In auto detection mode(reg_fsmode=0),this bit indicated whether the audio sampling rate is valid or not. In non auto detection mode(reg_fsmode!=0), Fs error indicates that configured fs is different with detected fs. Even FS Error Detection Ignore is set, this flag will be also asserted.</p> <p>bit1: This bit indicates whether the SCLK is valid or not. The SCLK ratio must be stable and in the range of 32-512FS to be valid.</p> <p>bit2: This bit indicates whether the SCLK is missing or not.</p> <p>bit3: This bit indicates whether the PLL is locked or not. The PLL will be reported as unlocked when it is disabled.</p> <p>bits4: This bit indicates whether the PLL is overrate</p> <p>bits5: This bit indicates whether the SCLK is overrate or underrate</p>

### 8.6.1.15 DSP\_PGM\_MODE Register (Offset = 40h) [reset = 0x01]

DSP\_PGM\_MODE is shown in [图 8-27](#) and described in [表 8-22](#).

Return to [表 8-6](#).

**图 8-27. DSP\_PGM\_MODE Register**

7	6	5	4	3	2	1	0
RESERVED				CH_A_HIZ	CH_B_HIZ	MODE_SEL	
R/W				R/W	R/W	R/W	

**表 8-22. DSP\_PGM\_MODE Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	These bits are reserved
3	CH_A_HIZ	R/W	0	1: Force Channel A (L channel) to Hiz mode. 0: Exit Force Hi-Z mode, Channel A is now controlled by Register 0x03, see <a href="#">表 8-10</a> . Notes: If channel has been forced to Hiz, only method to exit Force Hi-Z mode is set this bit to 0. This function is disabled in PBTL mode.
2	CH_B_HIZ	R/W	0	1: Force Channel B (R channel) to Hiz mode. 0: Exit Force Hi-Z mode, Channel B is now controlled by Register 0x03, see <a href="#">表 8-10</a> . Notes: If channel has been forced to Hiz, only method to exit Force Hi-Z mode is set this bit to 0. This function is disabled in PBTL mode.
1-0	MODE_SEL	R/W	01	DSP Program Selection These bits select the DSP program to use for audio processing. 00 => ram mode 01 => rom mode 1 10 => rom mode 2 11 => rom mode 3

### 8.6.1.16 DSP\_CTRL Register (Offset = 46h) [reset = 0x01]

DSP\_CTRL is shown in [Figure 8-28](#) and described in [Table 8-23](#).

Return to [Table 8-6](#).

**Figure 8-28. DSP\_CTRL Register**

7	6	5	4	3	2	1	0
RESERVED			USER_DEFINED_PROCESSING_RATE		RESERVED	BOOT_FROM_I RAM	USE_DEFAULT_COEFFS
R/W			R/W		R	R/W	R/W

**Table 8-23. DSP\_CTRL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	000	This bit is reserved
4-3	USER_DEFINED_PROCESSING_RATE	R/W	00	00:input 01:48k 10:96k 11:192k
2	RESERVED	R	0	This bit is reserved
1	RESERVED	R	0	This bit is reserved
0	USE_DEFAULT_COEFFS	R/W	1	Use default coefficients from ZROM this bit controls whether to use default coefficients from ZROM or use the non-default coefficients downloaded to device by the Host 0 : don't use default coefficients from ZROM 1 : use default coefficients from ZROM

### 8.6.1.17 DIG\_VOL Register (Offset = 4Ch) [reset = 30h]

DIG\_VOL is shown in [图 8-29](#) and described in [表 8-24](#).

Return to [表 8-6](#).

**图 8-29. DIG\_VOL Register**

7	6	5	4	3	2	1	0
PGA_LEFT							
R/W							

**表 8-24. DIG\_VOL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-0	PGA	R/W	00110000	Digital Volume These bits control both left and right channel digital volume. The digital volume is 24 dB to -103 dB in -0.5 dB step. 00000000: +24.0 dB 00000001: +23.5 dB ..... and 00101111: +0.5 dB 00110000: 0.0 dB 00110001: -0.5 dB ..... 11111110: -103 dB 11111111: Mute

#### 8.6.1.18 DIG\_VOL\_CTRL1 Register (Offset = 4Eh) [reset = 0x33]

DIG\_VOL\_CTRL1 is shown in [图 8-30](#) and described in [表 8-25](#).

Return to [表 8-6](#).

**图 8-30. DIG\_VOL\_CTRL1 Register**

7	6	5	4	3	2	1	0
PGA_RAMP_DOWN_SPEED		PGA_RAMP_DOWN_STEP		PGA_RAMP_UP_SPEED		PGA_RAMP_UP_STEP	
R/W		R/W		R/W		R/W	

**表 8-25. DIG\_VOL\_CTRL1 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-6	PGA_RAMP_DOWN_SPEED	R/W	00	Digital Volume Normal Ramp Down Frequency These bits control the frequency of the digital volume updates when the volume is ramping down. 00: Update every 1 FS period 01: Update every 2 FS periods 10: Update every 4 FS periods 11: Directly set the volume to zero (Instant mute)
5-4	PGA_RAMP_DOWN_STEP	R/W	11	Digital Volume Normal Ramp Down Step These bits control the step of the digital volume updates when the volume is ramping down. 00: Decrement by 4 dB for each update 01: Decrement by 2 dB for each update 10: Decrement by 1 dB for each update 11: Decrement by 0.5 dB for each update
3-2	PGA_RAMP_UP_SPEED	R/W	00	Digital Volume Normal Ramp Up Frequency These bits control the frequency of the digital volume updates when the volume is ramping up. 00: Update every 1 FS period 01: Update every 2 FS periods 10: Update every 4 FS periods 11: Directly restore the volume (Instant unmute)
1-0	PGA_RAMP_UP_STEP	R/W	11	Digital Volume Normal Ramp Up Step These bits control the step of the digital volume updates when the volume is ramping up. 00: Increment by 4 dB for each update 01: Increment by 2 dB for each update 10: Increment by 1 dB for each update 11: Increment by 0.5 dB for each update

### 8.6.1.19 DIG\_VOL\_CTRL2 Register (Offset = 4Fh) [reset = 0x30]

DIG\_VOL\_CTRL2 is shown in [图 8-31](#) and described in [表 8-26](#).

Return to [表 8-6](#).

**图 8-31. DIG\_VOL\_CTRL2 Register**

7	6	5	4	3	2	1	0
FAST_RAMP_DOWN_SPEED		FAST_RAMP_DOWN_STEP		RESERVED			
R/W		R/W		R/W			

**表 8-26. DIG\_VOL\_CTRL2 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-6	FAST_RAMP_DOWN_SPEED	R/W	00	Digital Volume Emergency Ramp Down Frequency These bits control the frequency of the digital volume updates when the volume is ramping down due to clock error or power outage, which usually needs faster ramp down compared to normal soft mute. 00: Update every 1 FS period 01: Update every 2 FS periods 10: Update every 4 FS periods 11: Directly set the volume to zero (Instant mute)
5-4	FAST_RAMP_DOWN_STEP	R/W	11	Digital Volume Emergency Ramp Down Step These bits control the step of the digital volume updates when the volume is ramping down due to clock error or power outage, which usually needs faster ramp down compared to normal soft mute. 00: Decrement by 4 dB for each update 01: Decrement by 2 dB for each update 10: Decrement by 1 dB for each update 11: Decrement by 0.5 dB for each update
3-0	RESERVED	R/W	0000	This bit is reserved

### 8.6.1.20 AUTO\_MUTE\_CTRL Register (Offset = 50h) [reset = 0x07]

AUTO\_MUTE\_CTRL is shown in [图 8-32](#) and described in [表 8-27](#).

Return to [表 8-6](#).

**图 8-32. AUTO\_MUTE\_CTRL Register**

7	6	5	4	3	2	1	0
RESERVED					REG_AUTO_MUTE_CTRL		
R/W					R/W		

**表 8-27. AUTO\_MUTE\_CTRL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-3	RESERVED	R/W	00000	This bit is reserved
2-0	REG_AUTO_MUTE_CTRL	R/W	111	bit0: 0: Disable left channel auto mute 1: Enable left channel auto mute bit1: 0: Disable right channel auto mute 1: Enable right channel auto mute bit2: 0: Auto mute left channel and right channel independently. 1: Auto mute left and right channels only when both channels are about to be auto muted.

### 8.6.1.21 AUTO\_MUTE\_TIME Register (Offset = 51h) [reset = 0x00]

AUTO\_MUTE\_TIME is shown in [图 8-33](#) and described in [表 8-28](#).

Return to [表 8-6](#).

**图 8-33. AUTO\_MUTE\_TIME Register**

7	6	5	4	3	2	1	0
RESERVED	AUTOMUTE_TIME_LEFT			RESERVED	AUTOMUTE_TIME_RIGHT		
R/W	R/W			R/W	R/W		

**表 8-28. AUTO\_MUTE\_TIME Register Field Descriptions**

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	This bit is reserved
6-4	AUTOMUTE_TIME_LEFT	R/W	000	Auto Mute Time for Left Channel These bits specify the length of consecutive zero samples at left channel before the channel can be auto muted. The times shown are for 96 kHz sampling rate and will scale with other rates. 000: 11.5 ms 001: 53 ms 010: 106.5 ms 011: 266.5 ms 100: 0.535 sec 101: 1.065 sec 110: 2.665 sec 111: 5.33 sec
3	RESERVED	R/W	0	This bit is reserved
2-0	AUTOMUTE_TIME_RIGHT	R/W	000	Auto Mute Time for Right Channel These bits specify the length of consecutive zero samples at right channel before the channel can be auto muted. The times shown are for 96 kHz sampling rate and will scale with other rates. 000: 11.5 ms 001: 53 ms 010: 106.5 ms 011: 266.5 ms 100: 0.535 sec 101: 1.065 sec 110: 2.665 sec 111: 5.33 sec

### 8.6.1.22 ANA\_CTRL Register (Offset = 53h) [reset = 0h]

ANA\_CTRL is shown in [图 8-34](#) and described in [表 8-29](#)

Return to [表 8-6](#)

**图 8-34. ANA\_CTRL Register**

7	6	5	4	3	2	1	0
AMUTE_DLY							
R/W							

**表 8-29. ANA\_CTRL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	This bit is reserved
6-5	Class D bandwidth control	R/W	00	00: 100kHz 01: 80kHz 10: 120kHz 11: 175kHz With Fsw=768kHz, 175kHz bandwidth should be selected for high audio performance.
4-1	RESERVED	R/W	0000	These bits are reserved
0	L and R PWM output phase control	R/W	0	0: out of phase 1: in phase

### 8.6.1.23 AGAIN Register (Offset = 54h) [reset = 0x00]

AGAIN is shown in [图 8-35](#) and described in [表 8-30](#).

Return to [表 8-6](#).

**图 8-35. AGAIN Register**

7	6	5	4	3	2	1	0
RESERVED				ANA_GAIN			
R/W				R/W			

**表 8-30. AGAIN Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-5	RESERVED	R/W	000	This bit is reserved
4-0	ANA_GAIN	R/W	00000	Analog Gain Control This bit controls the analog gain. 00000: 0 dB (29.5V peak voltage) 00001:-0.5db 11111: -15.5 dB

### 8.6.1.24 SPI\_CLK Register (Offset = 55h) [reset = 0x00]

SPI\_CLK is shown in [图 8-36](#) and described in [表 8-31](#).

Return to [表 8-6](#).

**图 8-36. SPI\_CLK Register**

7	6	5	4	3	2	1	0
RESERVED				SPI_CLK_SEL			
R/W				R/W			

**表 8-31. SPI\_CLK Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	This bit is reserved
3-0	SPI_CLK_SEL	R/W	0000	00:1.25M 01:2.5M 10:5M 11:10M

### 8.6.1.25 EEPROM\_CTRL0 Register (Offset = 56h) [reset = 0x00]

EEPROM\_CTRL0 is shown in [图 8-37](#) and described in [表 8-32](#).

Return to [表 8-6](#).

**图 8-37. EEPROM\_CTRL0 Register**

7	6	5	4	3	2	1	0
RESERVED		EEPROM_ADDR_24BITS_ENABLE	SPI_CLK_RATE		SPI_INV_POLAR	SPI_MST_LSB	LOAD_EEPROM_START
R/W		R/W	R/W		R/W	R/W	R/W

**表 8-32. EEPROM\_CTRL0 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-6	RESERVED	R/W	00	This bit is reserved
5	EEPROM_ADDR_24BITS_ENABLE	R/W	0	enable 24 bits mode for EEPROM address
4-3	SPI_CLK_RATE	R/W	00	0: spi clock rate = 1.25MHz 1: spi clock rate = 2.5MHz 2: spi clock rate = 5MHz 3: spi clock rate = 10MHz
2	SPI_INV_POLAR	R/W	0	0: spi serial data change at post edge SCK 1: spi serial data change at neg edge SCK
1	SPI_MST_LSB	R/W	0	0: msb first 1: lsb first
0	LOAD_EEPROM_START	R/W	0	0: dsp coefficients read from host 1: dsp coefficients read from EEPROM

### 8.6.1.26 EEPROM\_RD\_CMD Register (Offset = 57h) [reset = 0x03]

EEPROM\_RD\_CMD is shown in [图 8-38](#) and described in [表 8-33](#).

Return to [表 8-6](#).

**图 8-38. EEPROM\_RD\_CMD Register**

7	6	5	4	3	2	1	0
EEPROM_RD_CMD							
R/W-0000011							

**表 8-33. EEPROM\_RD\_CMD Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-0	EEPROM_RD_CMD	R/W	0000011	EEPROM read command

#### 8.6.1.27 EEPROM\_ADDR\_START0 Register (Offset = 58h) [reset = 0x00]

EEPROM\_ADDR\_START0 is shown in [图 8-39](#) and described in [表 8-34](#).

Return to [表 8-6](#).

**图 8-39. EEPROM\_ADDR\_START0 Register**

7	6	5	4	3	2	1	0
EEPROM_ADDR_START_HIGH							
R/W							

**表 8-34. EEPROM\_ADDR\_START0 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-0	EEPROM_ADDR_START_HIGH	R/W	00000000	8 msb of EEPROM read starting address for coefficient

#### 8.6.1.28 EEPROM\_ADDR\_START1 Register (Offset = 59h) [reset = 0x00]

EEPROM\_ADDR\_START1 is shown in [图 8-40](#) and described in [表 8-35](#).

Return to [表 8-6](#).

**图 8-40. EEPROM\_ADDR\_START1 Register**

7	6	5	4	3	2	1	0
EEPROM_ADDR_START_MIDDLE							
R/W							

**表 8-35. EEPROM\_ADDR\_START1 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-0	EEPROM_ADDR_START_MIDDLE	R/W	00000000	8 middle of EEPROM read starting address for coefficients

#### 8.6.1.29 EEPROM\_ADDR\_START2 Register (Offset = 5Ah) [reset = 0h]

EEPROM\_ADDR\_START2 is shown in [图 8-41](#) and described in [表 8-36](#).

Return to [表 8-6](#).

**图 8-41. EEPROM\_ADDR\_START2 Register**

7	6	5	4	3	2	1	0
EEPROM_ADDR_START_LOW							
R/W							

**表 8-36. EEPROM\_ADDR\_START2 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-0	EEPROM_ADDR_START_LOW	R/W	00000000	8 lsb of EEPROM read starting address for coefficients

### 8.6.1.30 EEPROM\_BOOT\_STATUS Register (Offset = 5Bh) [reset = 0x00]

EEPROM\_BOOT\_STATUS is shown in [图 8-42](#) and described in [表 8-37](#).

Return to [表 8-6](#).

**图 8-42. EEPROM\_BOOT\_STATUS Register**

7	6	5	4	3	2	1	0
RESERVED						LOAD_EEPROM_CRC_ERROR	LOAD_EEPROM_DONE
R						R	R

**表 8-37. EEPROM\_BOOT\_STATUS Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-2	RESERVED	R	000000	This bit is reserved
1	LOAD_EEPROM_CRC_ERROR	R	0	0: CRC pass for EEPROM boot load 1: CRC don't pass for EEPROM boot load.
0	LOAD_EEPROM_DONE	R	0	Indicate that the EEPROM boot load has been finished.

### 8.6.1.31 BQ\_WR\_CTRL1 Register (Offset = 5Ch) [reset = 0x000]

BQ\_WR\_CTRL1 is shown in [图 8-43](#) and described in [表 8-38](#).

Return to [表 8-6](#).

**图 8-43. BQ\_WR\_CTRL1 Register**

7	6	5	4	3	2	1	0
RESERVED						BQ_WR_FIRST_COEF	
R/W						R/W	

**表 8-38. BQ\_WR\_CTRL1 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-1	RESERVED	R/W	0000000	This bit is reserved
0	BQ_WR_FIRST_COEF	R/W	0	Indicate the first coefficient of a BQ is starting to write.

### 8.6.1.32 PVDD\_ADC Register (Offset = 5Eh) [reset = 0h]

PVDD\_ADC is shown in [图 8-44](#) and described in [表 8-39](#).

Return to [表 8-6](#).

**图 8-44. PVDD\_ADC Register**

7	6	5	4	3	2	1	0
ADC_DATA_OUT							
R							

**表 8-39. PVDD\_ADC Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-0	PVDD_ADC[7:0]	R	00000000	PVDD Voltage = PVDD_ADC[7:0] / 8.428 (V) 223: 26.45V 222: 26.34V 221: 26.22V ... 39: 4.63V 38: 4.51V 37: 4.39V

### 8.6.1.33 GPIO\_CTRL Register (Offset = 60h) [reset = 0x00]

GPIO\_CTRL is shown in [图 8-45](#) and described in [表 8-40](#).

Return to [表 8-6](#).

**图 8-45. GPIO\_CTRL Register**

7	6	5	4	3	2	1	0
RESERVED					GPIO2_OE	GPIO1_OE	GPIO0_OE
R/W					R/W	R/W	R/W

**表 8-40. GPIO\_CTRL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-3	RESERVED	R/W	0000	This bit is reserved
2	GPIO2_OE	R/W	0	GPIO2 Output Enable. This bit sets the direction of the GPIO2 pin 0: GPIO2 is input 1: GPIO2 is output
1	GPIO1_OE	R/W	0	GPIO1 Output Enable This bit sets the direction of the GPIO1 pin 0: GPIO1 is input 1: GPIO1 is output
0	GPIO0_OE	R/W	0	GPIO0 Output Enable This bit sets the direction of the GPIO0 pin 0: GPIO0 is input 1: GPIO0 is output

### 8.6.1.34 GPIO0\_SEL Register (Offset = 61h) [reset = 0x00]

GPIO0\_SEL is shown in [図 8-46](#) and described in [表 8-41](#).

Return to [表 8-6](#).

**図 8-46. GPIO0\_SEL Register**

7	6	5	4	3	2	1	0
RESERVED				GPIO0_SEL			
R/W				R/W			

**表 8-41. GPIO0\_SEL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	This bit is reserved
3-0	GPIO0_SEL	R/W	0000	0000: off (low) 0001: Reserved 0010: GPIO output value programmed by User in <a href="#">セクション 8.6.1.39</a> 0011: Auto mute flag (asserted when both L and R channels are auto muted) 0100: Auto mute flag for left channel 0101: Auto mute flag for right channel 0110: Clock invalid flag (clock error or clock missing) 0111: Reserved 1000: GPIO0 as WARNZ output 1001: Serial audio interface data output (SDOUT) 1011: GPIO0 as FAULTZ output 1100: GPIO0 as SPI CLK 1101: GPIO0 as SPI_MOSI 1110: Reserved 1111: Reserved

### 8.6.1.35 GPIO1\_SEL Register (Offset = 62h) [reset = 0x00]

GPIO1\_SEL is shown in [図 8-47](#) and described in [表 8-42](#).

Return to [表 8-6](#).

**図 8-47. GPIO1\_SEL Register**

7	6	5	4	3	2	1	0
RESERVED				GPIO1_SEL			
R/W				R/W			

**表 8-42. GPIO1\_SEL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	This bit is reserved
3-0	GPIO1_SEL	R/W	0000	0000: off (low) 0001: Reserved 0010: GPIO output value programmed by User in <a href="#">セクション 8.6.1.39</a> 0011: Auto mute flag (asserted when both L and R channels are auto muted) 0100: Auto mute flag for left channel 0101: Auto mute flag for right channel 0110: Clock invalid flag (clock error or clock missing) 0111: Reserved 1000: GPIO1 as WARNZ output 1001: Serial audio interface data output (SDOUT) 1011: GPIO1 as FAULTZ output 1100: GPIO1 as SPI CLK 1101: GPIO1 as SPI_MOSI 1110: Reserved 1111: Reserved

### 8.6.1.36 GPIO2\_SEL Register (Offset = 63h) [reset = 0x00]

GPIO2\_SEL is shown in [図 8-48](#) and described in [表 8-43](#).

Return to [表 8-6](#).

**図 8-48. GPIO2\_SEL Register**

7	6	5	4	3	2	1	0
RESERVED				GPIO2_SEL			
R/W				R/W			

**表 8-43. GPIO2\_SEL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	This bit is reserved
3-0	GPIO2_SEL	R/W	0000	0000: off (low) 0001: Reserved 0010: GPIO output value programmed by User in <a href="#">セクション 8.6.1.39</a> 0011: Auto mute flag (asserted when both L and R channels are auto muted) 0100: Auto mute flag for left channel 0101: Auto mute flag for right channel 0110: Clock invalid flag (clock error or clock missing) 0111: Reserved 1000: GPIO2 as WARNZ output 1001: Serial audio interface data output (SDOUT) 1011: GPIO2 as FAULTZ output 1100: GPIO2 as SPI CLK 1101: GPIO2 as SPI_MOSI 1110: Reserved 1111: Reserved

### 8.6.1.37 GPIO\_INPUT\_SEL Register (Offset = 64h) [reset = 0x00]

GPIO\_INPUT\_SEL is shown in [图 8-49](#) and described in [表 8-44](#).

Return to [表 8-6](#).

**图 8-49. GPIO\_INPUT\_SEL Register**

7	6	5	4	3	2	1	0
GPIO_SPI_MISO_SEL		GPIO_PHASE_SYNC_SEL		GPIO_RESETZ_SEL		GPIO_MUTEZ_SEL	
R/W		R/W		R/W		R/W	

**表 8-44. GPIO\_INPUT\_SEL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-6	GPIO_SPI_MISO_SEL	R/W	00	00: N/A 01: GPIO0 10: GPIO1 11: GPIO2
5-4	GPIO_PHASE_SYNC_SEL	R/W	00	00: N/A 01: GPIO0 10: GPIO1 11: GPIO2
3-2	GPIO_RESETZ_SEL	R/W	00	00: N/A 01: GPIO0 10: GPIO1 11: GPIO2 can not be reset by GPIO reset
1-0	GPIO_MUTEZ_SEL	R/W	00	00: N/A 01: GPIO0 10: GPIO1 11: GPIO2 MUTEZ pin active-low, output driver will set to HiZ state, Class D amplifier's output stop switching.

### 8.6.1.38 GPIO\_OUT Register (Offset = 65h) [reset = 0x00]

GPIO\_OUT is shown in [图 8-50](#) and described in [表 8-45](#).

Return to [表 8-6](#).

**图 8-50. GPIO\_OUT Register**

7	6	5	4	3	2	1	0
RESERVED					GPIO_OUT		
R/W					R/W		

**表 8-45. GPIO\_OUT Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-3	RESERVED	R/W	00000	This bit is reserved
2-0	GPIO_OUT	R/W	000	bit0: GPIO0 output bit1: GPIO1 output bit2: GPIO2 output

### 8.6.1.39 GPIO\_OUT\_INV Register (Offset = 66h) [reset = 0x00]

GPIO\_OUT\_INV is shown in [图 8-51](#) and described in [表 8-46](#).

Return to [表 8-6](#).

**图 8-51. GPIO\_OUT\_INV Register**

7	6	5	4	3	2	1	0
RESERVED					GPIO_OUT		
R/W					R/W		

**表 8-46. GPIO\_OUT\_INV Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-3	RESERVED	R/W	00000	This bit is reserved
2-0	GPIO_OUT	R/W	000	bit0: GPIO0 output invert bit1: GPIO1 output invert bit2: GPIO2 output invert

### 8.6.1.40 DIE\_ID Register (Offset = 67h) [reset = 95h]

DIE\_ID is shown in [图 8-52](#) and described in [表 8-47](#).

Return to [表 8-6](#).

**图 8-52. DIE\_ID Register**

7	6	5	4	3	2	1	0
DIE_ID							
R							

**表 8-47. DIE\_ID Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-0	DIE_ID	R	10010101	DIE ID

#### 8.6.1.41 POWER\_STATE Register (Offset = 68h) [reset = 0x00]

POWER\_STATE is shown in [图 8-53](#) and described in [表 8-48](#).

Return to [表 8-6](#).

**图 8-53. POWER\_STATE Register**

7	6	5	4	3	2	1	0
STATE_RPT							
R							

**表 8-48. POWER\_STATE Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-0	STATE_RPT	R	00000000	0: Deep sleep 1: Seep 2: HIZ 3: Play Others: reserved

### 8.6.1.42 AUTOMUTE\_STATE Register (Offset = 69h) [reset = 0x00]

AUTOMUTE\_STATE is shown in [图 8-54](#) and described in [表 8-49](#).

Return to [表 8-6](#).

**图 8-54. AUTOMUTE\_STATE Register**

7	6	5	4	3	2	1	0
RESERVED						ZERO_RIGHT_MON	ZERO_LEFT_MON
R						R	R

**表 8-49. AUTOMUTE\_STATE Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-2	RESERVED	R	000000	This bit is reserved
1	ZERO_RIGHT_MON	R	0	This bit indicates the auto mute status for right channel. 0: Not auto muted 1: Auto muted
0	ZERO_LEFT_MON	R	0	This bit indicates the auto mute status for left channel. 0: Not auto muted 1: Auto muted

### 8.6.1.43 PHASE\_CTRL Register (Offset = 6Ah) [reset = 0]

PHASE\_CTRL is shown in [图 8-55](#) and described in [表 8-50](#).

Return to [表 8-6](#).

**图 8-55. PHASE\_CTRL Register**

7	6	5	4	3	2	1	0
RESERVED				RAMP_PHASE_SEL		PHASE_SYNC_SEL	PHASE_SYNC_EN
R/W				R/W		R/W	R/W

**表 8-50. PHASE\_CTRL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-4	RESERVED	R/W	0000	This bit is reserved
3-2	RAMP_PHASE_SEL	R/W	00	select ramp clock phase when multi devices integrated in one system to reduce EMI and peak supply peak current, it is recommended set all devices the same RAMP frequency and same spread spectrum. it must be set before driving device into PLAY mode if this feature is needed. 2'b00: phase 0 2'b01: phase 1 2'b10: phase 2 2'b11: phase 3 all of above have a 45 degree of phase shift
1	PHASE_SYNC_SEL	R/W	0	ramp phase sync sel, 0: is gpio sync; 1: intenal sync
0	PHASE_SYNC_EN	R/W	0	ramp phase sync enable

#### 8.6.1.44 RAMP\_SS\_CTRL0 Register (Offset = 6Bh) [reset = 0x00]

RAMP\_SS\_CTRL0 is shown in [图 8-56](#) and described in [表 8-51](#).

Return to [表 8-6](#).

**图 8-56. SS\_CTRL0 Register**

7	6	5	4	3	2	1	0
RESERVED	RESERVED	SS_PRE_DIV_SEL	SS_MANUAL_MODE	RESERVED	RESERVED	SS_RDM_EN	SS_TRI_EN
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

**表 8-51. RAMP\_SS\_CTRL0 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	This bit is reserved
6	RESERVED	R/W	0	This bit is reserved
5	SS_PRE_DIV_SEL	R/W	0	Select pll clock divide 2 as source clock in manual mode
4	SS_MANUAL_MODE	R/W	0	Set ramp ss controller to manual mode
3-2	RESERVED	R/W	00	This bit is reserved
1	SS_RDM_EN	R/W	0	Random SS enable
0	SS_TRI_EN	R/W	0	Triangle SS enable

#### 8.6.1.45 SS\_CTRL1 Register (Offset = 6Ch) [reset = 0x00]

SS\_CTRL1 is shown in [图 8-57](#) and described in [表 8-52](#).

Return to [表 8-6](#).

**图 8-57. SS\_CTRL1 Register**

7	6	5	4	3	2	1	0
RESERVED	SS_RDM_CTRL	SS_TRI_CTRL	SS_TRI_CTRL	SS_TRI_CTRL	SS_TRI_CTRL	SS_TRI_CTRL	SS_TRI_CTRL
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

**表 8-52. SS\_CTRL1 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	This bit is reserved
6-4	SS_RDM_CTRL	R/W	000	Add Dither
3-0	SS_TRI_CTRL	R/W	0000	Triangle SS frequency and range control

### 8.6.1.46 SS\_CTRL2 Register (Offset = 6Dh) [reset = 0xA0]

SS\_CTRL2 is shown in [图 8-58](#) and described in [表 8-53](#).

Return to [表 8-6](#).

**图 8-58. SS\_CTRL2 Register**

7	6	5	4	3	2	1	0
TM_FREQ_CTRL							
R/W							

**表 8-53. SS\_CTRL2 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-0	TM_FREQ_CTRL	R/W	10100000	Control ramp frequency in manual mode, F=61440000/N

### 8.6.1.47 SS\_CTRL3 Register (Offset = 6Eh) [reset = 0x11]

SS\_CTRL3 is shown in [图 8-59](#) and described in [表 8-54](#).

Return to [表 8-6](#).

**图 8-59. SS\_CTRL3 Register**

7	6	5	4	3	2	1	0
TM_DSTEP_CTRL				TM_USTEP_CTRL			
R/W				R/W			

**表 8-54. SS\_CTRL3 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-4	SS_TM_DSTEP_CTRL	R/W	0001	Control triangle mode spread spectrum fall step in ramp ss manual mode
3-0	SS_TM_USTEP_CTRL	R/W	0001	Control triangle mode spread spectrum rise step in ramp ss manual mode

### 8.6.1.48 SS\_CTRL4 Register (Offset = 6Fh) [reset = 0x24]

SS\_CTRL4 is shown in [图 8-60](#) and described in [表 8-55](#).

Return to [表 8-6](#).

**图 8-60. SS\_CTRL4 Register**

7	6	5	4	3	2	1	0
RESERVED	TM_AMP_CTRL		SS_TM_PERIOD_BOUNDARY				
R/W	R/W		R/W				

**表 8-55. SS\_CTRL4 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7	RESERVED	R/W	0	This bit is reserved
6-5	TM_AMP_CTRL	R/W	01	Control ramp amp ctrl in ramp ss manual model
4-0	SS_TM_PERIOD_BOUNDARY	R/W	00100	Control triangle mode spread spectrum boundary in ramp ss manual mode

### 8.6.1.49 CHAN\_FAULT Register (Offset = 70h) [reset = 0x00]

CHAN\_FAULT is shown in [図 8-61](#) and described in [表 8-56](#).

Return to [表 8-6](#).

**図 8-61. CHAN\_FAULT Register**

7	6	5	4	3	2	1	0
RESERVED				CH1_DC_1	CH2_DC_1	CH1_OC_I	CH2_OC_I
R				R	R	R	R

**表 8-56. CHAN\_FAULT Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-4	RESERVED	R	0000	This bit is reserved
3	CH1_DC_1	R	0	Left channel DC fault. Once there is a DC fault, this bit will set to be 1. Class D output will set to Hi-Z. Report by FAULT pin (GPIO). Clear this fault by setting bit 7 of <a href="#">セクション 8.6.1.58</a> to 1 or this bit keeps 1.
2	CH2_DC_1	R	0	Right channel DC fault. Once there is a DC fault, this bit will set to be 1. Class D output will set to Hi-Z. Report by FAULT pin (GPIO). Clear this fault by setting bit 7 of <a href="#">セクション 8.6.1.58</a> to 1 or this bit keeps 1.
1	CH1_OC_I	R	0	Left channel over current fault. Once there is a OC fault, this bit will set to be 1. Class D output will set to Hi-Z. Report by FAULT pin (GPIO). Clear this fault by setting bit 7 of <a href="#">セクション 8.6.1.58</a> to 1 or this bit keeps 1.
0	CH2_OC_I	R	0	Right channel over current fault. Once there is a OC fault, this bit will set to be 1. Class D output will set to Hi-Z. Report by FAULT pin (GPIO). Clear this fault by setting bit 7 of <a href="#">セクション 8.6.1.58</a> to 1 or this bit keeps 1.

### 8.6.1.50 GLOBAL\_FAULT1 Register (Offset = 71h) [reset = 0h]

GLOBAL\_FAULT1 is shown in [図 8-62](#) and described in [表 8-57](#).

Return to [表 8-6](#).

**図 8-62. GLOBAL\_FAULT1 Register**

7	6	5	4	3	2	1	0
OTP_CRC_ERROR	BQ_WR_ERROR	LOAD_EEPROM_ERROR	RESERVED	RESERVED	CLK_FAULT_I	PVDD_OV_I	PVDD_UV_I
R	R	R	R	R	R	R	R

**表 8-57. GLOBAL\_FAULT1 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7	OTP_CRC_ERROR	R	0	Indicate OTP CRC check error.
6	BQ_WR_ERROR	R	0	The recent BQ is written failed
5	LOAD_EEPROM_ERROR	R	0	0: EEPROM boot load was done successfully 1: EEPROM boot load was done unsuccessfully
4	RESERVED	R	0	This bit is reserved
3	RESERVED	R	0	This bit is reserved
2	CLK_FAULT_I	R	0	Clock fault. Once there is a Clock fault, this bit will set to be 1. Class D output will set to Hi-Z. Report by FAULT pin (GPIO). Clock fault works with an auto-recovery mode, once the clock error removes, device automatically returns to the previous state. Clear this fault by setting bit 7 of <a href="#">セクション 8.6.1.58</a> to 1 or this bit keeps 1.
1	PVDD_OV_I	R	0	PVDD OV fault. Once there is a OV fault, this bit will set to be 1. Class D output will set to Hi-Z. Report by FAULT pin (GPIO). OV fault works with an auto-recovery mode, once the OV error removes, device automatically returns to the previous state. Clear this fault by setting bit 7 of <a href="#">セクション 8.6.1.58</a> to 1 or this bit keeps 1.
0	PVDD_UV_I	R	0	PVDD UV fault. Once there is a UV fault, this bit will set to be 1. Class D output will set to Hi-Z. Report by FAULT pin (GPIO). OV fault works with an auto-recovery mode, once the OV error removes, device automatically returns to the previous state. Clear this fault by setting bit 7 of <a href="#">セクション 8.6.1.58</a> to 1 or this bit keeps 1.

### 8.6.1.51 GLOBAL\_FAULT2 Register (Offset = 72h) [reset = 0h]

GLOBAL\_FAULT2 is shown in [図 8-63](#) and described in [表 8-58](#).

Return to [表 8-6](#).

**図 8-63. GLOBAL\_FAULT2 Register**

7	6	5	4	3	2	1	0
RESERVED					CBC_FAULT_C H2_I	CBC_FAULT_C H1_I	OTSD_I
R					R	R	R

**表 8-58. GLOBAL\_FAULT2 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-3	RESERVED	R	0000	This bit is reserved
2	CBC_FAULT_CH2_I	R	0	Right channel cycle by cycle over current fault
1	CBC_FAULT_CH1_I	R	0	Left channel cycle by cycle over current fault
0	OTSD_I	R	0	Over temperature shut down fault. Once there is a OT fault, this bit will set to be 1. Class D output will set to Hi-Z. Report by FAULT pin (GPIO). OV fault works with an auto-recovery mode, once the OV error removes, device automatically returns to the previous state. Clear this fault by setting bit 7 of <a href="#">セクション 8.6.1.58</a> to 1 or this bit keeps 1.

### 8.6.1.52 WARNING Register (Offset = 73h) [reset = 0x00]

WARNING is shown in [図 8-64](#) and described in [表 8-59](#).

Return to [表 8-6](#).

**図 8-64. WARNING Register**

7	6	5	4	3	2	1	0
RESERVED		CBCW_CH1_I	CBCW_CH2_I	OTW_LEVEL4_I	OTW_LEVEL3_I	OTW_LEVEL2_I	OTW_LEVEL1_I
R		R	R	R	R	R	R

**表 8-59. WARNING Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-6	RESERVED	R	0	This bit is reserved
5	CBCW_CH1_I	R	0	Left channel cycle by cycle over current warning
4	CBCW_CH2_I	R	0	Right channel cycle by cycle over current warning
3	OTW_LEVEL4_I	R	0	Over temperature warning leve4, 146C
2	OTW_LEVEL3_I	R	0	Over temperature warning leve3, 134C
1	OTW_LEVEL2_I	R	0	Over temperature warning leve2, 122C
0	OTW_LEVEL1_I	R	0	Over temperature warning leve1, 112C

### 8.6.1.53 PIN\_CONTROL1 Register (Offset = 74h) [reset = 0x00]

PIN\_CONTROL1 is shown in [图 8-65](#) and described in [表 8-60](#).

Return to [表 8-6](#).

**图 8-65. PIN\_CONTROL1 Register**

7	6	5	4	3	2	1	0
MASK_OTSD	MASK_DVDD_UV	MASK_DVDD_OV	MASK_CLK_FAULT	RESERVED	MASK_PVDD_UV	MASK_DC	MASK_OC
R/W	R/W	R/W	R/W	R	R/W	R/W	R/W

**表 8-60. PIN\_CONTROL1 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7	MASK_OTSD	R/W	0	Mask OTSD fault report
6	MASK_DVDD_UV	R/W	0	Mask DVDD UV fault report
5	MASK_DVDD_OV	R/W	0	Mask DVDD OV fault report
4	MASK_CLK_FAULT	R/W	0	Mask clock fault report
3	RESERVED	R	0	This bit is reserved
2	MASK_PVDD_UV	R/W	0	Mask PVDD UV fault report mask PVDD OV fault report
1	MASK_DC	R/W	0	Mask DC fault report
0	MASK_OC	R/W	0	Mask OC fault report

### 8.6.1.54 PIN\_CONTROL2 Register (Offset = 75h) [reset = 0xF8]

PIN\_CONTROL2 is shown in [图 8-66](#) and described in [表 8-61](#).

Return to [表 8-6](#).

**图 8-66. PIN\_CONTROL2 Register**

7	6	5	4	3	2	1	0
CBC_FAULT_LATCH_EN	CBC_WARN_LATCH_EN	CLKFLT_LATCH_EN	OTSD_LATCH_EN	OTW_LATCH_EN	MASK_OTW	MASK_CBCW	MASK_CBC_FAULT
R/W	R/W	R/W	R/W	R/W	R/W	R/W	R/W

**表 8-61. PIN\_CONTROL2 Register Field Descriptions**

Bit	Field	Type	Reset	Description
7	CBC_FAULT_LATCH_EN	R/W	1	Enable CBC fault latch by setting this bit to 1
6	CBC_WARN_LATCH_EN	R/W	1	Enable CBC warning latch by setting this bit to 1
5	CLKFLT_LATCH_EN	R/W	1	Enable clock fault latch by setting this bit to 1
4	OTSD_LATCH_EN	R/W	1	Enable OTSD fault latch by setting this bit to 1
3	OTW_LATCH_EN	R/W	1	Enable OT warning latch by setting this bit to 1
2	MASK_OTW	R/W	0	Mask OT warning report by setting this bit to 1
1	MASK_CBCW	R/W	0	Mask CBC warning report by setting this bit to 1
0	MASK_CBC_FAULT	R/W	0	Mask CBC fault report by setting this bit to 1

### 8.6.1.55 MISC\_CONTROL Register (Offset = 76h) [reset = 0x00]

MISC\_CONTROL is shown in [图 8-67](#) and described in [表 8-62](#).

Return to [表 8-6](#).

**图 8-67. MISC\_CONTROL Register**

7	6	5	4	3	2	1	0
DET_STATUS_LATCH	RESERVED		OTSD_AUTO_REC_EN	RESERVED			
R/W	R/W		R/W	R/W			

**表 8-62. MISC\_CONTROL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7	DET_STATUS_LATCH	R/W	0	1:Latch clock detection status 0:Don't latch clock detection status
6-5	RESERVED	R/W	00	These bits are reserved
4	OTSD_AUTO_REC_EN	R/W	0	OTSD auto recovery enable
3-0	RESERVED	R/W	0000	This bit is reserved

### 8.6.1.56 CBC\_CONTROL Register (Offset = 77h) [reset = 0x00]

CBC\_CONTROL is shown in [图 8-68](#) and described in [表 8-63](#).

Return to [表 8-6](#).

**图 8-68. CBC\_CONTROL Register**

7	6	5	4	3	2	1	0
RESERVED					CBC_EN	CBC_WARN_EN	CBC_FAULT_EN
R/W					R/W	R/W	R/W

**表 8-63. CBC\_CONTROL Register Field Descriptions**

Bit	Field	Type	Reset	Description
7-3	RESERVED	R/W	00000	These bits are reserved
2	CBC_EN	R/W	0	Enable CBC function
1	CBC_WARN_EN	R/W	0	Enable CBC warning
0	CBC_FAULT_EN	R/W	0	Enable CBC fault

### 8.6.1.57 FAULT\_CLEAR Register (Offset = 78h) [reset = 0x00]

FAULT\_CLEAR is shown in [图 8-69](#) and described in [表 8-64](#).

Return to [表 8-6](#).

**图 8-69. FAULT\_CLEAR Register**

7	6	5	4	3	2	1	0
ANALOG_FAULT_CLEAR	RESERVED						
W	R/W						

**表 8-64. FAULT\_CLEAR Register Field Descriptions**

Bit	Field	Type	Reset	Description
7	ANALOG_FAULT_CLEAR	W	0	WRITE CLEAR BIT once write this bit to 1, device will clear analog fault
6-0	RESERVED	R/W	0000000	This bit is reserved

## 9 Application and Implementation

### Note

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

### 9.1 Application Information

This section details the information required to configure the device for several popular configurations and provides guidance on integrating the DRV5825P device into the larger system.

#### 9.1.1 LC Filter Design For Piezo Speaker Driving

Compared with traditional coil speaker whose output SPL is regarded to be proportional to output power, piezo vendor suggests to use voltage on piezo to indicate output SPL. So piezo speaker drive circuit and algorithm design try to deliver high dynamic range for output voltage and avoid amplifier's over current protection based on the impedance of external circuit. It requires the algorithm understand the external circuit modeling.

##### 9.1.1.1 LC Filter Recommendation

LC filter selection recommendation principles show as below::

1. Make sure  $f_{\text{Resonance}} > 25 \text{ kHz}$  for over current avoidance and peaking voltage protection. The Max inductance of Inductor is limited by the  $f_{\text{Resonance}} > 25 \text{ kHz}$ .  $f_{\text{Resonance}} = 1/(2 \times \pi \times (L \times (C + 2 \times C_{\text{piezo}})))^{0.5}$
2. Larger inductor means larger DCR (better stability) and smaller startup/ripple current.
3. Larger inductor, smaller  $f_{\text{Resonance}}$ , more loop gain margin, better stability.
4. Some corner consideration:
  - Inductor variation and DCR variation. Suggest to keep within +/-10% make sure  $f_{\text{Resonance}} > 25 \text{ kHz}$ .
  - Make sure DCR of inductor larger than 25 mΩ.
  - Piezo speaker capacitance variation. Also make sure  $f_{\text{Resonance}} > 25 \text{ kHz}$ .

**表 9-1. LC Filter recommendation**

Piezo Speaker Capacitance	Fsw (Switching Frequency)	Class D Loop Bandwidth (kHz)	LC Filter Recommendation	Resonance Frequency
0.6 μF	768kHz	175kHz	8.2 μH (DCR ≥ 25 mΩ) +0.47 μF	43.4 kHz
			10 μH (DCR ≥ 25 mΩ) + 0.68 μF	36.9 kHz
			15 μH (DCR ≥ 25 mΩ) + 0.47 μF	32 kHz
			22 μH (DCR ≥ 25 mΩ) + 0.4 7μF	26.4 kHz
1 μF			8.2 μH (DCR ≥ 25 mΩ) +0.47 μF	35.1 kHz
			10 μH (DCR ≥ 25 mΩ) + 0.68 μF	30.5 kHz
			15 μH (DCR ≥ 25 mΩ) + 0.47 μF	26 kHz
2 μF			4.7 μH (DCR ≥ 25 mΩ) +0.47 μF	34.7 kHz
			8.2 μH (DCR ≥ 25 mΩ) +0.47 μF	26.3 kHz
4.5 μF				

#### 9.1.2 Bootstrap Capacitors

The output stage of the DRV5825P uses a high-side NMOS driver, rather than a PMOS driver. To generate the gate driver voltage for the high-side NMOS, a bootstrap capacitor for each output terminal acts as a floating power supply for the switching cycle. Use 0.47-μF capacitors to connect the appropriate output pin (OUT\_X) to the bootstrap pin (BST\_X). For example, connect a 0.47-μF capacitor between OUT\_A and BST\_A for bootstrapping the A channel. Similarly, connect another 0.47-μF capacitor between the OUT\_B and BST\_B pins for the B channel inverting output.

### 9.1.3 Power Supply Decoupling

To ensure high efficiency, low THD, and high PSRR, proper power supply decoupling is necessary. Noise transients on the power supply lines are short duration voltage spikes. These spikes can contain frequency components that extend into the hundreds of megahertz. The power supply input must be decoupled with some good quality, low ESL, Low ESR capacitors larger than 22  $\mu\text{F}$ . These capacitors bypasses low frequency noise to the ground plane. For high frequency decoupling, place 1- $\mu\text{F}$  or 0.1- $\mu\text{F}$  capacitors as close as possible to the PVDD pins of the device.

An idea power supply can deliver infinite amounts of current without a reduction in its output voltage. In reality, a power supply maximum current output depends on its series impedance. In practical audio applications, where the decoupling techniques are limited by cost and size, audio frequencies are mostly driven by the supply itself and not by decoupling/bulk capacitors. The time constant associated with audio frequencies (especially the mid and high areas) would require a large amount of capacitance which may be deemed impractical for most application. Play high audio frequency with a piezo speaker with high current, the supply voltage drop with larger bulk capacitors should much smaller than smaller bulk capacitors.

### 9.1.4 Output EMI Filtering

The DRV5825P device is often used with a low-pass filter, which is used to filter out the carrier frequency of the PWM modulated output. This filter is frequently referred to as the L-C Filter, due to the presence of an inductive element L and a capacitive element C to make up the 2-pole filter.

The L-C filter removes the carrier frequency, reducing electromagnetic emissions and smoothing the current waveform which is drawn from the power supply. The presence and size of the L-C filter is determined by several system level constraints. In some low-power use cases that have no other circuits which are sensitive to EMI, a simple ferrite bead or a ferrite bead plus a capacitor can replace the tradition large inductor and capacitor that are commonly used. In other high-power applications, large toroid inductors are required for maximum power and film capacitors can be used due to audio characteristics. Refer to the application report Class-D LC Filter Design ([SLOA119](#)) for a detailed description on the proper component selection and design of an L-C filter based upon the desired load and response.

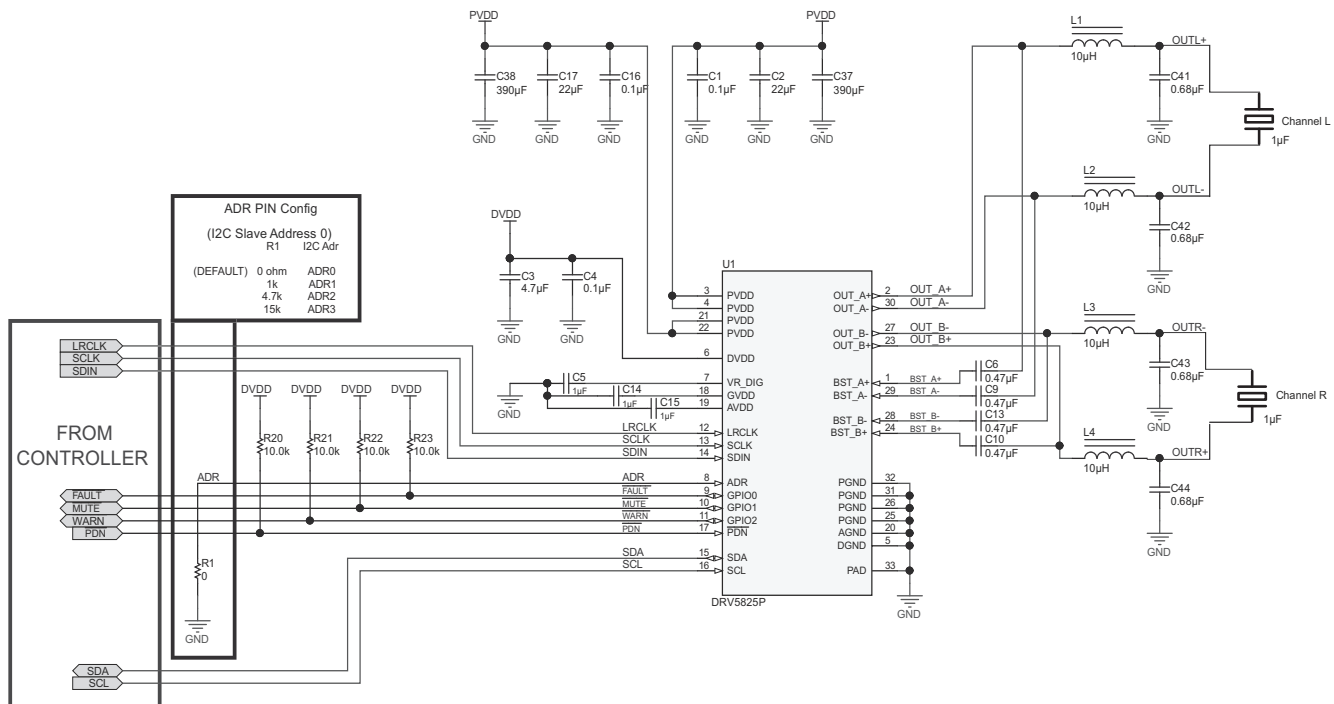
## 9.2 Typical Applications

### 9.2.1 2.0 (Stereo BTL) System

In the 2.0 system, two channels are presented to the amplifier via the digital input signal. These two channels are amplified and then sent to two separate speakers. In some cases, the amplified signal is further separated based upon frequency by a passive crossover network after the L-C filter. Even so, the application is considered 2.0.

Most commonly, the two channels are a pair of signals called a stereo pair, with one channel containing the audio for the left channel and the other channel containing the audio for the right channel. While certainly the two channels can contain any two audio channels, such as two surround channels of a multi-channel speaker system, the most popular occurrence in two channels systems is a stereo pair.

Figure 9-1 shows the 2.0 (Stereo BTL) system application.



**Figure 9-1. 2.0 (Stereo BTL) System Application Schematic**

## 9.2.2 Design Requirements

- Power supplies:
  - 3.3-V supply
  - 5-V to 24-V supply
- Communication: host processor serving as I<sup>2</sup>C compliant master
- External memory (such as EEPROM and FLASH) used for coefficients.

The requirements for the supporting components for the DRV5825P device in a Stereo 2.0 (BTL) system is provide in 表 9-2.

**表 9-2. Supporting Component Requirements for Stereo 2.0 (BTL) Systems**

REFERENCE DESIGNATOR	VALUE	SIZE	DETAILED DESCRIPTION
C1, C16	0.1 $\mu$ F	0402	CAP, CERM, 0.1 $\mu$ F, 50 V, $\pm$ 10%, X7R, 0402
C2, C17	22 $\mu$ F	0805	CAP, CERM, 22 $\mu$ F, 35 V, $\pm$ 20%, JB, 0805
C37, C38	390 $\mu$ F	10x10	CAP, AL, 390 $\mu$ F, 35 V, $\pm$ 20%, 0.08 $\Omega$ , SMD
C3	4.7 $\mu$ F	0603	CAP, CERM, 4.7 $\mu$ F, 10 V, $\pm$ 10%, X5R, 0603
C4	0.1 $\mu$ F	0603	CAP, CERM, 0.1 $\mu$ F, 16 V, $\pm$ 10%, X7R, 0603
C5, C14, C15	1 $\mu$ F	0603	CAP, CERM, 1 $\mu$ F, 16 V, $\pm$ 10%, X5R, 0603
C6, C9, C10, C13	0.47 $\mu$ F	0603	CAP, CERM, 0.47 $\mu$ F, 16 V, $\pm$ 10%, X7R, 0603
C41, C42, C43, C44	0.68 $\mu$ F	0805	CAP, CERM, 0.68 $\mu$ F, 50 V, $\pm$ 10%, X7R, 0805
L1, L2, L3, L4	10 $\mu$ H		Inductor, Shielded, Ferrite, 10 $\mu$ H, 4.4 A, 0.0304 $\Omega$ , SMD 1274AS-H-100M=P3
R1	0 $\Omega$	0402	RES, 0, 5%, 0.063 W, 0402
R20, R21, R22, R23	10 k $\Omega$	0402	RES, 10.0 k, 1%, 0.063 W, 0402

## 9.2.3 Detailed Design procedures

This Design procedures can be used for both Stereo 2.0 and Mono Mode.

### 9.2.3.1 Step One: Hardware Integration

- Using the Typical Application Schematic as a guide, integrate the hardware into the system schematic.
- Following the recommended component placement, board layout, and routing given in the example layout above, integrate the device and its supporting components into the system PCB file.
  - The most critical sections of the circuit are the power supply inputs, the amplifier output signals, and the high-frequency signals, all of which go to the serial audio port. Constructing these signals to ensure they are given precedent as design trade-offs are made is recommended.
  - For questions and support go to the E2E forums ([e2e.ti.com](http://e2e.ti.com)). If deviating from the recommended layout is necessary, go to the E2E forum to request a layout review.

### 9.2.3.2 Step Two: Hardware Integration

Using the DRV5825PEVM evaluation module and the development software to configure the desired device settings.

### 9.2.3.3 Step Three: Software Integration

- Using the End System Integration feature of the PPC3 app to generate a baseline configuration file.
- Generate additional configuration files based upon operating modes of the end-equipment and integrate static configuration information into initialization files.
- Integrate dynamic controls (such as volume controls, mute commands, and mode-based EQ curves) into the main system program.

## 9.2.4 MONO (PBTL) Systems

In MONO mode, DRV5825P can be used as PBTL mode to drive sub-woofer with more output power.

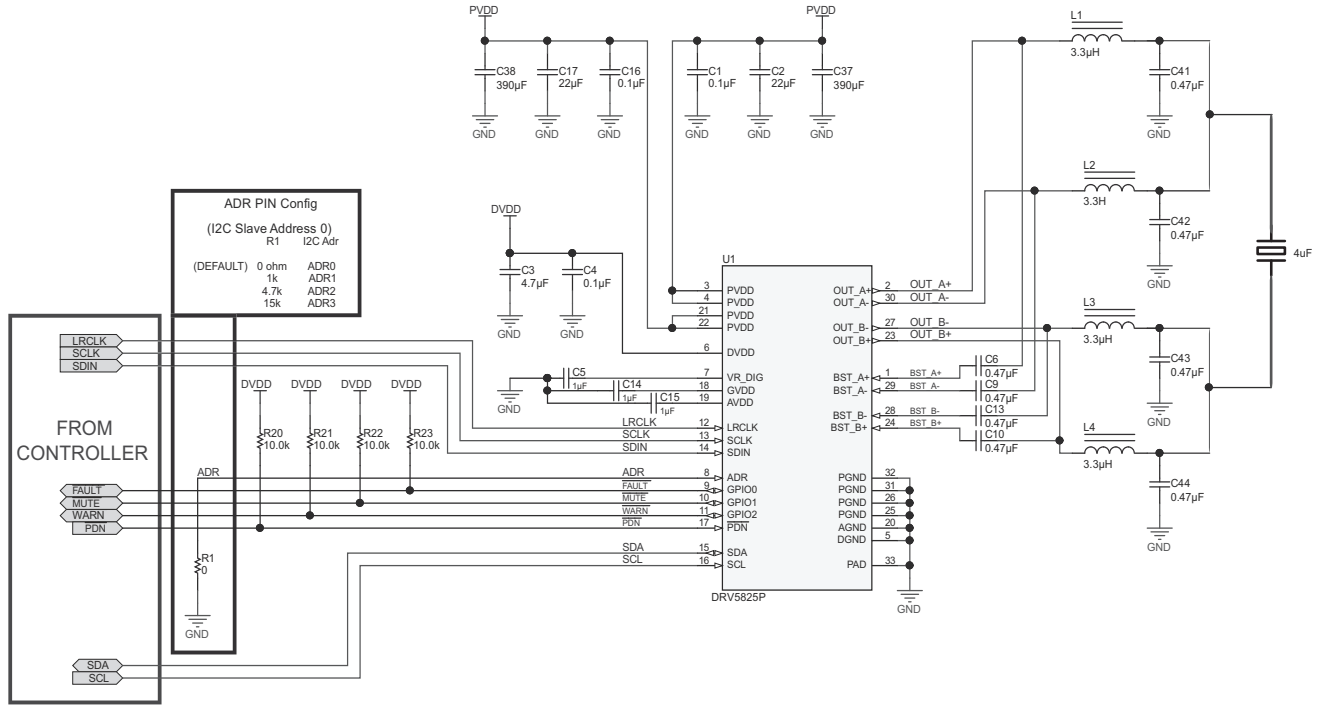


图 9-2. MONO (PBTL) Application Schematic

表 9-3. Supporting Component Requirements for Sub-woofer (PBTL) Systems

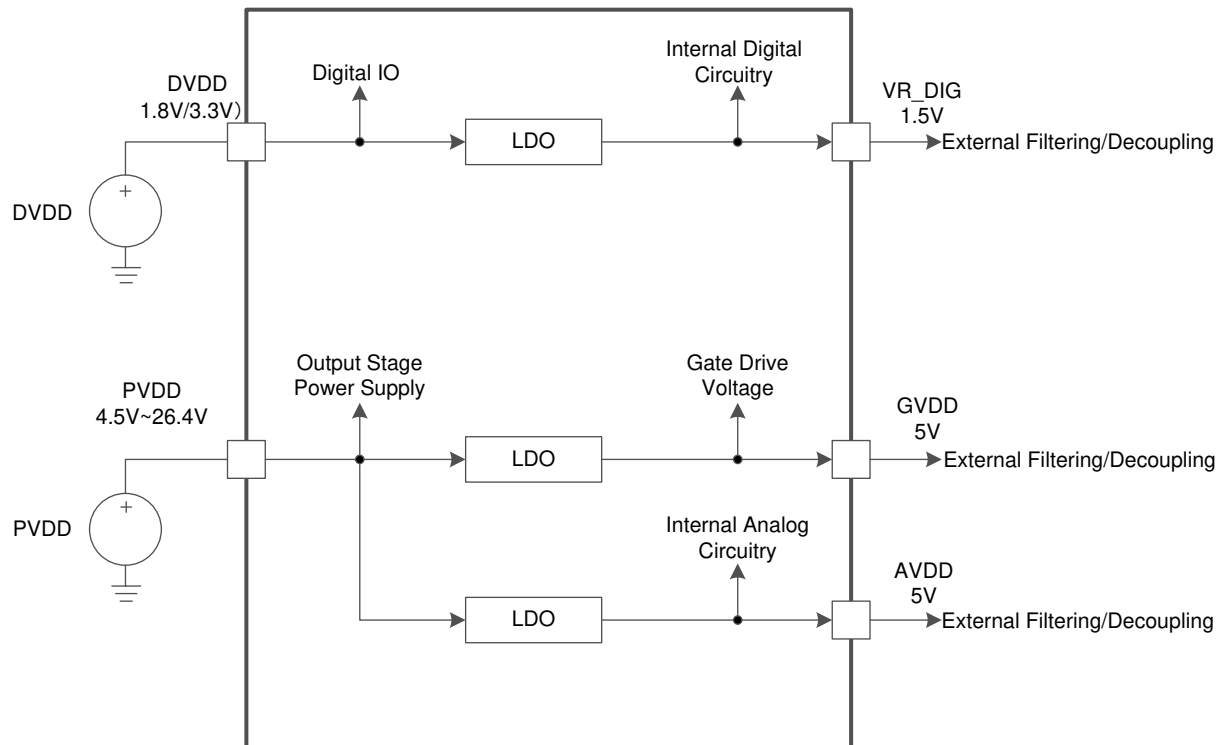
REFERENCE DESIGNATOR	VALUE	SIZE	DETAILED DESCRIPTION
C37,C38	390µF	10mmx10mm	CAP, AL, 390 µF, 35 V, +/- 20%, 0.08 ohm, SMD
C1, C16	0.1 µF	0402	CAP, CERM, 0.1 F, 50 V, ±10%, X7R, 0402
C2, C17	22 µF	0805	CAP, CERM, 22 µF, 35 V, ±20%, JB, 0805
C3	4.7 µF	0603	CAP, CERM, 4.7 µF, 10 V, ±10%, X5R, 0603
C4	0.1 µF	0603	CAP, CERM, 0.1 µF, 16 V, ±10%, X7R, 0603
C5,C14,C15	1 µF	0603	CAP, CERM, 1 µF, 16 V, ±10%, X5R, 0603
C6,C9,C10,C13	0.47 µF	0603	CAP, CERM, 0.47 µF, 16 V, ±10%, X7R, 0603
C41,C42,C43,C44	0.47 µF	0805	CAP, CERM, 0.47 µF, 50 V, ±10%, X7R, 0805
L1,L2,L3,L4	3.3 µH		Inductor, Shielded, 3.3 µH, 8.7 A
R1	0 kΩ	0402	RES, 0, 5%, 0.063 W, 0402

**表 9-3. Supporting Component Requirements for Sub-woofer (PBTl) Systems (continued)**

REFERENCE DESIGNATOR	VALUE	SIZE	DETAILED DESCRIPTION
R20,R21,R22,R23	10 k $\Omega$	0402	RES, 10.0 k, 1%, 0.063 W, 0402

## 10 Power Supply Recommendations

The DRV5825P device requires two power supplies for proper operation. A high-voltage supply calls PVDD is required to power the output stage of the speaker amplifier and its associated circuitry. Additionally, one low-voltage power supply which is calls DVDD is required to power the various low-power portions of the device. The allowable voltage range for both PVDD and DVDD supply are listed in the *Recommended Operating Conditions* table. The two power supplies do not have a required powerup sequence. The power supplies can be powered on in any order.



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FIG 10-1. Power Supply Function Block Diagram

### 10.1 DVDD Supply

The DVDD supply that is required from the system is used to power several portions of the device. As shown in FIG 10-1, it provides power to the DVDD pin. Proper connection, routing and decoupling techniques are highlighted in the セクション 9 section and the セクション 11.2 section and must be followed as closely as possible for proper operation and performance.

Some portions of the device also require a separate power supply that is a lower voltage than the DVDD supply. To simplify the power supply requirements for the system, the DRV5825P device includes an integrated low dropout (LDO) linear regulator to create this supply. This linear regulator is internally connected to the DVDD supply and its output is presented on the DVDD\_REG pin, providing a connection point for an external bypass capacitor. It is important to note that the linear regulator integrated in the device has only been designed to support the current requirements of the internal circuitry, and should not be used to power any additional external circuitry. Additional loading on this pin could cause the voltage to sag, negatively affecting the performance and operation of the device.

## 10.2 PVDD Supply

The output stage of the speaker amplifier drives the load using the PVDD supply. This is the power supply which provides the drive current to the load during playback. Proper connection, routing, and decoupling techniques are highlighted in the DRV5825PEVM and must be followed as closely as possible for proper operation and performance. Due to the high-voltage switching of the output stage, it is particularly important to properly decouple the output power stages in the manner described in the device [セクション 9](#). Lack of proper decoupling, like that shown in the [セクション 9](#), results in voltage spikes which can damage the device.

A separate power supply is required to drive the gates of the MOSFETs used in the output stage of the speaker amplifier. This power supply is derived from the PVDD supply via an integrated linear regulator. A GVDD pin is provided for the attachment of decoupling capacitor for the gate drive voltage regulator. It is important to note that the linear regulator integrated in the device has only been designed to support the current requirements of the internal circuitry, and should not be used to power any additional external circuitry. Additional loading on this pin could cause the voltage to sag, negatively affecting the performance and operation of the device.

Another separate power supply is derived from the PVDD supply via an integrated linear regulator is AVDD. AVDD pin is provided for the attachment of decoupling capacitor for the DRV5825P internal circuitry. It is important to note that the linear regulator integrated in the device has only been designed to support the current requirements of the internal circuitry, and should not be used to power any additional external circuitry. Additional loading on this pin could cause the voltage to sag, negatively affecting the performance and operation of the device.

## 11 Layout

### 11.1 Layout Guidelines

#### 11.1.1 General Guidelines for Audio Amplifiers

Audio amplifiers which incorporate switching output stages must have special attention paid to their layout and the layout of the supporting components used around them. The system level performance metrics, including thermal performance, electromagnetic compliance (EMC), device reliability, and audio performance are all affected by the device and supporting component layout.

Ideally, the guidance provided in the applications section with regard to device and component selection can be followed by precise adherence to the layout guidance shown in the [セクション 11.2](#) section. These examples represent exemplary baseline balance of the engineering trade-offs involved with laying out the device. These designs can be modified slightly as needed to meet the needs of a given application. In some applications, for instance, solution size can be compromised to improve thermal performance through the use of additional contiguous copper near the device. Conversely, EMI performance can be prioritized over thermal performance by routing on internal traces and incorporating a via picket-fence and additional filtering components. In all cases, it is recommended to start from the guidance shown in the [セクション 11.2](#) section and work with TI field application engineers or through the E2E community to modify it based upon the application specific goals.

#### 11.1.2 Importance of PVDD Bypass Capacitor Placement on PVDD Network

Placing the bypassing and decoupling capacitors close to supply has long been understood in the industry. This applies to DVDD, AVDD, GVDD and PVDD. However, the capacitors on the PVDD net for the DRV5825P device deserve special attention.

The small bypass capacitors on the PVDD lines of the DUT must be placed as close to the PVDD pins as possible. Not only does placing these devices far away from the pins increase the electromagnetic interference in the system, but doing so can also negatively affect the reliability of the device. Placement of these components too far from the DRV5825P device can cause ringing on the output pins that can cause the voltage on the output pin to exceed the maximum allowable ratings shown in the *Absolute Maximum Ratings* table, damaging the device. For that reason, the capacitors on the PVDD net must be no further away from their associated PVDD pins than what is shown in the example layouts in the [セクション 11.2](#) section.

#### 11.1.3 Optimizing Thermal Performance

Follow the layout example shown in the [図 11-1](#) to achieve the best balance of solution size, thermal, audio, and electromagnetic performance. In some cases, deviation from this guidance can be required due to design constraints which cannot be avoided. In these instances, the system designer should ensure that the heat can get out of the device and into the ambient air surrounding the device. Fortunately, the heat created in the device naturally travels away from the device and into the lower temperature structures around the device.

##### 11.1.3.1 Device, Copper, and Component Layout

Primarily, the goal of the PCB design is to minimize the thermal impedance in the path to those cooler structures. These tips should be followed to achieve that goal:

- Avoid placing other heat producing components or structures near the amplifier (including above or below in the end equipment).
- If possible, use a higher layer count PCB to provide more heat sinking capability for the device and to prevent traces and copper signal and power planes from breaking up the contiguous copper on the top and bottom layer.
- Place the DRV5825P device away from the edge of the PCB when possible to ensure that the heat can travel away from the device on all four sides.
- Avoid cutting off the flow of heat from the DRV5825P device to the surrounding areas with traces or via strings. Instead, route traces perpendicular to the device and line up vias in columns which are perpendicular to the device.
- Unless the area between two pads of a passive component is large enough to allow copper to flow in between the two pads, orient it so that the narrow end of the passive component is facing the DRV5825P device.

- Because the ground pins are the best conductors of heat in the package, maintain a contiguous ground plane from the ground pins to the PCB area surrounding the device for as many of the ground pins as possible.

### 11.1.3.2 Stencil Pattern

The recommended drawings for the DRV5825P device PCB foot print and associated stencil pattern are shown at the end of this document in the package addendum. Additionally, baseline recommendations for the via arrangement under and around the device are given as a starting point for the PCB design. This guidance is provided to suit the majority of manufacturing capabilities in the industry and prioritizes manufacturability over all other performance criteria. In elevated ambient temperature or under high-power dissipation use-cases, this guidance may be too conservative and advanced PCB design techniques may be used to improve thermal performance of the system.

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#### Note

The customer must verify that deviation from the guidance shown in the package addendum, including the deviation explained in this section, meets the customer's quality, reliability, and manufacturability goals.

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#### 11.1.3.2.1 PCB footprint and Via Arrangement

The PCB footprint (also known as a symbol or land pattern) communicates to the PCB fabrication vendor the shape and position of the copper patterns to which the DRV5825P device is soldered. This footprint can be followed directly from the guidance in the package addendum at the end of this data sheet. It is important to make sure that the thermal pad, which connects electrically and thermally to the PowerPAD™ of the DRV5825P device, be made no smaller than what is specified in the package addendum. This ensures that the DRV5825P device has the largest interface possible to move heat from the device to the board.

The via pattern shown in the package addendum provides an improved interface to carry the heat from the device through to the layers of the PCB, because small diameter plated vias (with minimally-sized annular rings) present a low thermal-impedance path from the device into the PCB. Once into the PCB, the heat travels away from the device and into the surrounding structures and air. By increasing the number of vias, as shown in the [セクション 11.2](#) section, this interface can benefit from improved thermal performance.

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#### Note

Vias can obstruct heat flow if they are not constructed properly.

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More notes on the construction and placement of vias are as follows:

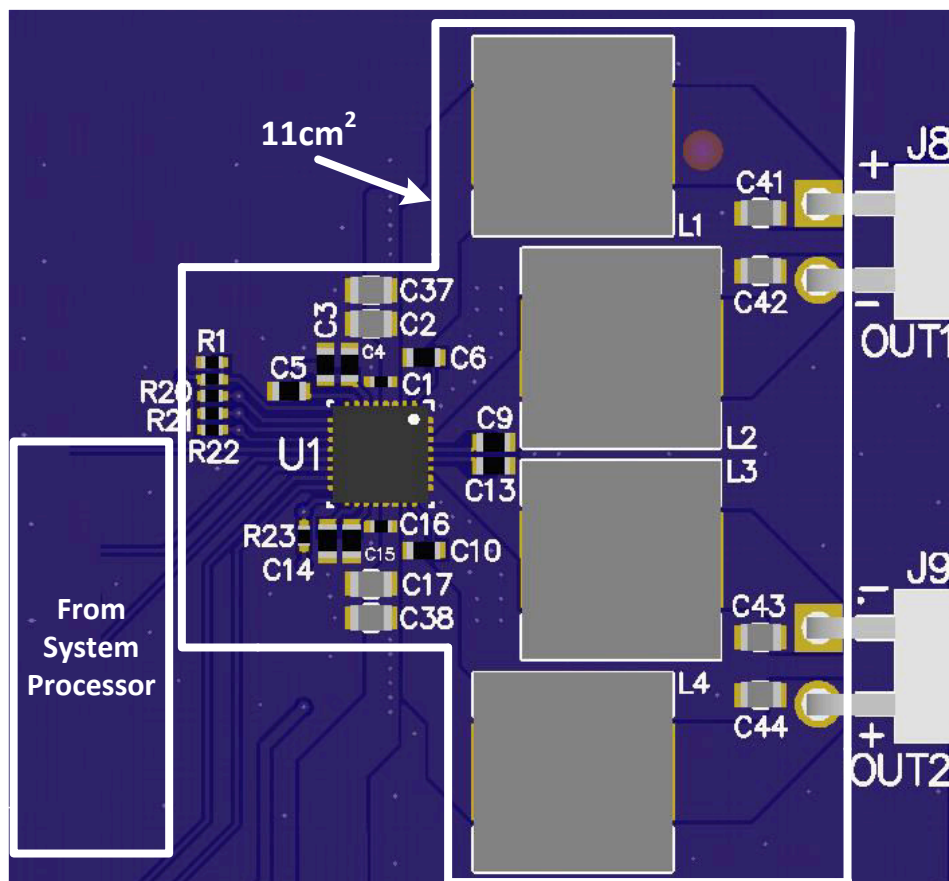
- Remove thermal reliefs on thermal vias, because they impede the flow of heat through the via.
- Vias filled with thermally conductive material are best, but a simple plated via can be used to avoid the additional cost of filled vias.
- The diameter of the drill must be 8 mm or less. Also, the distance between the via barrel and the surrounding planes should be minimized to help heat flow from the via into the surrounding copper material. In all cases, minimum spacing should be determined by the voltages present on the planes surrounding the via and minimized wherever possible.
- Vias should be arranged in columns, which extend in a line radially from the heat source to the surrounding area. This arrangement is shown in the [セクション 11.2](#) section.
- Ensure that vias do not cut off power current flow from the power supply through the planes on internal layers. If needed, remove some vias that are farthest from the DRV5825P device to open up the current path to and from the device.

#### 11.1.3.2.2 Solder Stencil

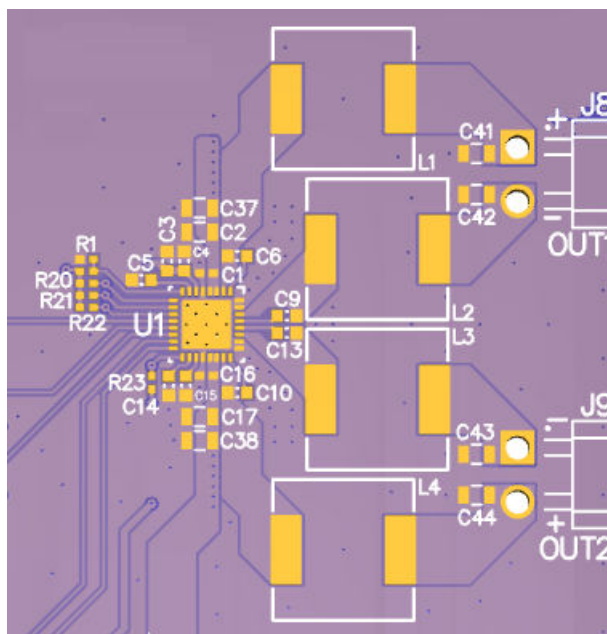
During the PCB assembly process, a piece of metal called a stencil on top of the PCB and deposits solder paste on the PCB wherever there is an opening (called an aperture) in the stencil. The stencil determines the quantity and the location of solder paste that is applied to the PCB in the electronic manufacturing process. In most cases, the aperture for each of the component pads is almost the same size as the pad itself. However, the thermal pad on the PCB is large and depositing a large, single deposition of solder paste would lead to

manufacturing issues. Instead, the solder is applied to the board in multiple apertures, to allow the solder paste to outgas during the assembly process and reduce the risk of solder bridging under the device. This structure is called an aperture array, and is shown in the [セクション 11.2](#) section. It is important that the total area of the aperture array (the area of all of the small apertures combined) covers between 70% and 80% of the area of the thermal pad itself.

## 11.2 Layout Example



☒ 11-1. 2.0 (Stereo BTL) 3-D View



### 11-2. 2.0 (Stereo BTL) Top Copper View

## 12 Device and Documentation Support

### 12.1 Device Support

#### 12.1.1 Device Nomenclature

The glossary listed in the section is a general glossary with commonly used acronyms and words which are defined in accordance with a broad TI initiative to comply with industry standards such as JEDEC, IPC, IEEE, and others. The glossary provided in this section defines words, phrases, and acronyms that are unique to this product and documentation, collateral, or support tools and software used with this product. For any additional questions regarding definitions and terminology, please see the [e2e Audio Amplifier Forum](#).

**Bridge tied load (BTL)** is an output configuration in which one terminal of the speaker is connected to one half-bridge and the other terminal is connected to another half-bridge.

**DUT** refers to a *device under test* to differentiate one device from another.

**Closed-loop architecture** describes a topology in which the amplifier monitors the output terminals, comparing the output signal to the input signal and attempts to correct for non-linearities in the output.

**Dynamic controls** are those which are changed during normal use by either the system or the end-user.

**GPIO** is a general purpose input/output pin. It is a highly configurable, bi-directional digital pin which can perform many functions as required by the system.

**Host processor (also known as System Processor, Scalar, Host, or System Controller)** refers to device which serves as a central system controller, providing control information to devices connected to it as well as gathering audio source data from devices upstream from it and distributing it to other devices. This device often configures the controls of the audio processing devices (like the SN005825C) in the audio path in order to optimize the audio output of a loudspeaker based on frequency response, time alignment, target sound pressure level, safe operating area of the system, and user preference.

**HybridFlow** uses components which are built in RAM and components which are built in ROM to make a configurable device that is easier to use than a fully-programmable device while remaining flexible enough to be used in several applications

**Maximum continuous output power** refers to the maximum output power that the amplifier can continuously deliver without shutting down when operated in a 25°C ambient temperature. Testing is performed for the period of time required that their temperatures reach thermal equilibrium and are no longer increasing

**Parallel bridge tied load (PBTL)** is an output configuration in which one terminal of the speaker is connected to two half-bridges which have been placed in parallel and the other terminal is connected to another pair of half bridges placed in parallel

**r<sub>DS(on)</sub>** is a measure of the on-resistance of the MOSFETs used in the output stage of the amplifier.

**Static controls/Static configurations** are controls which do not change while the system is in normal use.

**Vias** are copper-plated through-hole in a PCB.

### 12.2 Receiving Notification of Documentation Updates

To receive notification of documentation updates, navigate to the device product folder on ti.com. In the upper right corner, click on *Alert me* to register and receive a weekly digest of any product information that has changed. For change details, review the revision history included in any revised document.

### 12.3 Support Resources

### 12.4 Trademarks

PowerPAD™ are trademarks of Texas Instruments.

すべての商標は、それぞれの所有者に帰属します。

## 12.5 Electrostatic Discharge Caution



This integrated circuit can be damaged by ESD. Texas Instruments recommends that all integrated circuits be handled with appropriate precautions. Failure to observe proper handling and installation procedures can cause damage.

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

## 12.6 Glossary

**TI Glossary** This glossary lists and explains terms, acronyms, and definitions.

## Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

## PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package   Pins	Package qty   Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
<a href="#">DRV5825PRHBR</a>	Active	Production	VQFN (RHB)   32	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 85	5825P
DRV5825PRHBR.A	Active	Production	VQFN (RHB)   32	3000   LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-25 to 85	5825P

<sup>(1)</sup> **Status:** For more details on status, see our [product life cycle](#).

<sup>(2)</sup> **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

<sup>(3)</sup> **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

<sup>(4)</sup> **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

<sup>(5)</sup> **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

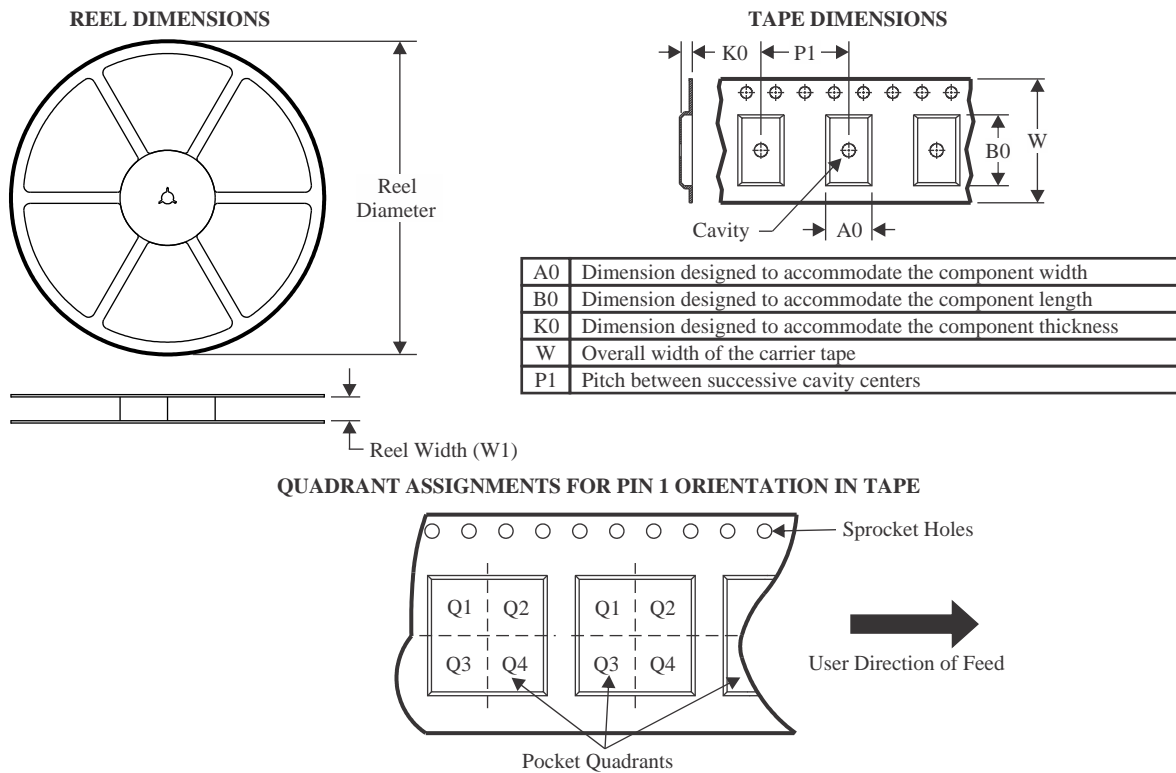
<sup>(6)</sup> **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

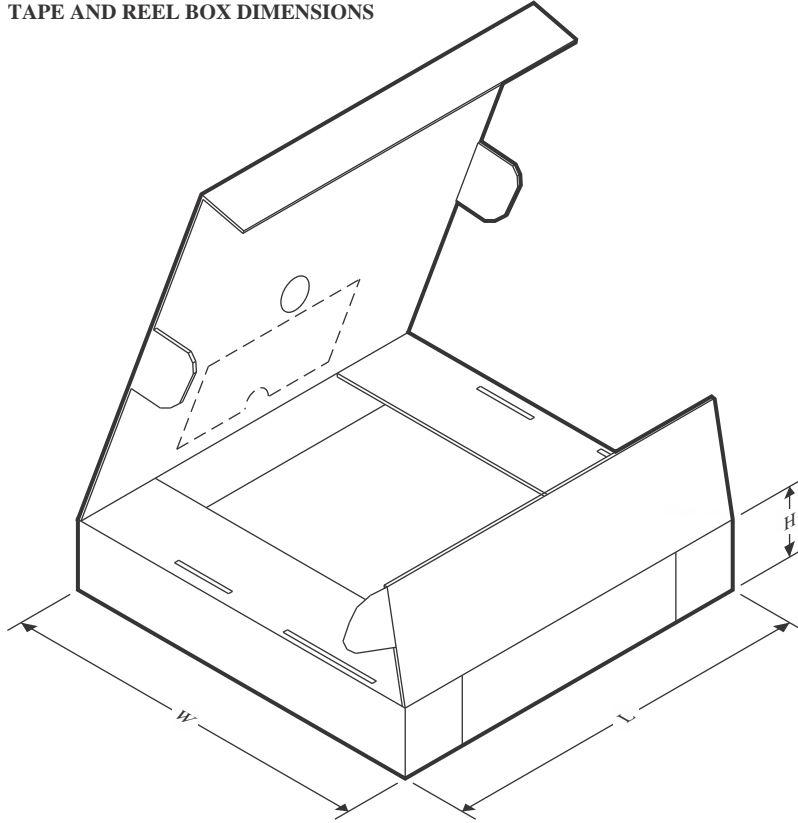
## TAPE AND REEL INFORMATION



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
DRV5825PRHBR	VQFN	RHB	32	3000	330.0	12.4	5.3	5.3	1.1	8.0	12.0	Q2

## TAPE AND REEL BOX DIMENSIONS



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
DRV5825PRHBR	VQFN	RHB	32	3000	367.0	367.0	35.0

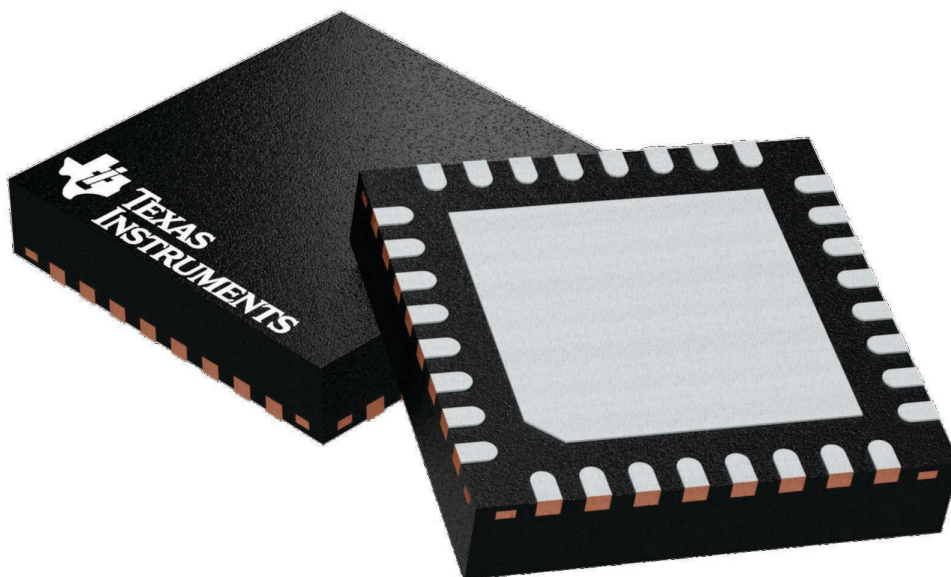
## GENERIC PACKAGE VIEW

**RHB 32**

**VQFN - 1 mm max height**

5 x 5, 0.5 mm pitch

PLASTIC QUAD FLATPACK - NO LEAD



Images above are just a representation of the package family, actual package may vary.  
Refer to the product data sheet for package details.

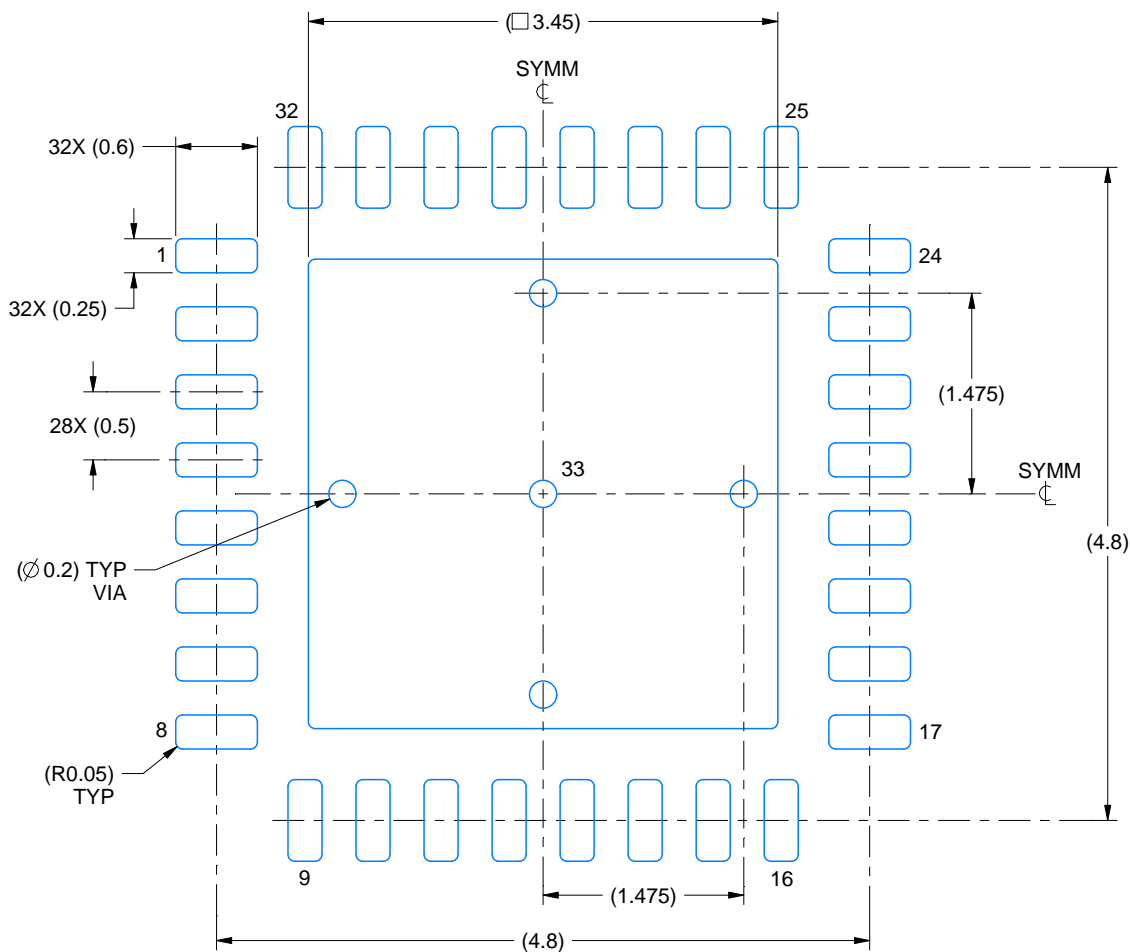
4224745/A

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

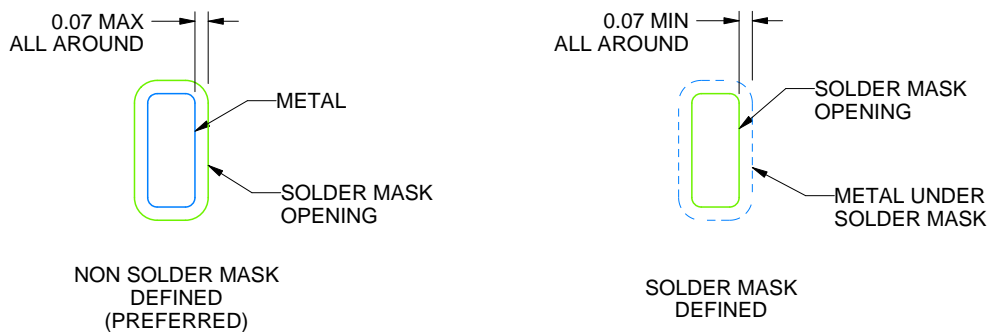
**RHB0032E**

### VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



LAND PATTERN EXAMPLE  
SCALE:18X



## SOLDER MASK DETAILS

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NOTES: (continued)

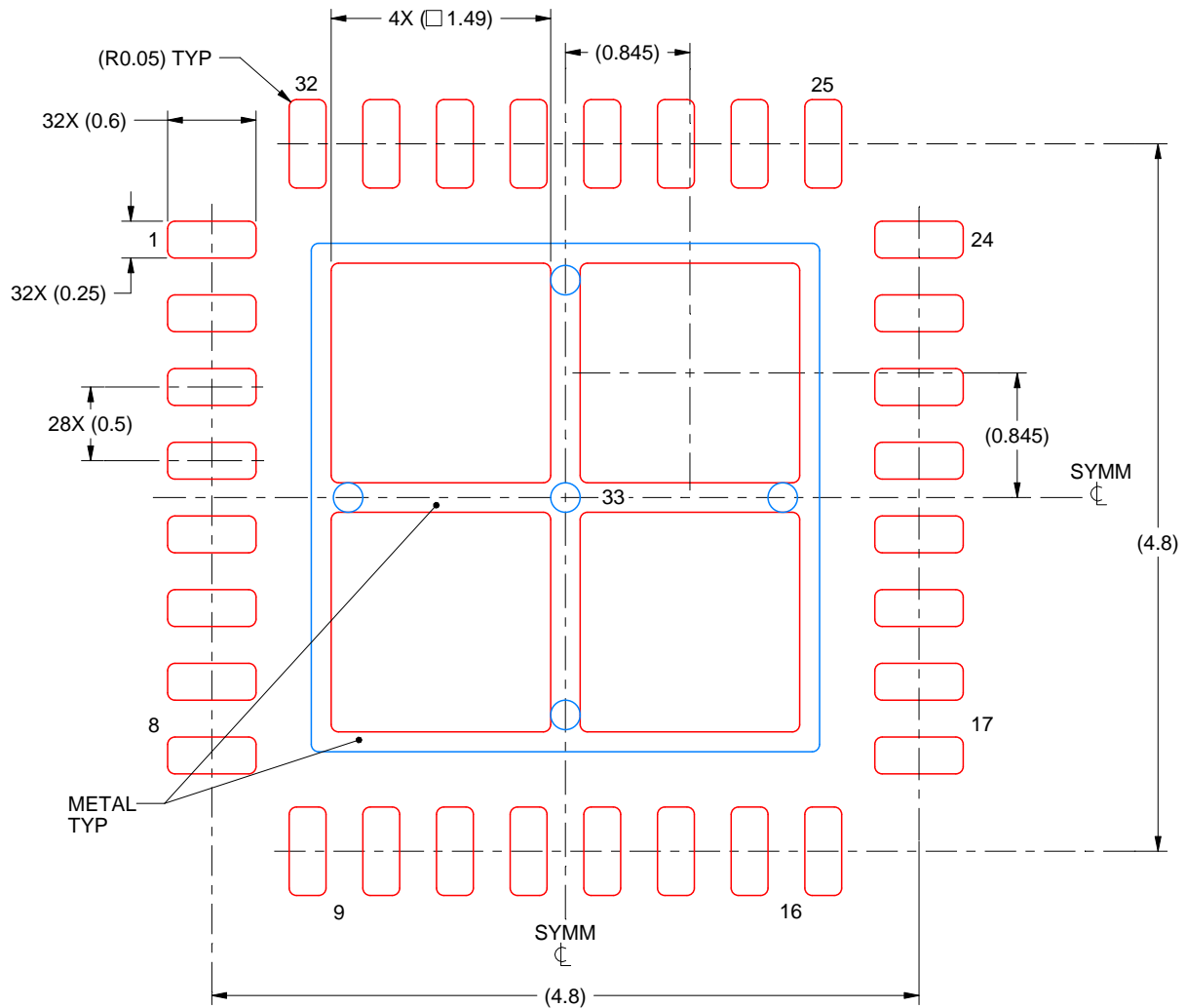
4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slue271](http://www.ti.com/lit/slue271)).
5. Vias are optional depending on application, refer to device data sheet. If any vias are implemented, refer to their locations shown on this view. It is recommended that vias under paste be filled, plugged or tented.

# EXAMPLE STENCIL DESIGN

RHB0032E

VQFN - 1 mm max height

PLASTIC QUAD FLATPACK - NO LEAD



**SOLDER PASTE EXAMPLE**  
 BASED ON 0.125 mm THICK STENCIL

EXPOSED PAD 33:  
 75% PRINTED SOLDER COVERAGE BY AREA UNDER PACKAGE  
 SCALE:20X

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NOTES: (continued)

6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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